315/433MHz RF Super-regenerative Receiver SoC Flash MCU

BC68F2420

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www.holtek.com

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Features

CPU Features

- Holtek TinyPower™ Technology
- Operating voltage
  - V_{DD} (MCU)
    - f_{SYS} = 32kHz: 2.2V~5.5V
    - f_{SYS} = 16MHz: 3.3V~5.5V
  - V_{DDRF} (RF)
    - f_{SYS} = 16MHz: 4.5V~5.5V
- Up to 0.25μs instruction cycle with 16MHz system clock at V_{DD}=5V
- Power down and wake-up functions to reduce power consumption
- Oscillator types:
  - Internal High Speed RC – HIRC
  - Internal Low Speed 32kHz RC – LIRC
- Multi-mode operation: FAST, SLOW, IDLE and SLEEP
- Fully integrated internal 16MHz oscillator requires no external components
- All instructions executed in one or two instruction cycles
- Table read instructions
- 63 powerful instructions
- 4-level subroutine nesting
- Bit manipulation instruction

Peripheral Features

- Flash Program Memory: 1K×14
- RAM Data Memory: 64×8
- True EEPROM Memory: 32×8
- Watchdog Timer function
- Up to 9 bidirectional I/O lines
- Programmable I/O port source current
- Two pin-shared external interrupts
- Multiple Timer Modules for time measurement, capture input, compare match output or PWM output or single pulse output function
  - 1 Compact type 10-bit Timer Module – CTM
  - 1 Standard type 10-bit Timer Module – STM
- Dual Time-Base functions for generation of fixed time interrupt signals
- Low voltage reset function
- Low voltage detect function
- Package types: 16-pin NSOP-EP

RF Receiver Features

- Supports OOK demodulation
- RF Symbol rate up to 15Ksps
- Frequency Band: 300MHz ~ 450MHz
- High sensitivity: -97dBm @ 5V / 5Ksps / 0.1%BER / 315MHz, 433MHz
- Operating current consumption: 4mA
- Integrated Low Noise Amplifier (LNA) with integrated Super Regenerative Oscillator

General Description

The BC68F2420 provides a combination of a fully featured MCU and an RF receiver function, giving it great flexibility for use in wide range of RF control applications. Offering users the convenience of Flash Memory multi-programming features, this device also includes a wide range of functions and features. Other memory includes an area of RAM Data Memory as well as an area of true EEPROM memory for storage of non-volatile data such as serial numbers, calibration data etc.

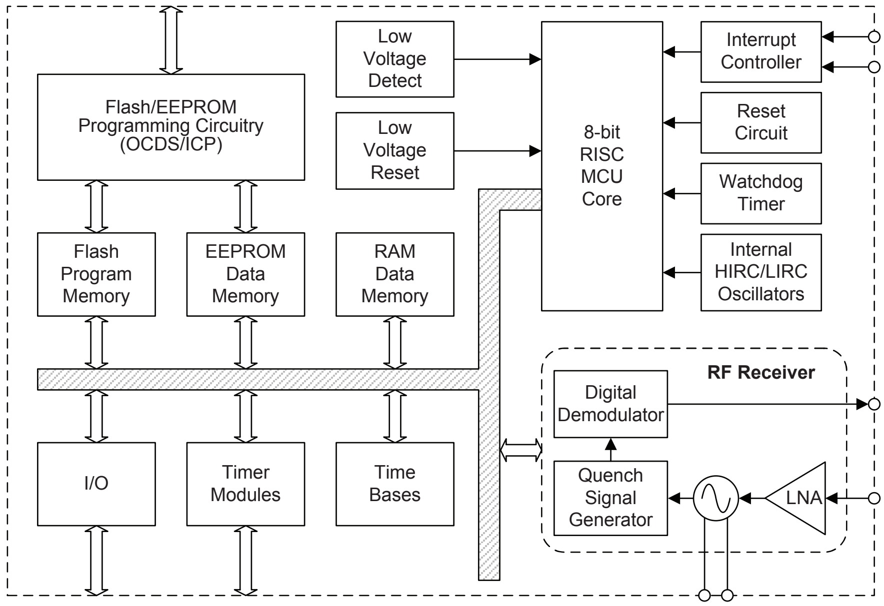
With regard to internal timers, the device includes multiple and extremely flexible Timer Modules providing functions for timing, pulse generation and PWM generation operations. Protective features such as an internal Watchdog Timer, Low Voltage Reset and Low Voltage Detector coupled with excellent noise immunity and ESD protection ensure that reliable operation is maintained in hostile electrical environments.

The device also includes fully integrated high and low speed oscillators which require no external components for their implementation. The ability to operate and switch dynamically between a range of operating modes using different clock sources gives users the ability to optimise the conflicting demands of microcontroller performance and power consumption.

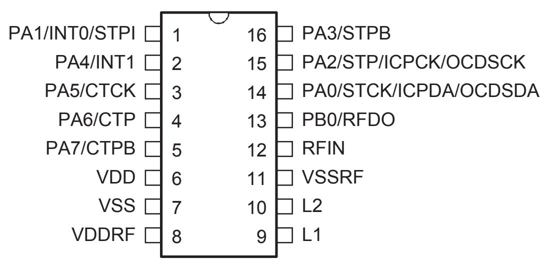
The integrated RF receiver can be used to receive On-Off keyed – OOK data in the 300MHz to 450MHz frequency band. The device will convert this RF input into a digital output signal, making it a genuine RF-in to Data-out integrated device and providing an easy to use solution for UHF receiver implementation. The RF data rate is up to 15Ksps. With few external components and low-current power consumption features, it provides an ideal solution for low cost and power-sensitive applications. The device contains a low-noise amplifier, a regenerative circuit, an integrated quench circuit and a baseband data-recovery circuitry.

The inclusion of flexible I/O programming features, Time-Base functions along with many other features ensure that the device can offer excellent capabilities in terms of functionality and power-saving as well as being highly cost effective in a huge range of remote wireless applications.

Block Diagram



Pin Assignment



BC68F2420/BC68V2420
16 NSOP-EP-A

Note: 1. If the pin-shared pin functions have multiple outputs, the desired pin-shared function is determined by corresponding software control bits.

2. The OCDSDA and OCDSCK pins are supplied for the OCDS dedicated pins and as such only available for the BC68V2420 device which is the OCDS EV chip for the BC68F2420 device.

Pin Description

With the exception of the power pins and some relevant RF control pins, all pins on the device can be referenced by their Port name, e.g. PA0, PA1 etc., which refer to the digital I/O function of the pins. However these Port pins are also shared with other function such as the Timer Module pins etc. The function of each pin is listed in the following table, however the details behind how each pin is configured is contained in other sections of the datasheet.

As the Pin Description Summary table applies to the package type with the most pins, not all of the above listed pins may be present on package types with smaller numbers of pins.

Pin Name	Function	OPT	I/T	O/T	Description
PA0/STCK/ICPDA/OCDSDA	PA0	PAPU PAWU	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	STCK	—	ST	—	STM clock input
	ICPDA	—	ST	CMOS	ICP data/address
	OCDSDA	—	ST	CMOS	OCDS address/data, for EV chip only
PA1/INT0/STPI	PA1	PAPU PAWU	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	INT0	—	ST	—	External interrupt 0 input
	STPI	IFS	ST	—	STM capture input
PA2/STP/ICPCK/OCDSCK	PA2	PAPU PAWU PXSR	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	STP	PXSR	—	CMOS	STM output
	ICPCK	—	ST	—	ICP clock
	OCDSCK	—	ST	—	OCDS clock, for EV chip only
PA3/STPB	PA3	PAPU PAWU PXSR	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	STPB	PXSR	—	CMOS	STM inverted output
PA4/INT1	PA4	PAPU PAWU	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	INT1	—	ST	—	External interrupt 1 input
PA5/CTCK	PA5	PAPU PAWU	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	CTCK	—	ST	—	CTM clock input
PA6/CTP	PA6	PAPU PAWU PXSR	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	CTP	PXSR	—	CMOS	CTM output
PA7/CTPB	PA7	PAPU PAWU PXSR	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	CTPB	PXSR	—	CMOS	CTM inverted output
PB0/RFDO	PB0	PBPU PBWU PXSR	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	RFDO	PXSR	—	CMOS	RF Demodulator data output
RFIN	RFIN	—	AN	—	RF signal input, OOK RF signal source

Pin Name	Function	OPT	I/T	O/T	Description
L1	L1	—	AN	AN	Oscillator input/output, connecting external LC tank
L2	L2	—	AN	AN	Oscillator input/output, connecting external LC tank
VDD	VDD	—	PWR	—	Digital positive power supply
VSS	VSS	—	PWR	—	Digital negative power supply
VSSRF	VSSRF	—	PWR	—	RF negative power supply
VDDRF	VDDRF	—	PWR	—	RF positive power supply

Legend: I/T: Input type; O/T: Output type;
OPT: Optional by register option; PWR: Power;
ST: Schmitt Trigger input; CMOS: CMOS output;
AN: Analog signal.

Absolute Maximum Ratings

Supply Voltage .... V_{SS}−0.3V to V_{SS}+6.0V
Input Voltage .... V_{SS}−0.3V to V_{DD}+0.3V
Storage Temperature .... -50˚C to 125˚C
Operating Temperature .... -40˚C to 85˚C
I_{OL} Total 80mA
I_{OH} Total .... -80mA
Total Power Dissipation 500mW

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the devices. Functional operation of the devices at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency, pin load conditions, temperature and program instruction type, etc., can all exert an influence on the measured values.

Operating Voltage Characteristics

Ta= -40°C~85°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Operating Voltage – HIRC	f_{SYS}=f_{HIRC}=16MHz	3.3	—	5.5	V
	Operating Voltage – LIRC	f_{SYS}=f_{LIRC}=32kHz	2.2	—	5.5	V

Standby Current Characteristics

Ta=25°C

Symbol	Standby Mode	Test Conditions		Min.	Typ.	Max.	Max.	Unit
		V_{DD}	Conditions				85°C	
I_{STB}	SLEEP Mode	2.2V	WDT off	—	0.2	0.6	0.7	μA
		3V		—	0.2	0.8	1	
		5V		—	0.5	1	1.2	
		2.2V	WDT on	—	1.2	2.4	2.9	μA
		3V		—	1.5	3	3.6	
		5V		—	3	5	6	
	IDLE0 Mode – LIRC	2.2V	f_{SUB} on	—	2.4	4	4.8	μA
		3V		—	3	5	6	
		5V		—	5	10	12	
	IDLE1 Mode – HIRC	3.3V	f_{SUB} on, f_{SYS}=16MHz	—	0.6	0.8	0.96	mA
		5V		—	1.4	2	2.4	

Notes: When using the characteristic table data, the following notes should be taken into consideration:

- Any digital inputs are setup in a non-floating condition.
- All measurements are taken under conditions of no load and with all peripherals in an off state.
- There are no DC current paths.
- All Standby Current values are taken after a HALT instruction execution thus stopping all instruction execution.

Operating Current Characteristics

Ta=25°C

Symbol	Operating Mode	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{DD}	SLOW Mode – LIRC	2.2V	f_{SYS}=32kHz	—	8	16	μA
		3V		—	10	20	
		5V		—	30	50	
	FAST Mode – HIRC	3.3V	f_{SYS}=16MHz	—	1.5	2.0	mA
		5V		—	3.2	4.8	

Notes: When using the characteristic table data, the following notes should be taken into consideration:

- Any digital inputs are setup in a non-floating condition.
- All measurements are taken under conditions of no load and with all peripherals in an off state.
- There are no DC current paths.
- All Operating Current values are measured using a continuous NOP instruction program loop.

A.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency and temperature etc., can all exert an influence on the measured values.

High Speed Internal Oscillator – HIRC – Frequency Accuracy

During the program writing operation the writer will trim the HIRC oscillator at a user selected HIRC frequency and user selected voltage of 5V.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Temp.				
f_{HIRC}	16MHz Writer Trimmed HIRC Frequency	5V	25°C	-1%	16	+1%	MHz
			-40°C~85°C	-2%	16	+2%	
		3.3V~5.5V	25°C	-2.5%	16	+2.5%	
			-40°C~85°C	-3%	16	+3%	

Notes: 1. The 5V value for V_{DD} is provided as this is the fixed voltage at which the HIRC frequency is trimmed by the writer.
2. The row below the 5V trim voltage row is provided to show the values for the full VDD range operating voltage.
3. The minimum and maximum tolerance values provided in the table are only for the frequency at which the writer trims the HIRC oscillator. After trimming at this chosen specific frequency any change in HIRC oscillator frequency using the oscillator register control bits by the application program will give a frequency tolerance to within ±20%.

Low Speed Internal Oscillator Characteristics – LIRC

Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Temp.				
f_{LIRC}	LIRC Frequency	2.2V~5.5V	25°C	-5%	32	+5%	kHz
			-40°C~85°C	-10%	32	+10%	
t_{START}	LIRC Start Up Time	—	—	—	—	100	μs

System Start Up Time Characteristics

Ta= -40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
t_{SST}	System Start-up Time Wake-up from condition where f_{SYS} is off	—	$f_{SYS}=f_H \sim f_H/64$, $f_H=f_{HIRC}$	—	16	—	t_{SYS}
		—	$f_{SYS}=f_{SUB}=f_{LIRC}$	—	2	—	t_{SYS}
	System Start-up Time Wake-up from condition where f_{SYS} is on	—	$f_{SYS}=f_H \sim f_H/64$, $f_H=f_{HIRC}$	—	2	—	t_{SYS}
		—	$f_{SYS}=f_{SUB}=f_{LIRC}$	—	2	—	t_{SYS}
	System Speed Switch Time FAST to SLOW Mode or SLOW to FAST Mode	—	f_{HIRC} switches from off → on	—	16	—	t_{HIRC}
t_{RSTD}	System Reset Delay Time Reset source from Power-on reset or LVR hardware reset	—	RR_{POR}=5V/ms	42	48	54	ms
	System Reset Delay Time LVRC/WDTC software reset	—	—				
	System Reset Delay Time Reset source from WDT overflow	—	—	14	16	18	ms
t_{SRESET}	Minimum Software Reset Width to Reset	—	—	45	90	120	μs

Notes: 1. For the System Start-up time values, whether f_{SYS} is on or off depends upon the mode type and the chosen f_{SYS} system oscillator. Details are provided in the System Operating Modes section.

2. The time units, shown by the symbols t_{HIRC}, t_{SYS} etc. are the inverse of the corresponding frequency values as provided in the frequency tables. For example $t_{HIRC}=1/f_{HIRC}$, $t_{SYS}=1/f_{SYS}$ etc.

3. If the LIRC is used as the system clock and if it is off when in the SLEEP Mode, then an additional LIRC start up time, t_{START}, as provided in the LIRC frequency table, must be added to the t_{SST} time in the table above.

4. The System Speed Switch Time is effectively the time taken for the newly activated oscillator to start up.

Input/Output Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{IL}	Input Low Voltage for I/O Ports	5V	—	0	—	1.5	V
		—		0	—	$0.2V_{DD}$	
V_{IH}	Input High Voltage for I/O Ports	5V	—	3.5	—	5.0	V
		—		$0.8V_{DD}$	—	V_{DD}	
I_{OL}	Sink Current for I/O Ports	3V	$V_{OL}=0.1V_{DD}$, DRVCC[m]=0 (m=0~3)	1	2	—	mA
		5V		2	4	—	
		3V	$V_{OL}=0.1V_{DD}$, DRVCC[m]=1 (m=0~3)	5	10	—	mA
		5V		10	20	—	
I_{OH}	Port Source Current for I/O Ports	3V	$V_{OH}=0.9V_{DD}$, DRVCC[m]=0 (m=0~3)	-1	-2	—	mA
		5V		-2	-4	—	
		3V	$V_{OH}=0.9V_{DD}$, DRVCC[m]=1 (m=0~3)	-1	-5	—	mA
		5V		-5	-10	—	
R_{PH}	Pull-high Resistance for I/O Ports (Note)	3V	—	20	60	100	kΩ
		5V		10	30	50	
I_{LEAK}	Input Leakage Current	3V	$V_{IN}=V_{DD}$ or $V_{IN}=V_{SS}$	—	—	±1	μA
		5V		—	—	±1	μA
SR_{RISE}	Output Rising Slew rate for I/O ports	3V	SLEWC[m+1, m]=00B (m=0 or 2 or 4 or 6), $0.1V_{DD}$ to $0.9V_{DD}$, C_{LOAD}=20pF	150	—	—	V/μs
		5V		380	—	—	V/μs
		3V	SLEWC[m+1, m]=01B (m=0 or 2 or 4 or 6), $0.1V_{DD}$ to $0.9V_{DD}$, C_{LOAD}=20pF	—	87	—	V/μs
		5V		—	240	—	V/μs
		3V	SLEWC[m+1, m]=10B (m=0 or 2 or 4 or 6), $0.1V_{DD}$ to $0.9V_{DD}$, C_{LOAD}=20pF	—	45	—	V/μs
		5V		—	120	—	V/μs
		3V	SLEWC[m+1, m]=11B (m=0 or 2 or 4 or 6), $0.1V_{DD}$ to $0.9V_{DD}$, C_{LOAD}=20pF	—	20	—	V/μs
		5V		—	60	—	V/μs
SR_{FALL}	Output Falling Slew rate for I/O ports	3V	SLEWC[m+1, m]=00B (m=0 or 2 or 4 or 6), $0.9V_{DD}$ to $0.1V_{DD}$, C_{LOAD}=20pF	200	—	—	V/μs
		5V		500	—	—	V/μs
		3V	SLEWC[m+1, m]=01B (m=0 or 2 or 4 or 6), $0.9V_{DD}$ to $0.1V_{DD}$, C_{LOAD}=20pF	—	61	—	V/μs
		5V		—	180	—	V/μs
		3V	SLEWC[m+1, m]=10B (m=0 or 2 or 4 or 6), $0.9V_{DD}$ to $0.1V_{DD}$, C_{LOAD}=20pF	—	29	—	V/μs
		5V		—	90	—	V/μs
		3V	SLEWC[m+1, m]=11B (m=0 or 2 or 4 or 6), $0.9V_{DD}$ to $0.1V_{DD}$, C_{LOAD}=20pF	—	15	—	V/μs
		5V		—	45	—	V/μs
t_{TCK}	TM TCK Input Pin Minimum Pulse Width	—	—	0.3	—	—	μs
t_{TPI}	TM TPI Input Pin Minimum Pulse Width	—	—	0.3	—	—	μs
t_{INT}	External Interrupt Minimum Pulse Width	—	—	0.3	—	—	μs

Note: The R_{PH} internal pull high resistance value is calculated by connecting to ground and enabling the input pin with a pull-high resistor and then measuring the input sink current at the specified supply voltage level. Dividing the voltage by this measured current provides the R_{PH} value.

Memory Characteristics

Ta= -40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{RW}	V_{DD} for Read / Write	—	—	V_{DDmin}	—	V_{DDmax}	V
Flash Program / Data EEPROM Memory							
t_{DEW}	Erase / Write Cycle Time – Flash Program Memory	—	—	—	2	3	ms
	Write Cycle Time – Data EEPROM Memory	—	—	—	4	6	ms
I_{DDPGM}	Programming / Erase Current on V_{DD}	—	—	—	—	5.0	mA
E_P	Cell Endurance	—	—	100K	—	—	E/W
t_{RETD}	ROM Data Retention Time	—	Ta=25°C	—	40	—	Year
RAM Data Memory							
V_{DR}	RAM Data Retention Voltage	—	Device in SLEEP Mode	1.0	—	—	V

LVD/LVR Electrical Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{LVR}	Low Voltage Reset Voltage	—	LVR enable, voltage select 2.1V	-5%	2.1	+5%	V
			LVR enable, voltage select 2.55V	-5%	2.55	+5%	
			LVR enable, voltage select 3.15V	-5%	3.15	+5%	
			LVR enable, voltage select 3.8V	-5%	3.8	+5%	
V_{LVD}	Low Voltage Detection Voltage	—	LVD enable, voltage select 2.0V	-5%	2.0	+5%	V
			LVD enable, voltage select 2.2V	-5%	2.2	+5%	
			LVD enable, voltage select 2.4V	-5%	2.4	+5%	
			LVD enable, voltage select 2.7V	-5%	2.7	+5%	
			LVD enable, voltage select 3.0V	-5%	3.0	+5%	
			LVD enable, voltage select 3.3V	-5%	3.3	+5%	
			LVD enable, voltage select 3.6V	-5%	3.6	+5%	
			LVD enable, voltage select 4.0V	-5%	4.0	+5%	
I_{LVR}	Additional Current for LVR Enable	—	LVD disable, VBGEN=0	—	—	20	μA
I_{LVD}	Additional Current for LVD Enable	—	LVR disable, VBGEN=0	—	—	0.3	μA
t_{LVDS}	LVDO Stable Time	—	For LVR enable, VBGEN=0, LVD off → on	—	—	20	μs
t_{LVR}	Minimum Low Voltage Width to Reset	—	—	120	240	480	μs
t_{LVD}	Minimum Low Voltage Width to Interrupt	—	—	30	60	120	μs

RF Receiver Electrical Characteristics

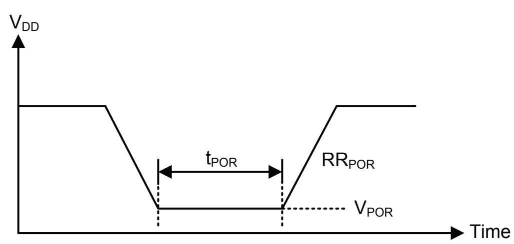
Ta= 25°C, Frequency Band=315/433MHz, and R_L=50Ω load matched

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DDRF}	RF Operating Voltage	—	Continuous operation	4.5	—	5.5	V
I_{RF}	RF Operating Current	5V	Continuous operation	—	4	—	mA
P_{SENS}	Receiver sensitivity	5V	f_{RX}=315/433.92MHz, symbol rate=5Ksps, BER is 0.1% (PN9 data)	—	-97	—	dBm
f_{RX}	Receiver Input Frequency Range	5V	—	—	315/433	—	MHz
BW	RX Bandwidth	5V	—	—	1	—	MHz
SR	Symbol Rate	5V	Symbol rate=5Ksps	0.5	5	—	Ksps

Power-on Reset Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{POR}	V_{DD} Start Voltage to Ensure Power-on Reset	—	—	—	—	100	mV
RR_{POR}	V_{DD} Rising Rate to Ensure Power-on Reset	—	—	0.035	—	—	V/ms
t_{POR}	Minimum Time for V_{DD} Stays at V_{POR} to Ensure Power-on Reset	—	—	1	—	—	ms



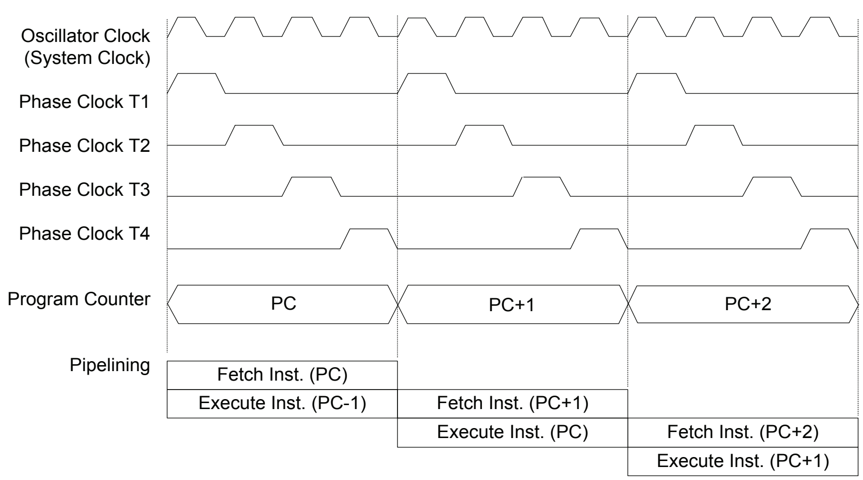
System Architecture

A key factor in the high-performance features of the Holtek range of microcontrollers is attributed to their internal system architecture. The range of the device take advantage of the usual features found within RISC microcontrollers providing increased speed of operation and enhanced performance. The pipelining scheme is implemented in such a way that instruction fetching and instruction execution are overlapped, hence instructions are effectively executed in one cycle, with the exception of branch or call instructions. An 8-bit wide ALU is used in practically all instruction set operations, which carries out arithmetic operations, logic operations, rotation, increment, decrement, branch decisions, etc. The internal data path is simplified by moving data through the Accumulator and the ALU. Certain internal registers are implemented in the Data Memory and can be directly or indirectly addressed. The simple addressing methods of these registers along with additional architectural features ensure that a minimum of external components is required to provide a functional I/O control system with maximum reliability and flexibility. This makes the device suitable for low-cost, high-volume production for controller applications.

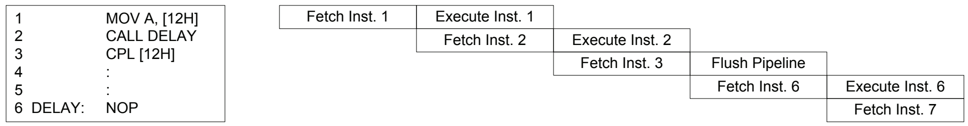
Clocking and Pipelining

The main system clock, derived from either a HIRC or LIRC oscillator is subdivided into four internally generated non-overlapping clocks, T1~T4. The Program Counter is incremented at the beginning of the T1 clock during which time a new instruction is fetched. The remaining T2~T4 clocks carry out the decoding and execution functions. In this way, one T1~T4 clock cycle forms one instruction cycle. Although the fetching and execution of instructions takes place in consecutive instruction cycles, the pipelining structure of the microcontroller ensures that instructions are effectively executed in one instruction cycle. The exception to this are instructions where the contents of the Program Counter are changed, such as subroutine calls or jumps, in which case the instruction will take one more instruction cycle to execute.

For instructions involving branches, such as jump or call instructions, two machine cycles are required to complete instruction execution. An extra cycle is required as the program takes one cycle to first obtain the actual jump or call address and then another cycle to actually execute the branch. The requirement for this extra cycle should be taken into account by programmers in timing sensitive applications.



System Clocking and Pipelining



Instruction Fetching

Program Counter

During program execution, the Program Counter is used to keep track of the address of the next instruction to be executed. It is automatically incremented by one each time an instruction is executed except for instructions, such as "JMP" or "CALL" that demand a jump to a non-consecutive Program Memory address. Only the lower 8 bits, known as the Program Counter Low Register, are directly addressable by the application program.

When executing instructions requiring jumps to non-consecutive addresses such as a jump instruction, a subroutine call, interrupt or reset, etc., the microcontroller manages program control by loading the required address into the Program Counter. For conditional skip instructions, once the condition has been met, the next instruction, which has already been fetched during the present instruction execution, is discarded and a dummy cycle takes its place while the correct instruction is obtained.

Program Counter	
High Byte	**Low Byte (PCL)**
PC9~PC8	PCL7~PCL0

Program Counter

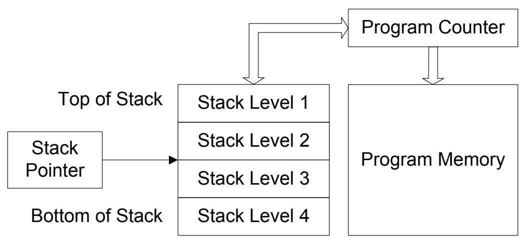
The lower byte of the Program Counter, known as the Program Counter Low register or PCL, is available for program control and is a readable and writeable register. By transferring data directly into this register, a short program jump can be executed directly; however, as only this low byte is available for manipulation, the jumps are limited to the present page of memory that is 256 locations. When such program jumps are executed it should also be noted that a dummy cycle will be inserted. Manipulating the PCL register may cause program branching, so an extra cycle is needed to pre-fetch.

Stack

This is a special part of the memory which is used to save the contents of the Program Counter only. The stack has multiple levels and is neither part of the data nor part of the program space, and is neither readable nor writeable. The activated level is indexed by the Stack Pointer, and is neither readable nor writeable. At a subroutine call or interrupt acknowledge signal, the contents of the Program Counter are pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction, RET or RETI, the Program Counter is restored to its previous value from the stack. After a device reset, the Stack Pointer will point to the top of the stack.

If the stack is full and an enabled interrupt takes place, the interrupt request flag will be recorded but the acknowledge signal will be inhibited. When the Stack Pointer is decremented, by RET or RETI, the interrupt will be serviced. This feature prevents stack overflow allowing the programmer to use the structure more easily. However, when the stack is full, a CALL subroutine instruction can still be executed which will result in a stack overflow. Precautions should be taken to avoid such cases which might cause unpredictable program branching.

If the stack is overflow, the first Program Counter save in the stack will be lost.



Arithmetic and Logic Unit – ALU

The arithmetic-logic unit or ALU is a critical area of the microcontroller that carries out arithmetic and logic operations of the instruction set. Connected to the main microcontroller data bus, the ALU receives related instruction codes and performs the required arithmetic or logical operations after which the result will be placed in the specified register. As these ALU calculation or operations may result in carry, borrow or other status changes, the status register will be correspondingly updated to reflect these changes. The ALU supports the following functions:

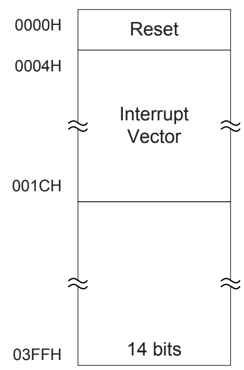
- Arithmetic operations: ADD, ADDM, ADC, ADCM, SUB, SUBM, SBC, SBCM, DAA
- Logic operations: AND, OR, XOR, ANDM, ORM, XORM, CPL, CPLA
- Rotation RRA, RR, RRCA, RRC, RLA, RL, RLCA, RLC
- Increment and Decrement INCA, INC, DECA, DEC
- Branch decision, JMP, SZ, SZA, SNZ, SIZ, SDZ, SIZA, SDZA, CALL, RET, RETI

Flash Program Memory

The Program Memory is the location where the user code or program is stored. For the devices the Program Memory is Flash type, which means it can be programmed and re-programmed a large number of times, allowing the user the convenience of code modification on the same device. By using the appropriate programming tools, the Flash devices offer users the flexibility to conveniently debug and develop their applications while also offering a means of field programming and updating.

Structure

The Program Memory has a capacity of 1K×14 bits. The Program Memory is addressed by the Program Counter and also contains data, table information and interrupt entries. Table data, which can be setup in any location within the Program Memory, is addressed by a separate table pointer register.



Program Memory Structure

Special Vectors

Within the Program Memory, certain locations are reserved for the reset and interrupts. The location 0000H is reserved for use by the device reset for program initialisation. After a device reset is initiated, the program will jump to this location and begin execution.

Look-up Table

Any location within the Program Memory can be defined as a look-up table where programmers can store fixed data. To use the look-up table, the table pointer must first be setup by placing the address of the look up data to be retrieved in the table pointer register, TBLP. These registers define the total address of the look-up table.

After setting up the table pointer, the table data can be retrieved from the Program Memory using the "TABRDC [m]" or "TABRDL [m]" instructions, respectively. When the instruction is executed, the lower order table byte from the Program Memory will be transferred to the user defined Data Memory register [m] as specified in the instruction. The higher order table data byte from the Program Memory will be transferred to the TBLH special register. Any unused bits in this transferred higher order byte will be read as 0.

The accompanying diagram illustrates the addressing data flow of the look-up table.

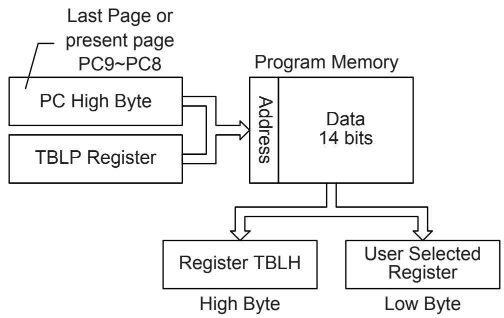


Table Program Example

The following example shows how the table pointer and table data is defined and retrieved from the microcontroller. This example uses raw table data located in the Program Memory which is stored there using the ORG statement. The value at this ORG statement is "0300H" which refers to the start address of the last page within the 1K Program Memory of the device. The table pointer low byte register is setup here to have an initial value of "06H". This will ensure that the first data read from the data table will be at the Program Memory address "0306H" or 6 locations after the start of the last page. Note that the value for the table pointer is referenced to the first address of the present page if the "TABRDC [m]" instruction is being used. The high byte of the table data which in this case is equal to zero will be transferred to the TBLH register automatically when the "TABRDL [m]" instruction is executed.

Because the TBLH register is a read-only register and cannot be restored, care should be taken to ensure its protection if both the main routine and Interrupt Service Routine use table read instructions. If using the table read instructions, the Interrupt Service Routines may change the value of the TBLH and subsequently cause errors if used again by the main routine. As a rule it is recommended that simultaneous use of the table read instructions should be avoided. However, in situations where simultaneous use cannot be avoided, the interrupts should be disabled prior to the execution of any main routine table-read instructions. Note that all table related instructions require two instruction cycles to complete their operation.

Table Read Program Example

```
tempreg1 db ?      ; temporary register #1
tempreg2 db ?      ; temporary register #2
     :
mov a,06h          ; initialize table pointer - note that this address
                   ; is referenced
mov tblp, a        ; to the last page or present page
     :
tabrdl tempreg1    ; transfers value in table referenced by table pointer to tempreg1
                   ; data at program memory address "0306H" transferred to
                   ; to tempreg1 and TBLH
dec tblp           ; reduce value of table pointer by one
tabrdl tempreg2    ; transfers value in table referenced by table pointer to tempreg2
                   ; data at program memory address "0305H" transferred to tempreg2 and
                   ; TBLH in this example the data "1AH" is transferred to tempreg1 and
                   ; data "0FH" to register tempreg2 the value "00H" will be transferred
                   ; to the high byte register TBLH
     :
org 0300h          ; sets initial address of last page
dc 00Ah, 00Bh, 00Ch, 00Dh, 00Eh, 00Fh, 01Ah, 01Bh
     :
```

In Circuit Programming – ICP

The provision of Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device.

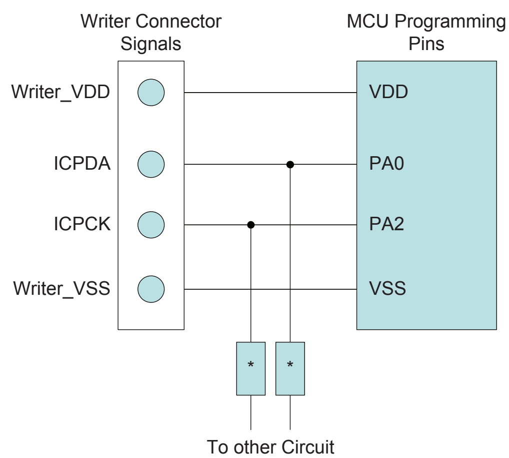
As an additional convenience, Holtek has provided a means of programming the microcontroller in-circuit using a 4-pin interface. This provides manufacturers with the possibility of manufacturing their circuit boards complete with a programmed or un-programmed microcontroller, and then programming or upgrading the program at a later stage. This enables product manufacturers to easily keep their manufactured products supplied with the latest program releases without removal and re-insertion of the device.

The Holtek Flash MCU to Writer Programming Pin correspondence table is as follows:

Holtek Writer Pins	MCU Programming Pins	Pin Description
ICPDA	PA0	Programming Serial Data/Address
ICPCK	PA2	Programming Clock
VDD	VDD	Power Supply
VSS	VSS	Ground

The Program Memory and EEPROM Data Memory can be programmed serially in-circuit using this 4-wire interface. Data is downloaded and uploaded serially on a single pin with an additional line for the clock. Two additional lines are required for the power supply. The technical details regarding the in-circuit programming of the device is beyond the scope of this document and will be supplied in supplementary literature.

During the programming process, the user must take care of the ICPDA and ICPCK pins for data and clock programming purposes to ensure that no other outputs are connected to these two pins.



Note: * may be resistor or capacitor. The resistance of * must be greater than 1kΩ or the capacitance of * must be less than 1nF.

On-Chip Debug Support – OCDS

There is an EV chip named BC68V2420 which is used to emulate the BC68F2420 device. The EV chip device also provides an "On-Chip Debug" function to debug the real MCU device during the development process. The EV chip and the real MCU device are almost functionally compatible except for "On-Chip Debug" function. Users can use the EV chip device to emulate the real chip device behavior by connecting the OCDSDA and OCDSCK pins to the Holtek HT-IDE development tools. The OCDSDA pin is the OCDS Data/Address input/output pin while the OCDSCK pin is the OCDS clock input pin. When users use the EV chip for debugging, other functions which are shared with the OCDSDA and OCDSCK pins in the device will have no effect in the EV chip. However, the two OCDS pins which are pin-shared with the ICP programming pins are still used as the Flash Memory programming pins for ICP. For more detailed OCDS information, refer to the corresponding document named "Holtek e-Link for 8-bit MCU OCDS User's Guide".

Holtek e-Link Pins	EV Chip Pins	Pin Description
OCDSDA	OCDSDA	On-Chip Debug Support Data/Address input/output
OCDSCK	OCDSCK	On-Chip Debug Support Clock input
VDD	VDD	Power Supply
VSS	VSS	Ground

Data Memory

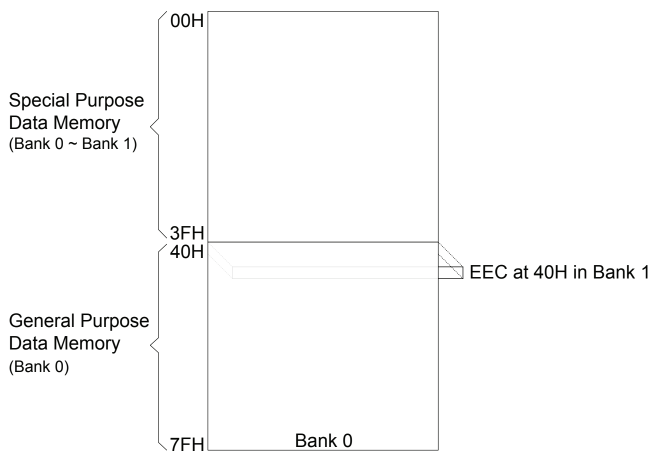
The Data Memory is a volatile area of 8-bit wide RAM internal memory and is the location where temporary information is stored.

Structure

Divided into two areas, the first of these is an area of RAM, known as the Special Function Data Memory. Here are located registers which are necessary for correct operation of the device. Many of these registers can be read from and written to directly under program control, however, some remain protected from user manipulation. The second area of Data Memory is known as the General Purpose Data Memory, which is reserved for general purpose use. All locations within this area are read and write accessible under program control.

The overall Data Memory is subdivided into two banks. The Special Purpose Data Memory registers are accessible in Bank 0, along with the EEC register at address 40H, which is only accessible in Bank 1. Switching between the different Data Memory banks is achieved by setting the Bank Pointer to the correct value. The start address of the Data Memory for the device is the address 00H.

Special Purpose Data Memory	General Purpose Data Memory	
Bank: Address	Capacity	Bank: Address
0: 00H~3FH 1: 40H	64×8	0: 40H~7FH



Data Memory Structure

General Purpose Data Memory

There are 64 bytes of general purpose data memory which are arranged in 40H~7FH of Bank 0. All microcontroller programs require an area of read/write memory where temporary data can be stored and retrieved for use later. It is this area of RAM memory that is known as General Purpose Data Memory. This area of Data Memory is fully accessible by the user programing for both reading and writing operations. By using the bit operation instructions individual bits can be set or reset under program control giving the user a large range of flexibility for bit manipulation in the Data Memory.

Special Purpose Data Memory

This area of Data Memory is where registers, necessary for the correct operation of the microcontroller, are stored. Most of the registers are both readable and writeable but some are protected and are readable only, the details of which are located under the relevant Special Function Register section. Note that for locations that are unused, any read instruction to these addresses will return the value "00H".

Address	Bank 0	Bank 1
00H	IAR0	
01H	MP0	
02H	IAR1	
03H	MP1	
04H	BP	
05H	ACC	
06H	PCL	
07H	TBLP	
08H	TBLH	
09H		
0AH	STATUS	
0BH	SCC	
0CH	HIRCC	
0DH	INTEG	
0EH	INTC0	
0FH	INTC1	
10H	MFI0	
11H	MFI1	
12H	MFI2	
13H	RSTFC	
14H	PA	
15H	PAC	
16H	PAPU	
17H	PAWU	
18H	PB	
19H	PBC	
1AH	PBPU	
1BH	LVDC	
1CH	WDTC	
1DH	PSCR	
1EH	EEA	
1FH	EED	

Address	Bank 0	Bank 1
20H	STMC0	
21H	STMC1	
22H	STMDL	
23H	STMDH	
24H	STMAL	
25H	STMAH	
26H		
27H	CTMC0	
28H	CTMC1	
29H	CTMDL	
2AH	CTMDH	
2BH	CTMAL	
2CH	CTMAH	
2DH	TB0C	
2EH	TB1C	
2FH	IFS	
30H	RFC0	
31H	RFC1	
32H	RFC2	
33H	RFC3	
34H	RFC4	
35H	RFC5	
36H	RFC6	
37H	RFC7	
38H		
39H	RFDEBC	
3AH	PXSR	
3BH	PBWU	
3CH	LVRC	
3DH	DRVCC	
3EH	SLEWC	
3FH		
40H		EEC

: Unused, read as 00H.
: Reserved, cannot be changed.

Special Purpose Data Memory Structure

Special Function Register Description

Most of the Special Function Register details will be described in the relevant functional sections; however several registers require a separate description in this section.

Indirect Addressing Register – IAR0, IAR1

The Indirect Addressing Registers, IAR0 and IAR1, although having their locations in normal RAM register space, do not actually physically exist as normal registers. The method of indirect addressing for RAM data manipulation uses these Indirect Addressing Registers and Memory Pointers, in contrast to direct memory addressing, where the actual memory address is specified. Actions on the IAR0 and IAR1 registers will result in no actual read or write operation to these registers but rather to the memory location specified by their corresponding Memory Pointers, MP0 or MP1. Acting as a pair, IAR0 and MP0 can together access data from Bank 0 while the IAR1 and MP1 register pair can access data from any bank. As the Indirect Addressing Registers are not physically implemented, reading the Indirect Addressing Registers indirectly will return a result of "00H" and writing to the registers indirectly will result in no operation.

Memory Pointers – MP0, MP1

Two Memory Pointers, known as MP0 and MP1 are provided. These Memory Pointers are physically implemented in the Data Memory and can be manipulated in the same way as normal registers providing a convenient way with which to address and track data. When any operation to the relevant Indirect Addressing Registers is carried out, the actual address that the microcontroller is directed to, is the address specified by the related Memory Pointer. MP0, together with Indirect Addressing Register, IAR0, are used to access data from Bank 0, while MP1 and IAR1 are used to access data from all banks according to BP register. Direct Addressing can only be used with Bank 0, all other Banks must be addressed indirectly using MP1 and IAR1.

The following example shows how to clear a section of four Data Memory locations already defined as locations adres1 to adres4.

Indirect Addressing Program Example

```
data .section ´data´
adres1   db ?
adres2   db ?
adres3   db ?
adres4   db ?
block    db ?
code .section at 0 ´code´
org 00h
start:
     mov a,04h               ; setup size of block
     mov block,a
     mov a,offset adres1     ; Accumulator loaded with first RAM address
     mov mp0,a               ; setup memory pointer with first RAM address
loop:
     clr IAR0                ; clear the data at address defined by mp0
     inc mp0                 ; increment memory pointer
     sdz block               ; check if last memory location has been cleared
     jmp loop
continue:
```

The important point to note here is that in the example shown above, no reference is made to specific Data Memory addresses.

Bank Pointer – BP

For this device, the Data Memory is divided into two banks, Bank 0 and Bank 1. Selecting the required Data Memory area is achieved using the Bank Pointer. Bit 0 of the Bank Pointer is used to select Data Memory Banks 0~1.

The Data Memory is initialised to Bank 0 after a reset, except for a WDT time-out reset in the Power Down Mode, in which case, the Data Memory bank remains unaffected. It should be noted that the Special Function Data Memory is not affected by the bank selection, which means that the Special Function Registers can be accessed from within any bank. Directly addressing the Data Memory will always result in Bank 0 being accessed irrespective of the value of the Bank Pointer. Accessing data from Bank 1 must be implemented using Indirect Addressing.

BP Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	DMBP0
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **DMBP0**: Select Data Memory Banks
0: Bank 0
1: Bank 1

Accumulator – ACC

The Accumulator is central to the operation of any microcontroller and is closely related with operations carried out by the ALU. The Accumulator is the place where all intermediate results from the ALU are stored. Without the Accumulator it would be necessary to write the result of each calculation or logical operation such as addition, subtraction, shift, etc., to the Data Memory resulting in higher programming and timing overheads. Data transfer operations usually involve the temporary storage function of the Accumulator; for example, when transferring data between one user defined register and another, it is necessary to do this by passing the data through the Accumulator as no direct transfer between two registers is permitted.

Program Counter Low Register – PCL

To provide additional program control functions, the low byte of the Program Counter is made accessible to programmers by locating it within the Special Purpose area of the Data Memory. By manipulating this register, direct jumps to other program locations are easily implemented. Loading a value directly into this PCL register will cause a jump to the specified Program Memory location, however, as the register is only 8-bit wide, only jumps within the current Program Memory page are permitted. When such operations are used, note that a dummy cycle will be inserted.

Look-up Table Registers – TBLP, TBLH

These two special function registers are used to control operation of the look-up table which is stored in the Program Memory. TBLP is the table pointer and indicates the location where the table data is located. Its value must be setup before any table read commands are executed. Its value can be changed, for example using the "INC" or "DEC" instructions, allowing for easy table data pointing and reading. TBLH is the location where the high order byte of the table data is stored after a table read data instruction has been executed. Note that the lower order table data byte is transferred to a user defined location.

Status Register – STATUS

This 8-bit register contains the zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). These arithmetic/logical operation and system management flags are used to record the status and operation of the microcontroller.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition, operations related to the status register may give different results due to the different instruction operations. The TO flag can be affected only by a system power-up, a WDT time-out or by executing the "CLR WDT" or "HALT" instruction. The PDF flag is affected only by executing the "HALT" or "CLR WDT" instruction or during a system power-up.

The Z, OV, AC and C flags generally reflect the status of the latest operations.

- C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. C is also affected by a rotate through carry instruction.
- AC is set if an operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
- Z is set if the result of an arithmetic or logical operation is zero; otherwise Z is cleared.
- OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
- PDF is cleared by a system power-up or executing the "CLR WDT" instruction. PDF is set by executing the "HALT" instruction.
- TO is cleared by a system power-up or executing the "CLR WDT" or "HALT" instruction. TO is set by a WDT time-out.

In addition, on entering an interrupt sequence or executing a subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status registers are important and if the subroutine can corrupt the status register, precautions must be taken to correctly save it.

STATUS Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	TO	PDF	OV	Z	AC	C
R/W	—	—	R	R	R/W	R/W	R/W	R/W
POR	—	—	0	0	x	x	x	x

"x": Unknown

Bit 7~6 Unimplemented, read as "0"

Bit 5 **TO**: Watchdog Time-Out flag
0: After power up or executing the "CLR WDT" or "HALT" instruction
1: A watchdog time-out occurred.

Bit 4 **PDF**: Power down flag
0: After power up or executing the «CLR WDT" instruction
1: By executing the "HALT" instruction

Bit 3 **OV**: Overflow flag
0: No overflow
1: An operation results in a carry into the highest-order bit but not a carry out of the highest-order bit or vice versa.

Bit 2 **Z**: Zero flag
0: The result of an arithmetic or logical operation is not zero
1: The result of an arithmetic or logical operation is zero

Bit 1 **AC**: Auxiliary flag
0: No auxiliary carry
1: An operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction

Bit 0 **C**: Carry flag
0: No carry-out
1: An operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation
C is also affected by a rotate through carry instruction.

EEPROM Data Memory

This device contains an area of internal EEPROM Data Memory. EEPROM, which stands for Electrically Erasable Programmable Read Only Memory, is by its nature a non-volatile form of re-programmable memory, with data retention even when its power supply is removed. By incorporating this kind of data memory, a whole new host of application possibilities are made available to the designer. The availability of EEPROM storage allows information such as product identification numbers, calibration values, specific user data, system setup data or other product information to be stored directly within the product microcontroller. The process of reading and writing data to the EEPROM memory has been reduced to a very trivial affair.

EEPROM Data Memory Structure

The EEPROM Data Memory capacity is 32×8 bits for the device. Unlike the Program Memory and RAM Data Memory, the EEPROM Data Memory is not directly mapped into memory space and is therefore not directly addressable in the same way as the other types of memory. Read and Write operations to the EEPROM are carried out in single byte operations using an address and a data register in Bank 0 and a single control register in Bank 1.

EEPROM Registers

Three registers control the overall operation of the internal EEPROM Data Memory. These are the address register, EEA, the data register, EED and a single control register, EEC. As both the EEA and EED registers are located in Bank 0, they can be directly accessed in the same way as any other Special Function Register. The EEC register however, being located in Bank 1, can be read from or written to indirectly using the MP1 Memory Pointer and Indirect Addressing Register, IAR1. Because the EEC control register is located at address 40H in Bank 1, the MP1 Memory Pointer must first be set to the value 40H and the Bank Pointer register, BP, set to the value, 01H, before any operations on the EEC register are executed.

Register Name	Bit							
	7	6	5	4	3	2	1	0
EEA	—	—	—	EEA4	EEA3	EEA2	EEA1	EEA0
EED	D7	D6	D5	D4	D3	D2	D1	D0
EEC	—	—	—	—	WREN	WR	RDEN	RD

EEPROM Registers List

EEA Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	EEA4	EEA3	EEA2	EEA1	EEA0
R/W	—	—	—	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	0	0	0	0	0

Bit 7~5 Unimplemented, read as "0"

Bit 4~0 **EEA4~EEA0**: Data EEPROM address
Data EEPROM address bit 4 ~ bit 0

EED Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Data EEPROM data
Data EEPROM data bit 7 ~ bit 0

EEC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	WREN	WR	RDEN	RD
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3 **WREN**: Data EEPROM Write Enable
0: Disable
1: Enable
This is the Data EEPROM Write Enable Bit which must be set high before Data EEPROM write operations are carried out. Clearing this bit to zero will inhibit Data EEPROM write operations.

Bit 2 **WR**: EEPROM Write Control
0: Write cycle has finished
1: Activate a write cycle
This is the Data EEPROM Write Control Bit and when set high by the application program will activate a write cycle. This bit will be automatically reset to zero by the hardware after the write cycle has finished. Setting this bit high will have no effect if the WREN has not first been set high.

Bit 1 **RDEN**: Data EEPROM Read Enable
0: Disable
1: Enable
This is the Data EEPROM Read Enable Bit which must be set high before Data EEPROM read operations are carried out. Clearing this bit to zero will inhibit Data EEPROM read operations.

Bit 0 **RD**: EEPROM Read Control
0: Read cycle has finished
1: Activate a read cycle
This is the Data EEPROM Read Control Bit and when set high by the application program will activate a read cycle. This bit will be automatically reset to zero by the hardware after the read cycle has finished. Setting this bit high will have no effect if the RDEN has not first been set high.

Note: The WREN, WR, RDEN and RD cannot be set high at the same time in one instruction. The WR and RD cannot be set high at the same time.

Reading Data from the EEPROM

To read data from the EEPROM, the read enable bit, RDEN, in the EEC register must first be set high to enable the read function. The EEPROM address of the data to be read must then be placed in the EEA register. If the RD bit in the EEC register is now set high, a read cycle will be initiated. Setting the RD bit high will not initiate a read operation if the RDEN bit has not been set. When the read cycle terminates, the RD bit will be automatically cleared to zero, after which the data can be read from the EED register. The data will remain in the EED register until another read or write operation is executed. The application program can poll the RD bit to determine when the data is valid for reading.

Writing Data to the EEPROM

To write data to the EEPROM, the EEPROM address of the data to be written must first be placed in the EEA register and the data placed in the EED register. Then the write enable bit, WREN, in the EEC register must first be set high to enable the write function. After this, the WR bit in the EEC register must be immediately set high to initiate a write cycle. These two instructions must be executed consecutively. The global interrupt bit EMI should also first be cleared before implementing any write operations, and then set again after the write cycle has started. Note that setting the WR bit high will not initiate a write cycle if the WREN bit has not been set. As the EEPROM write cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been written into the EEPROM. Detecting when the write cycle has finished can be implemented either by polling the WR bit in the EEC register or by using the EEPROM interrupt. When the write cycle terminates, the WR bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been written to the EEPROM. The application program can therefore poll the WR bit to determine when the write cycle has ended.

Write Protection

Protection against inadvertent write operation is provided in several ways. After the device is powered-on the Write Enable bit in the control register will be cleared preventing any write operations. Also at power-on the Bank Pointer, BP, will be reset to zero, which means that Data Memory Bank 0 will be selected. As the EEPROM control register is located in Bank 1, this adds a further measure of protection against spurious write operations. During normal program operation, ensuring that the Write Enable bit in the control register is cleared will safeguard against incorrect write operations.

EEPROM Interrupt

The EEPROM write interrupt is generated when an EEPROM write cycle has ended. The EEPROM interrupt must first be enabled by setting the DEE bit in the relevant interrupt register. However as the EEPROM is contained within a Multi-function Interrupt, the associated multi-function interrupt enable bit must also be set. When an EEPROM write cycle ends, the DEF request flag and its associated multi-function interrupt request flag will both be set. If the global, EEPROM and Multi-function interrupts are enabled and the stack is not full, a jump to the associated Multi-function Interrupt vector will take place. When the interrupt is serviced only the Multi-function interrupt flag will be automatically reset, the EEPROM interrupt flag must be manually reset by the application program. More details can be obtained in the Interrupt section.

Programming Considerations

Care must be taken that data is not inadvertently written to the EEPROM. Protection can be enhanced by ensuring that the Write Enable bit is normally cleared to zero when not writing. Also the Bank Pointer could be normally cleared to zero as this would inhibit access to Bank 1 where the EEPROM control register exist. Although certainly not necessary, consideration might be given in the application program to the checking of the validity of new write data by a simple read back process.

When writing data the WR bit must be set high immediately after the WREN bit has been set high, to ensure the write cycle executes correctly. The global interrupt bit EMI should also be cleared before a write cycle is executed and then re-enabled after the write cycle starts. Note that the device should not enter the IDLE or SLEEP mode until the EEPROM read or write operation is totally complete. Otherwise, the EEPROM read or write operation will fail.

Programming Examples

- **Reading data from the EEPROM – polling method**

```
MOV  A, EEPROM_ADRES      ; user defined address
MOV  EEA, A
MOV  A, 040H              ; setup memory pointer MP1
MOV  MP1, A               ; MP1 points to EEC register
MOV  A, 01H               ; setup Bank Pointer
MOV  BP, A
SET  IAR1.1               ; set RDEN bit, enable read operations
SET  IAR1.0               ; start Read Cycle - set RD bit
BACK:
SZ   IAR1.0               ; check for read cycle end
JMP  BACK
CLR  IAR1                 ; disable EEPROM read/write
CLR  BP
MOV  A, EED               ; move read data to register
MOV  READ_DATA, A
```

- **Writing Data to the EEPROM – polling method**

```
MOV  A, EEPROM_ADRES      ; user defined address
MOV  EEA, A
MOV  A, EEPROM_DATA       ; user defined data
MOV  EED, A
MOV  A, 040H              ; setup memory pointer MP1
MOV  MP1, A               ; MP1 points to EEC register
MOV  A, 01H               ; setup Bank Pointer
MOV  BP, A
CLR  EMI
SET  IAR1.3               ; set WREN bit, enable write operations
SET  IAR1.2               ; start Write Cycle - set WR bit – executed immediately
                          ; after set WREN bit
SET  EMI
BACK:
SZ   IAR1.2               ; check for write cycle end
JMP  BACK
CLR  IAR1                 ; disable EEPROM read/write
CLR  BP
```

Oscillators

Various oscillator options offer the user a wide range of functions according to their various application requirements. The flexible features of the oscillator functions ensure that the best optimisation can be achieved in terms of speed and power saving. Oscillator selections and operation are selected through registers.

Oscillator Overview

In addition to being the source of the main system clock the oscillators also provide clock sources for the Watchdog Timer and Time Base Interrupts. Fully integrated internal oscillators, requiring no external components, are provided to form a wide range of both fast and slow system oscillators. The higher frequency oscillators provide higher performance but carry with it the disadvantage of higher power requirements, while the opposite is of course true for the lower frequency oscillators. With the capability of dynamically switching between fast and slow system clock, the device has the flexibility to optimize the performance/power ratio, a feature especially important in power sensitive portable applications.

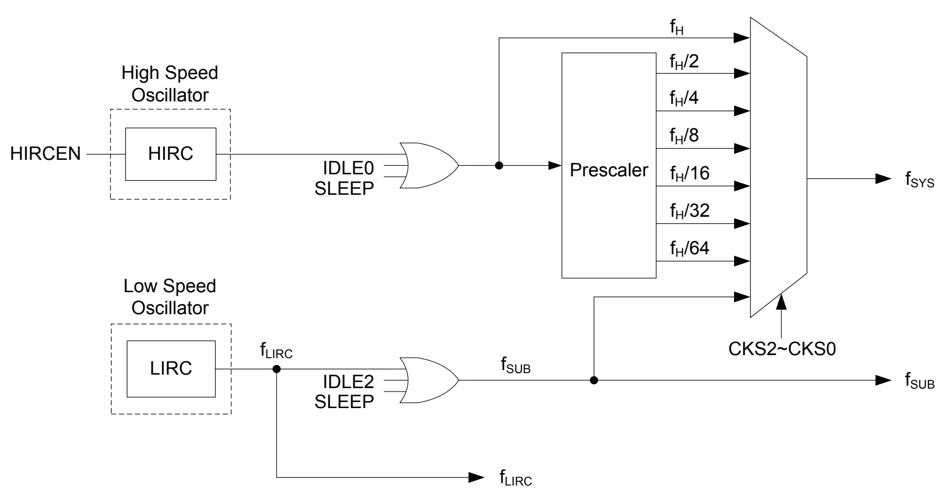
Type	Name	Frequency
Internal High Speed RC	HIRC	16MHz
Internal Low Speed RC	LIRC	32kHz

Oscillator Types

System Clock Configurations

There are two methods of generating the system clock, one high speed oscillator and one low speed oscillator. The high speed oscillator is the internal 16MHz RC oscillator. The low speed oscillator is the internal 32kHz RC oscillator. Selecting whether the low or high speed oscillator is used as the system oscillator is implemented using the CKS2~CKS0 bits in the SCC register and as the system clock can be dynamically selected.

The frequency of the slow speed or high speed system clock is also determined using CKS2~CKS0 bits in the SCC register. Note that two oscillator selections must be made namely one high speed and one low speed system oscillators. It is not possible to choose a no-oscillator selection for either the high or low speed oscillator.



System Clock Configurations

Internal RC Oscillator – HIRC

The internal RC oscillator is a fully integrated system oscillator requiring no external components. The internal RC oscillator has a fixed frequency of 16MHz. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised. It requires no external pins for its operation. Refer to the A.C. Characteristics for more frequency accuracy details.

Internal 32kHz Oscillator – LIRC

The internal 32kHz System Oscillator is the low frequency oscillator. It is a fully integrated RC oscillator with a typical frequency of 32kHz, requiring no external components for its implementation. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised. Refer to the A.C. Characteristics for more frequency accuracy details.

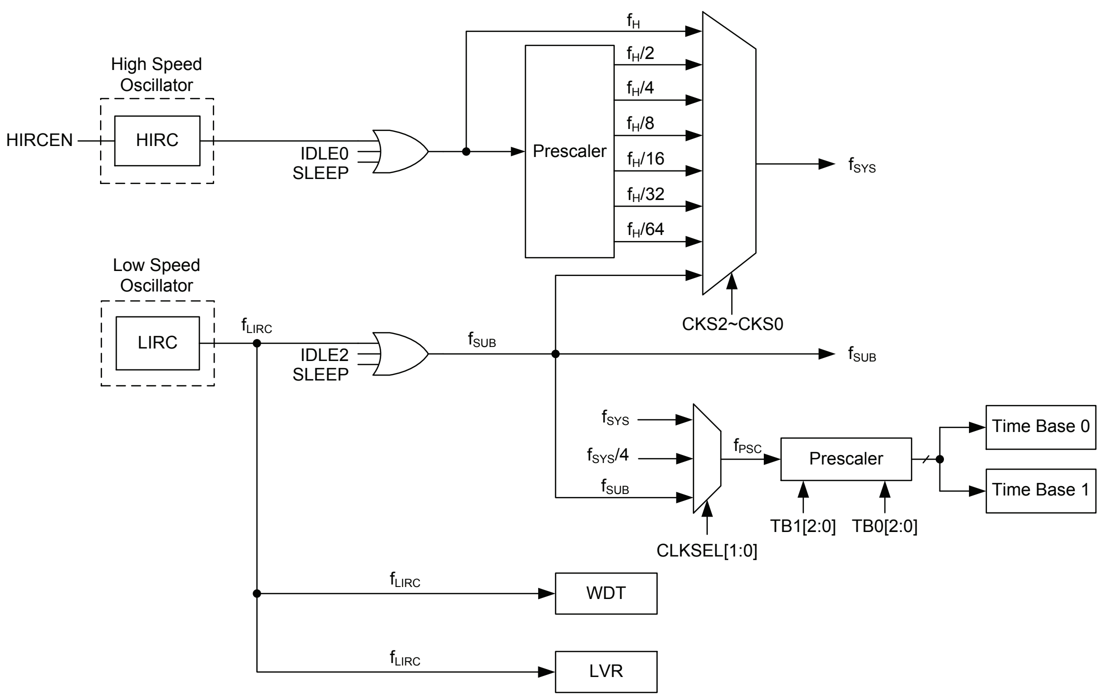
Operating Modes and System Clocks

Present day applications require that their microcontrollers have high performance but often still demand that they consume as little power as possible, conflicting requirements that are especially true in battery powered portable applications. The fast clocks required for high performance will by their nature increase current consumption and of course vice-versa, lower speed clocks reduce current consumption. As Holtek has provided this device with both high and low speed clock sources and the means to switch between them dynamically, the user can optimise the operation of their microcontroller to achieve the best performance/power ratio.

System Clocks

The device has many different clock sources for both the CPU and peripheral function operation. By providing the user with a wide range of clock options using register programming, a clock system can be configured to obtain maximum application performance.

The main system clock, can come from either a high frequency f_H or low frequency f_{SUB} source, and is selected using the CKS2~CKS0 bits in the SCC register. The high speed system clock can be sourced from the HIRC oscillator. The low speed system clock source can be sourced from the LIRC oscillator. The other choice, which is a divided version of the high speed system oscillator has a range of $f_H/2$~$f_H/64$.



Device Clock Configurations

Note: When the system clock source f_{SYS} is switched to f_{SUB} from f_H, the high speed oscillator can be stopped to conserve the power or continue to oscillate to provide the clock source, f_H ~ $f_H/64$, for peripheral circuit to use, which is determined by configuring the corresponding high speed oscillator enable control bit.

System Operation Modes

There are six different modes of operation for the microcontroller, each one with its own special characteristics and which can be chosen according to the specific performance and power requirements of the application. There are two modes allowing normal operation of the microcontroller, the FAST Mode and SLOW Mode. The remaining four modes, the SLEEP, IDLE0, IDLE1 and IDLE2 Mode are used when the microcontroller CPU is switched off to conserve power.

Operation Mode	CPU	Register Setting			f_{SYS}	f_H	f_{SUB}	f_{LIRC}
		FHIDEN	FSIDEN	CKS2~CKS0				
FAST	On	x	x	000~110	f_H ~ $f_H/64$	On	On	On
SLOW	On	x	x	111	f_{SUB}	On/Off (1)	On	On
IDLE0	Off	0	1	000~110	Off	Off	On	On
				111	On			
IDLE1	Off	1	1	xxx	On	On	On	On
IDLE2	Off	1	0	000~110	On	On	Off	On
				111	Off			
SLEEP	Off	0	0	xxx	Off	Off	Off	On/Off (2)

"x": Don't care

Note: 1. The f_H clock will be switched on or off by configuring the corresponding oscillator enable bit in the SLOW mode.

2. The f_{LIRC} clock can be switched on or off which is controlled by the WDT function being enabled or disabled in the SLEEP mode.

FAST Mode

As the name suggests this is one of the main operating modes where the microcontroller has all of its functions operational and where the system clock is provided by the high speed oscillator. This mode operates allowing the microcontroller to operate normally with a clock source will come from the high speed oscillator HIRC. The high speed oscillator will however first be divided by a ratio ranging from 1 to 64, the actual ratio being selected by the CKS2~CKS0 bits in the SCC register. Although a high speed oscillator is used, running the microcontroller at a divided clock ratio reduces the operating current.

SLOW Mode

This is also a mode where the microcontroller operates normally although now with a slower speed clock source. The clock source used will be from f_{SUB}. The f_{SUB} clock is derived from the LIRC oscillator. Running the microcontroller in this mode allows it to run with much lower operating currents. In the SLOW mode, the f_H clock will be switched on or off by configuring the corresponding oscillator enable bit HIRCEN.

SLEEP Mode

The SLEEP Mode is entered when an HALT instruction is executed and when the FHIDEN and FSIDEN bit are low. In the SLEEP mode the CPU will be stopped. However the f_{LIRC} clock can still continue to operate if the WDT function is enabled, the f_{LIRC} clock will be stopped too, if the Watchdog Timer function is disabled.

IDLE0 Mode

The IDLE0 Mode is entered when an HALT instruction is executed and when the FHIDEN bit in the SCC register is low and the FSIDEN bit in the SCC register is high. In the IDLE0 Mode the CPU will be switched off but the low speed oscillator will be turned on to drive some peripheral functions.

IDLE1 Mode

The IDLE1 Mode is entered when an HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is high. In the IDLE1 Mode the CPU will be switched off but both the high and low speed oscillators will be turned on to provide a clock source to keep some peripheral functions operational.

IDLE2 Mode

The IDLE2 Mode is entered when an HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is low. In the IDLE2 Mode the CPU will be switched off but the high speed oscillator will be turned on to provide a clock source to keep some peripheral functions operational.

Control Register

The registers, SCC and HIRCC, are used to control the system clock and the corresponding oscillator configurations.

SCC Register

Bit	7	6	5	4	3	2	1	0
Name	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
R/W	R/W	R/W	R/W	—	—	—	R/W	R/W
POR	0	0	1	—	—	—	0	0

Bit 7~5 **CKS2~CKS0**: System clock selection
000: f_H
001: $f_H/2$
010: $f_H/4$
011: $f_H/8$
100: $f_H/16$
101: $f_H/32$
110: $f_H/64$
111: f_{SUB}
These three bits are used to select which clock is used as the system clock source. In addition to the system clock source directly derived from f_H or f_{SUB}, a divided version of the high speed system oscillator can also be chosen as the system clock source.

Bit 4~2 Unimplemented, read as "0"

Bit 1 **FHIDEN**: High frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the high speed oscillator is activated or stopped when the CPU is switched off by executing an "HALT" instruction.

Bit 0 **FSIDEN**: Low frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the low speed oscillator is activated or stopped when the CPU is switched off by executing an "HALT" instruction.

HIRCC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	HIRCF	HIRCEN
R/W	—	—	—	—	—	—	R	R/W
POR	—	—	—	—	—	—	0	1

Bit 7~2 Unimplemented, read as "0"

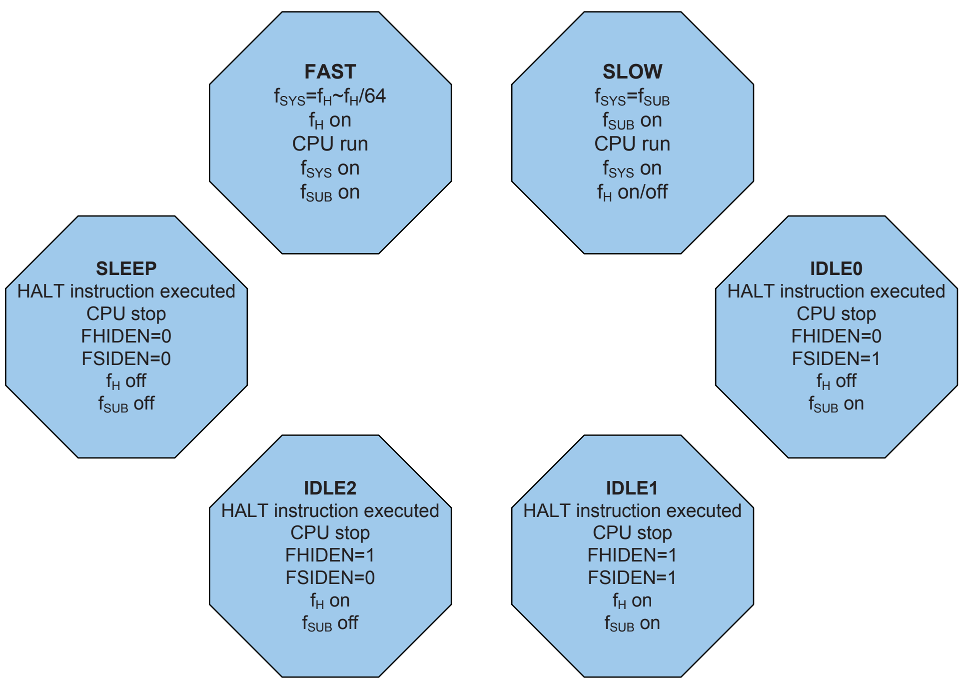
Bit 1 **HIRCF**: HIRC oscillator stable flag
0: HIRC unstable
1: HIRC stable
This bit is used to indicate whether the HIRC oscillator is stable or not. When the HIRCEN bit is set to 1 to enable the HIRC oscillator, the HIRCF bit will first be cleared to 0 and then set to 1 after the HIRC oscillator is stable.

Bit 0 **HIRCEN**: HIRC oscillator enable control
0: Disable
1: Enable

Operating Mode Switching

The device can switch between operating modes dynamically allowing the user to select the best performance/power ratio for the present task in hand. In this way microcontroller operations that do not require high performance can be executed using slower clocks thus requiring less operating current and prolonging battery life in portable applications.

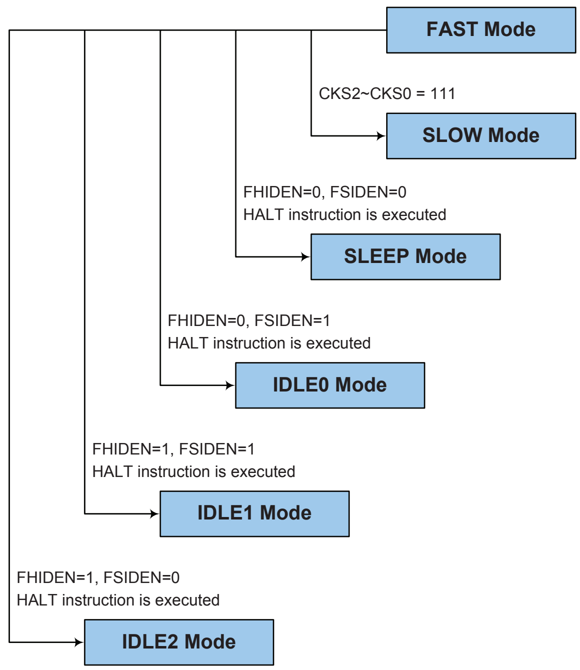
In simple terms, Mode Switching between the FAST Mode and SLOW Mode is executed using the CKS2~CKS0 bits in the SCC register while Mode Switching from the FAST/SLOW Modes to the SLEEP/IDLE Modes is executed via the HALT instruction. When a HALT instruction is executed, whether the device enters the IDLE Mode or the SLEEP Mode is determined by the condition of the FHIDEN and FSIDEN bits in the SCC register.



FAST Mode to SLOW Mode Switching

When running in the FAST Mode, which uses the high speed system oscillator, and therefore consumes more power, the system clock can switch to run in the SLOW Mode by set the CKS2~CKS0 bits to "111" in the SCC register. This will then use the low speed system oscillator which will consume less power. Users may decide to do this for certain operations which do not require high performance and can subsequently reduce power consumption.

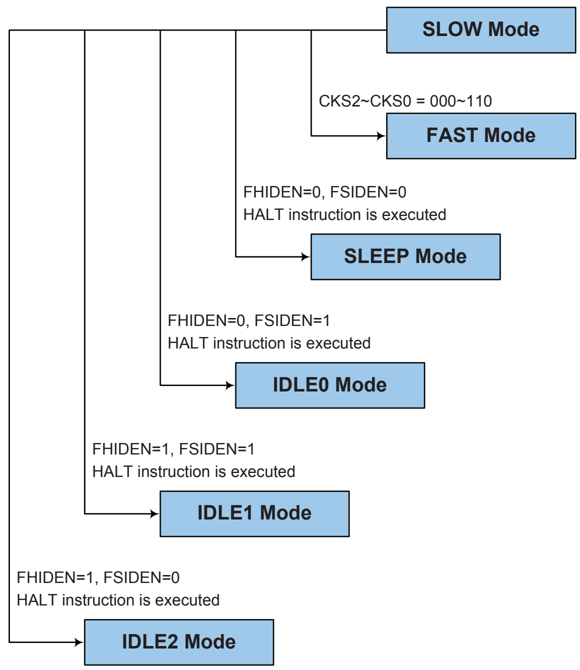
The SLOW Mode is sourced from the LIRC oscillator and therefore requires this oscillator to be stable before full mode switching occurs.



SLOW Mode to FAST Mode Switching

In SLOW mode the system clock is derived from f_{SUB}. When system clock is switched back to the FAST mode from f_{SUB}, the CKS2~CKS0 bits should be set to "000"~"110" and then the system clock will respectively be switched to f_H~ $f_H/64$.

However, if f_H is not used in SLOW mode and thus switched off, it will take some time to re-oscillate and stabilise when switching to the FAST mode from the SLOW Mode. This is monitored using the HIRCF bit in the HIRCC register. The time duration required for the high speed system oscillator stabilization is specified in the System Start Up Time Characteristics.



Entering the SLEEP Mode

There is only one way for the device to enter the SLEEP Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bit in SCC register equal to "0". In this mode all the clocks and functions will be switched off except the WDT function. When this instruction is executed under the conditions described above, the following will occur:

- The system clock will be stopped and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and stopped.

Entering the IDLE0 Mode

There is only one way for the device to enter the IDLE0 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in SCC register equal to "0" and the FSIDEN bit in SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be stopped and the application program will stop at the "HALT" instruction, but the f_{SUB} clock will be on.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and stopped.

Entering the IDLE1 Mode

There is only one way for the device to enter the IDLE0 Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H and f_{SUB} clocks will be on and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and stopped.

Entering the IDLE2 Mode

There is only one way for the device to enter the IDLE2 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "1" and the FSIDEN bit in the SCC register equal to "0". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be on but the f_{SUB} clock will be off and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and stopped.

Standby Current Considerations

As the main reason for entering the SLEEP or IDLE Mode is to keep the current consumption of the device to as low a value as possible, perhaps only in the order of several micro-amps except in the IDLE1 and IDLE2 Mode, there are other considerations which must also be taken into account by the circuit designer if the power consumption is to be minimised. Special attention must be made to the I/O pins on the device. All high-impedance input pins must be connected to either a fixed high or low level as any floating input pins could create internal oscillations and result in increased current consumption. This also applies to the device which has different package types, as there may be unbonded pins. These must either be setup as outputs or if setup as inputs must have pull-high resistors connected.

Care must also be taken with the loads, which are connected to I/O pins, which are setup as outputs. These should be placed in a condition in which minimum current is drawn or connected only to external circuits that do not draw current, such as other CMOS inputs. Also note that additional standby current will also be required if the LIRC oscillator has enabled.

In the IDLE1 and IDLE2 Mode the high speed oscillator is on, if the peripheral function clock source is derived from the high speed oscillator, the additional standby current will also be perhaps in the order of several hundred micro-amps.

Wake-up

To minimise power consumption the device can enter the SLEEP or any IDLE Mode, where the CPU will be switched off. However, when the device is woken up again, it will take a considerable time for the original system oscillator to restart, stabilise and allow normal operation to resume.

After the system enters the SLEEP or IDLE Mode, it can be woken up from one of various sources listed as follows:

- An external falling edge on I/O Port
- A system interrupt
- A WDT overflow

When the device executes the "HALT" instruction, the PDF flag will be set to 1. The PDF flag will be cleared to 0 if the device experiences a system power-up or executes the clear Watchdog Timer instruction. If the system is woken up by a WDT overflow, a Watchdog Timer reset will be initiated and the TO flag will be set to 1. The TO flag is set if a WDT time-out occurs and causes a wake-up that only resets the Program Counter and Stack Pointer, other flags remain in their original status.

Each pin on I/O Port can be setup using the PxWU register to permit a negative transition on the pin to wake-up the system. When a I/O Port pin wake-up occurs, the program will resume execution at the instruction following the "HALT" instruction. If the system is woken up by an interrupt, then two possible situations may occur. The first is where the related interrupt is disabled or the interrupt is enabled but the stack is full, in which case the program will resume execution at the instruction following the "HALT" instruction. In this situation, the interrupt which woke-up the device will not be immediately serviced, but will rather be serviced later when the related interrupt is finally enabled or when a stack level becomes free. The other situation is where the related interrupt is enabled and the stack is not full, in which case the regular interrupt response takes place. If an interrupt request flag is set high before entering the SLEEP or IDLE Mode, the wake-up function of the related interrupt will be disabled.

Watchdog Timer

The Watchdog Timer is provided to prevent program malfunctions or sequences from jumping to unknown locations, due to certain uncontrollable external events such as electrical noise.

Watchdog Timer Clock Source

The Watchdog Timer clock source is provided by the internal clock, f_{LIRC}, which is sourced from the LIRC oscillator. The LIRC internal oscillator has an approximate frequency of 32kHz and this specified internal clock period can vary with V_{DD}, temperature and process variations. The Watchdog Timer source clock is then subdivided by a ratio of 2^8 to 2^{18} to give longer timeouts, the actual value being chosen using the WS2~WS0 bits in the WDTC register.

Watchdog Timer Control Register

A single register, WDTC, controls the required timeout period as well as the enable/disable operation.

WDTC Register

Bit	7	6	5	4	3	2	1	0
Name	WE4	WE3	WE2	WE1	WE0	WS2	WS1	WS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	0	1	1

Bit 7~3 **WE4~WE0**: WDT function software control
10101: Disable
01010: Enable
Others: Reset MCU
When these bits are changed to any other values due to environmental noise the microcontroller will be reset; this reset operation will be activated after a delay time, t_{SRESET}, and the WRF bit in the RSTFC register will be set high.

Bit 2~0 **WS2~WS0**: WDT time-out period selection
000: $2^8/f_{LIRC}$
001: $2^{10}/f_{LIRC}$
010: $2^{12}/f_{LIRC}$
011: $2^{14}/f_{LIRC}$
100: $2^{15}/f_{LIRC}$
101: $2^{16}/f_{LIRC}$
110: $2^{17}/f_{LIRC}$
111: $2^{18}/f_{LIRC}$
These three bits determine the division ratio of the watchdog timer source clock, which in turn determines the time-out period.

RSTFC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

"x": Unknown

Bit 7~3 Unimplemented, read as "0"

Bit 2 **LVRF**: LVR function reset flag
Described elsewhere.

Bit 1 **LRF**: LVR Control register software reset flag
Described elsewhere.

Bit 0 **WRF**: WDT Control register software reset flag
0: Not occur
1: Occurred
This bit is set high by the WDT Control register software reset and cleared by the application program. Note that this bit can only be cleared to zero by the application program.

Watchdog Timer Operation

The Watchdog Timer operates by providing a device reset when its timer overflows. This means that in the application program and during normal operation the user has to strategically clear the Watchdog Timer before it overflows to prevent the Watchdog Timer from executing a reset. This is done using the clear watchdog instructions. If the program malfunctions for whatever reason, jumps to an unknown location, or enters an endless loop, these clear instructions will not be executed in the correct manner, in which case the Watchdog Timer will overflow and reset the device. There are five bits, WE4~WE0, in the WDTC register to offer the enable/disable control and reset control of the Watchdog Timer. The WDT function will be disabled when the WE4~WE0 bits are set to a value of 10101B while the WDT function will be enabled if the WE4~WE0 bits are equal to 01010B. If the WE4~WE0 bits are set to any other values, other than 01010B and 10101B, it will reset the device after a delay time, t_{SRESET}. After power on these bits will have a value of 01010B.

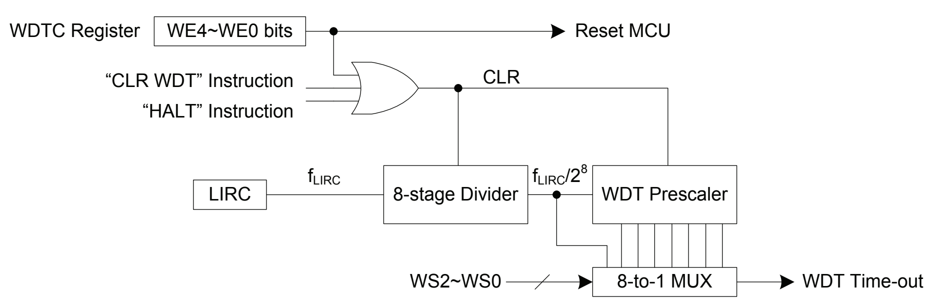
WE4 ~ WE0 Bits	WDT Function
10101B	Disable
01010B	Enable
Any other values	Reset MCU

Watchdog Timer Enable/Disable Control

Under normal program operation, a Watchdog Timer time-out will initialise a device reset and set the status bit TO. However, if the system is in the SLEEP or IDLE Mode, when a Watchdog Timer time-out occurs, the TO bit in the status register will be set and only the Program Counter and Stack Pointer will be reset. Three methods can be adopted to clear the contents of the Watchdog Timer. The first is a WDT reset, which means a certain value except 01010B and 10101B written into the WE4~WE0 bit filed, the second is using the Watchdog Timer software clear instruction and the third is via a HALT instruction.

There is only one method of using software instruction to clear the Watchdog Timer. That is to use the single "CLR WDT" instruction to clear the WDT.

The maximum time out period is when the 2^{18} division ratio is selected. As an example, with a 32kHz LIRC oscillator as its source clock, this will give a maximum watchdog period of around 8 second for the 2^{18} division ratio, and a minimum timeout of 8ms for the 2^8 division ration.



Watchdog Timer

Reset and Initialisation

A reset function is a fundamental part of any microcontroller ensuring that the device can be set to some predetermined condition irrespective of outside parameters. The most important reset condition is after power is first applied to the microcontroller. In this case, internal circuitry will ensure that the microcontroller, after a short delay, will be in a well-defined state and ready to execute the first program instruction. After this power-on reset, certain important internal registers will be set to defined states before the program commences. One of these registers is the Program Counter, which will be reset to zero forcing the microcontroller to begin program execution from the lowest Program Memory address.

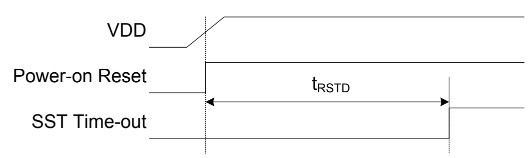
Another type of reset is when the Watchdog Timer overflows and resets. All types of reset operations result in different register conditions being setup. Another reset exists in the form of a Low Voltage Reset, LVR, where a full reset, is implemented in situations where the power supply voltage falls below a certain threshold.

Reset Functions

There are several ways in which a microcontroller reset can occur, through events occurring internally.

Power-on Reset

The most fundamental and unavoidable reset is the one that occurs after power is first applied to the microcontroller. As well as ensuring that the Program Memory begins execution from the first memory address, a power-on reset also ensures that certain other registers are preset to known conditions. All the I/O port and port control registers will power up in a high condition ensuring that all I/O ports will be first set to inputs.

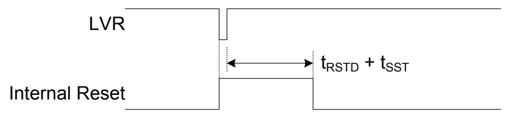


Note: t_{RSTD} is power-on delay, typical time=48ms

Power-On Reset Timing Chart

Low Voltage Reset – LVR

The microcontroller contains a low voltage reset circuit in order to monitor the supply voltage of the device. The LVR function is always enabled with a specific LVR voltage V_{LVR}. If the supply voltage of the device drops to within a range of 0.9V~V_{LVR} such as might occur when changing the battery, the LVR will automatically reset the device internally and the LVRF bit in the RSTFC register will also be set high. For a valid LVR signal, a low supply voltage, i.e., a voltage in the range between 0.9V~V_{LVR} must exist for a time greater than that specified by t_{LVR} in the LVD/LVR Electrical Characteristics. If the low supply voltage state does not exceed this value, the LVR will ignore the low supply voltage and will not perform a reset function. The actual V_{LVR} value can be selected by the LVS7~LVS0 bits in the LVRC register. If the LVS7~LVS0 bits are changed to some certain values by the environmental noise or software setting, the LVR will reset the device after a delay time, t_{SRESET}. When this happens, the LRF bit in the RSTFC register will be set high. After power on the register will have the value of 01010101B. Note that the LVR function will be automatically disabled when the device enters the power down mode.



Note: t_{RSTD} is power-on delay, typical time=48ms

Low Voltage Reset Timing Chart

- **LVRC Register**

Bit	7	6	5	4	3	2	1	0
Name	LVS7	LVS6	LVS5	LVS4	LVS3	LVS2	LVS1	LVS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	1	0	1

Bit 7~0 **LVS7~LVS0**: LVR voltage select
01010101: 2.1V
00110011: 2.55V
10011001: 3.15V
10101010: 3.8V
Other values: MCU reset

When an actual low voltage condition occurs, as specified by one of the four defined LVR voltage values above, an MCU reset will be generated. The reset operation will be activated after the low voltage condition keeps more than a t_{LVR} time. In this situation the register contents will remain the same after such a reset occurs.

Any register value, other than the four defined LVR values above, will also result in the generation of an MCU reset. The reset operation will be activated after a delay time, t_{SRESET}. However in this situation the register contents will be reset to the POR value.

- **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

"x": Unknown

Bit 7~3 Unimplemented, read as "0"

Bit 2 **LVRF**: LVR function reset flag
0: Not occur
1: Occurred

This bit is set high when a specific Low Voltage Reset situation condition occurs. This bit can only be cleared to zero by the application program.

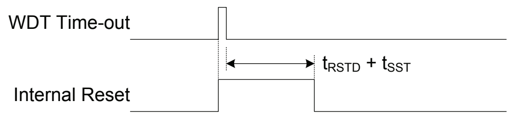
Bit 1 **LRF**: LVR Control register software reset flag
0: Not occur
1: Occurred

This bit is set high if the LVRC register contains any non-defined LVR voltage register values. This in effect acts like a software-reset function. This bit can only be cleared to zero by the application program.

Bit 0 **WRF**: WDT Control register software reset flag
Described elsewhere.

Watchdog Time-out Reset during Normal Operation

The Watchdog time-out Reset during normal operation in the FAST or SLOW mode is the same as LVR reset except that the Watchdog time-out flag TO will be set high.

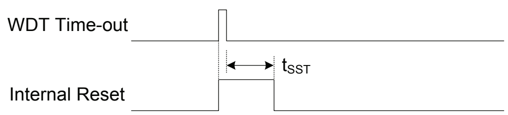


Note: t_{RSTD} is power-on delay, typical time=16ms

WDT Time-out Reset during Normal Operation Timing Chart

Watchdog Time-out Reset during SLEEP or IDLE Mode

The Watchdog time-out Reset during SLEEP or IDLE Mode is a little different from other kinds of reset. Most of the conditions remain unchanged except that the Program Counter and the Stack Pointer will be cleared to zero and the TO flag will be set high. Refer to the System Start Up Time Characteristics for t_{SST} details.



WDT Time-out Reset during Sleep or IDLE Mode Timing Chart

Reset Initial Conditions

The different types of reset described affect the reset flags in different ways. These flags, known as PDF and TO are located in the status register and are controlled by various microcontroller operations, such as the SLEEP or IDLE Mode function or Watchdog Timer. The reset flags are shown in the table:

TO	PDF	Reset Conditions
0	0	Power-on reset
u	u	LVR reset during FAST or SLOW Mode operation
1	u	WDT time-out reset during FAST or SLOW Mode operation
1	1	WDT time-out reset during IDLE or SLEEP Mode operation

Note: "u" stands for unchanged

The following table indicates the way in which the various components of the microcontroller are affected after a power-on reset occurs.

Item	Condition after Reset
Program Counter	Reset to zero
Interrupts	All interrupts will be disabled
WDT, Time Bases	Clear after reset, WDT begins counting
Timer Modules	Timer Modules will be turned off
Input/Output Ports	I/O ports will be setup as inputs
Stack Pointer	Stack Pointer will point to the top of the stack

The different kinds of resets all affect the internal registers of the microcontroller in different ways. To ensure reliable continuation of normal program execution after a reset occurs, it is important to know what condition the microcontroller is in after a particular reset occurs. The following table describes how each type of reset affects each of the microcontroller internal registers.

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
MP0	1xxx xxxx	1xxx xxxx	1uuu uuuu
MP1	1xxx xxxx	1xxx xxxx	1uuu uuuu
BP	---- ---0	---- ---0	---- ---u
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLH	--xx xxxx	--uu uuuu	--uu uuuu
STATUS	--00 xxxx	--1u uuuu	--11 uuuu
SCC	001- --00	001- --00	uuu- --uu
HIRCC	---- --01	---- --01	---- --uu
INTEG	---- 0000	---- 0000	---- uuuu
INTC0	-000 0000	-000 0000	-uuu uuuu
INTC1	0000 0000	0000 0000	uuuu uuuu
MFI0	--00 --00	--00 --00	--uu --uu
MFI1	--00 --00	--00 --00	--uu --uu
MFI2	-000 -000	-000 -000	-uuu -uuu
RSTFC	**---- -x00**	**---- -uuu**	**---- -uuu**
PA	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	uuuu uuuu
PAPU	0000 0000	0000 0000	uuuu uuuu
PAWU	0000 0000	0000 0000	uuuu uuuu
PB	---1 1111	---1 1111	---u uuuu
PBC	---1 1111	---1 1111	---u uuuu
PBPU	---0 0000	---0 0000	---u uuuu
LVDC	--00 0000	--00 0000	--uu uuuu
WDTC	0101 0011	0101 0011	uuuu uuuu
PSCR	---- --00	---- --00	---- --uu
EEA	---0 0000	---0 0000	---u uuuu
EED	0000 0000	0000 0000	uuuu uuuu
STMC0	0000 0000	0000 0000	uuuu uuuu
STMC1	0000 0000	0000 0000	uuuu uuuu
STMDL	0000 0000	0000 0000	uuuu uuuu
STMDH	---- --00	---- --00	---- --uu
STMAL	0000 0000	0000 0000	uuuu uuuu
STMAH	---- --00	---- --00	---- --uu
CTMC0	0000 0000	0000 0000	uuuu uuuu
CTMC1	0000 0000	0000 0000	uuuu uuuu
CTMDL	0000 0000	0000 0000	uuuu uuuu
CTMDH	---- --00	---- --00	---- --uu
CTMAL	0000 0000	0000 0000	uuuu uuuu
CTMAH	---- --00	---- --00	---- --uu
TB0C	0--- -000	0--- -000	u--- -uuu

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
TB1C	0 - - - - 0 0 0	0 - - - - 0 0 0	u - - - - u u u
IFS	- - - - - - - 0	- - - - - - - 0	- - - - - - - u
RFC0	- 0 1 0 1 0 1 1	- 0 1 0 1 0 1 1	- u u u u u u u
RFC1	1 1 1 1 1 - - -	1 1 1 1 1 - - -	u u u u u - - -
RFC2	- - 1 1 - - - -	- - 1 1 - - - -	- - u u - - - -
RFC3	0 0 0 0 0 0 0 0	0 0 0 0 0 0 0 0	u u u u u u u u
RFC4	0 0 0 0 0 0 0 0	0 0 0 0 0 0 0 0	u u u u u u u u
RFC5	0 0 0 0 0 0 0 0	0 0 0 0 0 0 0 0	u u u u u u u u
RFC6	1 0 0 0 1 0 0 0	1 0 0 0 1 0 0 0	u u u u u u u u
RFC7	0 0 0 0 0 0 0 0	0 0 0 0 0 0 0 0	u u u u u u u u
RFDEBC	0 - - - - 0 0 1	0 - - - - 0 0 1	u - - - - u u u
PXSR	0 0 - - 0 0 - 0	0 0 - - 0 0 - 0	u u - - u u - u
PBWU	- - - 0 0 0 0 0	- - - 0 0 0 0 0	- - - u u u u u
LVRC	0 1 0 1 0 1 0 1	0 1 0 1 0 1 0 1	u u u u u u u u
DRVCC	- - - - 0 0 0 0	- - - - 0 0 0 0	- - - - u u u u
SLEWC	0 0 0 0 0 0 0 0	0 0 0 0 0 0 0 0	u u u u u u u u
EEC	- - - - 0 0 0 0	- - - - 0 0 0 0	- - - - u u u u

Note: "u" stands for unchanged
"x" stands for unknown
"-" stands for unimplemented

Input/Output Ports

Holtek microcontrollers offer considerable flexibility on their I/O ports. With the input or output designation of every pin fully under user program control, pull-high selections for all ports and wake-up selections on certain pins, the user is provided with an I/O structure to meet the needs of a wide range of application possibilities.

The device provides bidirectional input/output lines labeled with port names PA and PB. These I/O ports are mapped to the RAM Data Memory with specific addresses as shown in the Special Purpose Data Memory table. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, which means the inputs must be ready at the T2 rising edge of instruction "MOV A, [m]", where m denotes the port address. For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PA	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
PAC	PAC7	PAC6	PAC5	PAC4	PAC3	PAC2	PAC1	PAC0
PAPU	PAPU7	PAPU6	PAPU5	PAPU4	PAPU3	PAPU2	PAPU1	PAPU0
PAWU	PAWU7	PAWU6	PAWU5	PAWU4	PAWU3	PAWU2	PAWU1	PAWU0
PB	—	—	—	PB4	PB3	PB2	PB1	PB0
PBC	—	—	—	PBC4	PBC3	PBC2	PBC1	PBC0
PBPU	—	—	—	PBPU4	PBPU3	PBPU2	PBPU1	PBPU0
PBWU	—	—	—	PBWU4	PBWU3	PBWU2	PBWU1	PBWU0

"–": Unimplemented, read as "0"

I/O Logic Function Registers List

Pull-high Resistors

Many product applications require pull-high resistors for their switch inputs usually requiring the use of an external resistor. To eliminate the need for these external resistors, all I/O pins, when configured as an input have the capability of being connected to an internal pull-high resistor. These pull-high resistors are selected using registers PAPU~PBPU, and are implemented using weak PMOS transistors.

Note that the pull-high resistor can be controlled by the relevant pull-high control register only when the pin-shared functional pin is selected as an input or NMOS output. Otherwise, the pull-high resistors cannot be enabled.

PxPU Register

Bit	7	6	5	4	3	2	1	0
Name	PxPU7	PxPU6	PxPU5	PxPU4	PxPU3	PxPU2	PxPU1	PxPU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

PxPUn: I/O Port x Pin pull-high function control

0: Disable

1: Enable

The PxPUn bit is used to control the pin pull-high function. Here the "x" can be A or B. However, the actual available bits for each I/O Port may be different.

I/O Port Wake-up

The HALT instruction forces the microcontroller into the SLEEP or IDLE Mode which preserves power, a feature that is important for battery and other low-power applications. Various methods exist to wake-up the microcontroller, one of which is to change the logic condition on one of the I/O Port pins from high to low. This function is especially suitable for applications that can be woken up via external switches. Each pin on I/O Port can be selected individually to have this wake-up feature using the PAWU~PBWU register.

Note that the wake-up function can be controlled by the wake-up control registers only when the pin-shared functional pin is selected as general purpose input/output and the MCU enters the Power down mode.

PxWU Register

Bit	7	6	5	4	3	2	1	0
Name	PxWU7	PxWU6	PxWU5	PxWU4	PxWU3	PxWU2	PxWU1	PxWU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

PxWUn: I/O Port x Pin wake-up function control
0: Disable
1: Enable

The PxWUn bit is used to control the pin wake-up function. Here the "x" can be A or B. However, the actual available bits for each I/O Port may be different.

I/O Port Control Registers

Each I/O port has its own control register known as PAC and PBC, to control the input/output configuration. With this control register, each CMOS output or input can be reconfigured dynamically under software control. Each pin of the I/O ports is directly mapped to a bit in its associated port control register. For the I/O pin to function as an input, the corresponding bit of the control register must be written as a "1". This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a "0", the I/O pin will be setup as a CMOS output. If the pin is currently setup as an output, instructions can still be used to read the output register. However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin.

PxC Register

Bit	7	6	5	4	3	2	1	0
Name	PxC7	PxC5	PxC5	PxC4	PxC3	PxC2	PxC1	PxC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	1	1	1	1	1	1	1	1

PxCn: I/O Port x Pin type selection
0: Output
1: Input

The PxCn bit is used to control the pin type selection. Here the "x" can be A or B. However, the actual available bits for each I/O Port may be different.

I/O Port Output Current Control Registers

The I/O ports, PA~PB, can be setup to have a choice of high or low drive currents using specific registers. The PA~PB must be selected by nibble pins to have various output current using the DRVCC register. Users should refer to the Input/Output Characteristics section to obtain the exact value for different applications.

DRVCC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	DRVCC3	DRVCC2	DRVCC1	DRVCC0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3 **DRVCC3**: PB4 source & sink current selection
0: Source & Sink current = Level 0 (Min.)
1: Source & Sink current = Level 1 (Max.)

Bit 2 **DRVCC2**: PB3~PB0 source & sink current selection
0: Source & Sink current = Level 0 (Min.)
1: Source & Sink current = Level 1 (Max.)

Bit 1 **DRVCC1**: PA7~PA4 source & sink current selection
0: Source & Sink current = Level 0 (Min.)
1: Source & Sink current = Level 1 (Max.)

Bit 0 **DRVCC0**: PA3~PA0 source & sink current selection
0: Source & Sink current = Level 0 (Min.)
1: Source & Sink current = Level 1 (Max.)

I/O Port Output Slew Rate Control Registers

The I/O ports, PA~PB, can be setup to have a choice of various slew rate using specific registers. The PA~PB must be selected by nibble pins to have various slew rate using the SLEWC register. Users should refer to the Input/Output Characteristics section to obtain the exact value for different applications.

SLEWC Register

Bit	7	6	5	4	3	2	1	0
Name	SLEWC7	SLEWC6	SLEWC5	SLEWC4	SLEWC3	SLEWC2	SLEWC1	SLEWC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **SLEWC7~SLEWC6**: PB4 output slew rate selection
00: Slew rate = Level 0
01: Slew rate = Level 1
10: Slew rate = Level 2
11: Slew rate = Level 3

Bit 5~4 **SLEWC5~SLEWC4**: PB3~PB0 output slew rate selection
00: Slew rate = Level 0
01: Slew rate = Level 1
10: Slew rate = Level 2
11: Slew rate = Level 3

Bit 3~2 **SLEWC3~SLEWC2**: PA7~PA4 output slew rate selection
00: Slew rate = Level 0
01: Slew rate = Level 1
10: Slew rate = Level 2
11: Slew rate = Level 3

Bit 1~0 **SLEWC1~SLEWC0**: PA3~PA0 output slew rate selection
00: Slew rate = Level 0
01: Slew rate = Level 1
10: Slew rate = Level 2
11: Slew rate = Level 3

Pin-shared Functions

The flexibility of the microcontroller range is greatly enhanced by the use of pins that have more than one function. Limited numbers of pins can force serious design constraints on designers but by supplying pins with multi-functions, many of these difficulties can be overcome. For these pins, the desired function of the multi-function I/O pins is selected by a series of registers via the application program control.

Pin-shared Function Selection Registers

The limited number of supplied pins in a package can impose restrictions on the amount of functions a certain device can contain. However by allowing the same pins to share several different functions and providing a means of function selection, a wide range of different functions can be incorporated into even relatively small package sizes. The device includes I/O Port Output Function Selection register, labeled as PXSR, and Input Function Selection register, labeled as IFS, which can select the desired functions of the multi-function pin-shared pins.

The most important point to note is to make sure that the desired pin-shared function is properly selected and also deselected. To select the desired pin-shared function, the pin-shared function should first be correctly selected using the corresponding pin-shared control register. After that the corresponding peripheral functional setting should be configured and then the peripheral function can be enabled. To correctly deselect the pin-shared function, the peripheral function should first be disabled and then the corresponding pin-shared function control register can be modified to select other pin-shared functions.

• **PXSR Register**

Bit	7	6	5	4	3	2	1	0
Name	PXS7	PXS6	—	—	PXS3	PXS2	—	PXS0
R/W	R/W	R/W	—	—	R/W	R/W	—	R/W
POR	0	0	—	—	0	0	—	0

Bit 7 **PXS7**: PA7 pin-shared function selection
0: PA7
1: CTPB

Bit 6 **PXS6**: PA6 pin-shared function selection
0: PA6
1: CTP

Bit 5~4 Unimplemented, read as "0"

Bit 3 **PXS3**: PA3 pin-shared function selection
0: PA3
1: STPB

Bit 2 **PXS2**: PA2 pin-shared function selection
0: PA2
1: STP

Bit 1 Unimplemented, read as "0"

Bit 0 **PXS0**: PB0 pin-shared function selection
0: PB0
1: RFDO

- **IFS Register**

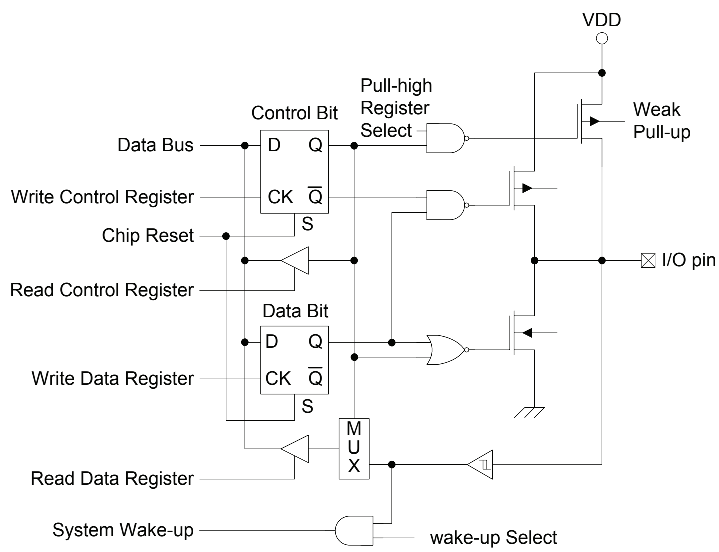
Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	STPIPS
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **STPIPS**: STPI input source pin selection
0: From external PA1 pin
1: From internal RFDATA signal
Note: RFDATA is RF digital data output signal.

I/O Pin Structures

The accompanying diagram illustrates the internal structures of the I/O logic function. As the exact logical construction of the I/O pin will differ from this drawing, it is supplied as a guide only to assist with the functional understanding of the logic function I/O pins. The wide range of pin-shared structures does not permit all types to be shown.



Logic Function Input/Output Structure

Programming Considerations

Within the user program, one of the first things to consider is port initialisation. After a reset, all of the I/O data and port control registers will be set high. This means that all I/O pins will default to an input state, the level of which depends on the other connected circuitry and whether pull-high selections have been chosen. If the port control registers, PAC~PBC, are then programmed to setup some pins as outputs, these output pins will have an initial high output value unless the associated port data registers, PA~PB, are first programmed. Selecting which pins are inputs and which are outputs can be achieved byte-wide by loading the correct values into the appropriate port control register or by programming individual bits in the port control register using the "SET [m].i" and "CLR [m].i" instructions. Note that when using these bit control instructions, a read-modify-write operation takes place. The microcontroller must first read in the data on the entire port, modify it to the required new bit values and then rewrite this data back to the output ports.

All I/O Ports have the additional capability of providing wake-up functions. When the device is in the SLEEP or IDLE Mode, various methods are available to wake the device up. One of these is a high to low transition of any of the I/O Port pins. Single or multiple pins on I/O Port can be setup to have this function.

Timer Modules – TM

One of the most fundamental functions in any microcontroller device is the ability to control and measure time. To implement time related functions the device includes several Timer Modules, abbreviated to the name TM. The TMs are multi-purpose timing units and serve to provide operations such as Timer/Counter, Input Capture, Compare Match Output and Single Pulse Output as well as being the functional unit for the generation of PWM signals. Each of the TMs has two individual interrupts. The addition of input and output pins for each TM ensures that users are provided with timing units with a wide and flexible range of features.

The common features of the different TM types are described here with more detailed information provided in the individual Compact and Standard TM sections.

Introduction

The device contains two TMs and each individual TM can be categorised as a certain type, namely Compact Type TM or Standard Type TM. Although similar in nature, the different TM types vary in their feature complexity. The common features to the Compact and Standard TMs will be described in this section. The detailed operation regarding each of the TM types will be described in separate sections. The main features and differences between the two types of TMs are summarised in the accompanying table.

Function	CTM	STM
Timer/Counter	√	√
Input Capture	—	√
Compare Match Output	√	√
PWM Channels	1	1
Single Pulse Output	—	1
PWM Alignment	Edge	Edge
PWM Adjustment Period & Duty	Duty or Period	Duty or Period

TM Function Summary

TM Operation

The different types of TMs offer a diverse range of functions, from simple timing operations to PWM signal generation. The key to understanding how the TM operates is to see it in terms of a free running counter whose value is then compared with the value of pre-programmed internal comparators. When the free running counter has the same value as the pre-programmed comparator, known as a compare match situation, a TM interrupt signal will be generated which can clear the counter and perhaps also change the condition of the TM output pin. The internal TM counter is driven by a user selectable clock source, which can be an internal clock or an external pin.

TM Clock Source

The clock source which drives the main counter in each TM can originate from various sources. The selection of the required clock source is implemented using the xTCK2~xTCK0 bits in the xTM control registers, where "x" stands for C, or S type TM. The clock source can be a ratio of the system clock f_{SYS} or the internal high clock f_H, the f_{SUB} clock source or the external xTCK pin. The xTCK pin clock source is used to allow an external signal to drive the TM as an external clock source or for event counting.

TM Interrupts

The Compact and Standard type TMs each has two internal interrupts, the internal comparator A or comparator P, which generate a TM interrupt when a compare match condition occurs. When a TM interrupt is generated, it can be used to clear the counter and also to change the state of the TM output pin.

TM External Pins

Each of the TMs, irrespective of what type, has one TM input pin, with the label xTCK. The xTM input pin, xTCK, is essentially a clock source for the xTM and is selected using the xTCK2~xTCK0 bits in the xTMC0 register. This external TM input pin allows an external clock source to drive the internal TM. The xTCK input pin can be chosen to have either a rising or falling active edge. The xTCK pin is also used as the external trigger input pin in single pulse output mode.

For the STM, the other input pin, STPI, is the capture input whose active edge can be a rising edge, a falling edge or both rising and falling edges and the active edge transition type is selected using the STIO1~STIO0 bits in the STMC1 register.

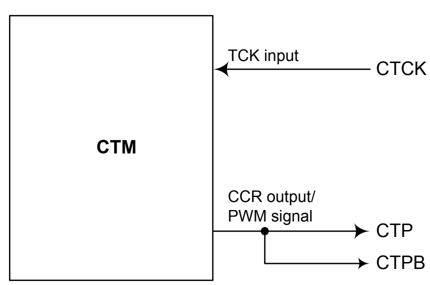
The TMs each have two output pins with the label xTP and xTPB. When the TM is in the Compare Match Output Mode, these pins can be controlled by the TM to switch to a high or low level or to toggle when a compare match situation occurs. The external xTP and xTPB output pins are also the pins where the TM generates the PWM output waveform. As the TM input and output pins are pin-shared with other functions, the TM input and output function must first be setup using relevant pin-shared function selection register described in the Pin-shared Function section.

CTM		STM	
Input	Output	Input	Output
CTCK	CTP, CTPB	STCK, STPI	STP, STPB

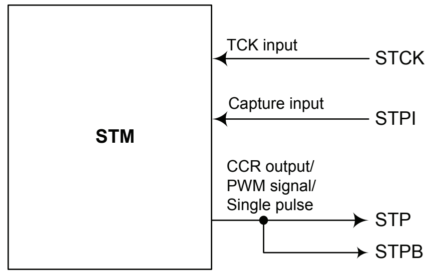
TM External Pins

TM Input/Output Pin Selection

Selecting to have a TM input/output or whether to retain its other shared function is implemented using the relevant pin-shared function selection registers, with the corresponding selection bits in each pin-shared function register corresponding to a TM input/output pin. Configuring the selection bits correctly will setup the corresponding pin as a TM input/output. The details of the pin-shared function selection are described in the pin-shared function section.



CTM Function Pin Control Block Diagram

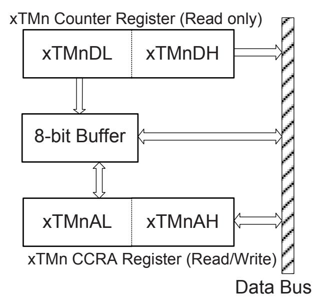


STM Function Pin Control Block Diagram

Programming Considerations

The TM Counter Registers and the Capture/Compare CCRA registers, all have a low and high byte structure. The high bytes can be directly accessed, but as the low bytes can only be accessed via an internal 8-bit buffer, reading or writing to these register pairs must be carried out in a specific way. The important point to note is that data transfer to and from the 8-bit buffer and its related low byte only takes place when a write or read operation to its corresponding high byte is executed.

As the CCRA registers are implemented in the way shown in the following diagram and accessing this register pair is carried out in a specific way described above, it is recommended to use the "MOV" instruction to access the CCRA low byte register, named xTMAL, in the following access procedures. Accessing the CCRA low byte register without following these access procedures will result in unpredictable values.

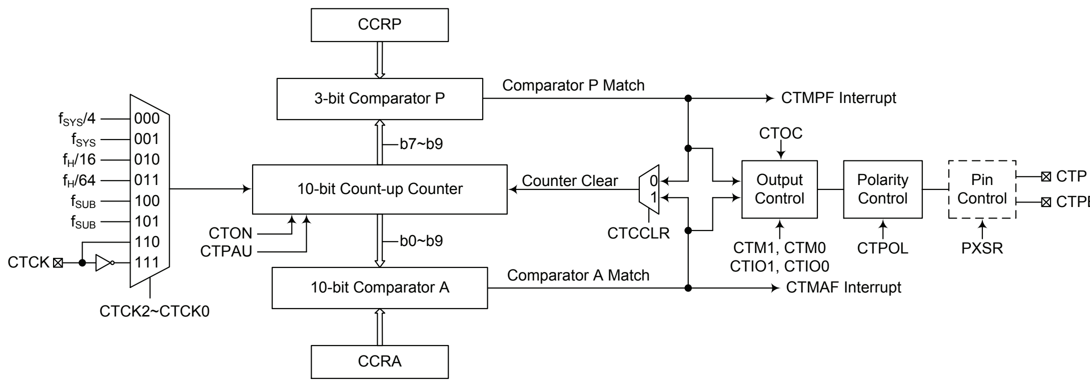


The following steps show the read and write procedures:

- Writing Data to CCRA
  - Step 1. Write data to Low Byte xTMAL
    – Note that here data is only written to the 8-bit buffer.
  - Step 2. Write data to High Byte xTMAH
    – Here data is written directly to the high byte registers and simultaneously data is latched from the 8-bit buffer to the Low Byte registers.
- Reading Data from the Counter Registers and or CCRA
  - Step 1. Read data from the High Byte xTMDH, xTMAH
    – Here data is read directly from the High Byte registers and simultaneously data is latched from the Low Byte register into the 8-bit buffer.
  - Step 2. Read data from the Low Byte xTMDL, xTMAL
    – This step reads data from the 8-bit buffer.

Compact Type TM – CTM

Although the simplest form of the three TM types, the Compact TM type still contains three operating modes, which are Compare Match Output, Timer/Event Counter and PWM Output modes. The Compact TM can also be controlled with an external input pin and can drive two external output pins.



Note: CTPB is the inverted output of CTP.

Compact Type TM Block Diagram

Compact TM Operation

At its core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRP is three bits wide whose value is compared with the highest three bits in the counter while the CCRA is the ten bits and therefore compares with all counter bits.

The only way of changing the value of the 10-bit counter using the application program, is to clear the counter by changing the CTON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators. When these conditions occur, a CTM interrupt signal will also usually be generated. The Compact Type TM can operate in a number of different operational modes, can be driven by different clock sources including an input pin and can also control two output pins. All operating setup conditions are selected using relevant internal registers.

Compact Type TM Register Description

Overall operation of each Compact TM is controlled using several registers. A read only register pair exists to store the internal counter 10-bit value, while a read/write register pair exists to store the internal 10-bit CCRA value. The remaining two registers are control registers which setup the different operating and control modes as well as the three CCRP bits.

Register Name	Bit							
	7	6	5	4	3	2	1	0
CTMC0	CTPAU	CTCK2	CTCK1	CTCK0	CTON	CTRP2	CTRP1	CTRP0
CTMC1	CTM1	CTM0	CTIO1	CTIO0	CTOC	CTPOL	CTDPX	CTCCLR
CTMDL	D7	D6	D5	D4	D3	D2	D1	D0
CTMDH	—	—	—	—	—	—	D9	D8
CTMAL	D7	D6	D5	D4	D3	D2	D1	D0
CTMAH	—	—	—	—	—	—	D9	D8

10-bit Compact TM Registers List

CTMC0 Register

Bit	7	6	5	4	3	2	1	0
Name	CTPAU	CTCK2	CTCK1	CTCK0	CTON	CTRP2	CTRP1	CTRP0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **CTPAU**: CTM Counter Pause Control

0: Run
1: Pause

The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the CTM will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **CTCK2~CTCK0**: Select CTM Counter clock

000: $f_{SYS}/4$
001: f_{SYS}
010: $f_H/16$
011: $f_H/64$
100: f_{SUB}
101: f_{SUB}
110: CTCK rising edge clock
111: CTCK falling edge clock

These three bits are used to select the clock source for the CTM. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_H and f_{SUB} are other internal clocks, the details of which can be found in the oscillator section.

Bit 3 **CTON**: CTM Counter On/Off Control

0: Off
1: On

This bit controls the overall on/off function of the CTM. Setting the bit high enables the counter to run, clearing the bit disables the CTM. Clearing this bit to zero will stop the counter from counting and turn off the CTM which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again.

If the CTM is in the Compare Match Output Mode or the PWM Output Mode then the CTM output pin will be reset to its initial condition, as specified by the CTOC bit, when the CTON bit changes from low to high.

Bit 2~0 **CTRP2~CTRP0**: CTM CCRP 3-bit register, compared with the CTM Counter bit 9~bit 7

Comparator P Match Period:

000: 1024 CTM clocks
001: 128 CTM clocks
010: 256 CTM clocks
011: 384 CTM clocks
100: 512 CTM clocks
101: 640 CTM clocks
110: 768 CTM clocks
111: 896 CTM clocks

These three bits are used to setup the value on the internal CCRP 3-bit register, which are then compared with the internal counter's highest three bits. The result of this comparison can be selected to clear the internal counter if the CTCCLR bit is set to zero. Setting the CTCCLR bit to zero ensures that a compare match with the CCRP values will reset the internal counter. As the CCRP bits are only compared with the highest three counter bits, the compare values exist in 128 clock cycle multiples. Clearing all three bits to zero is in effect allowing the counter to overflow at its maximum value.

CTMC1 Register

Bit	7	6	5	4	3	2	1	0
Name	CTM1	CTM0	CTIO1	CTIO0	CTOC	CTPOL	CTDPX	CTCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **CTM1~CTM0**: Select CTM Operating Mode
00: Compare Match Output Mode
01: Undefined
10: PWM Output Mode
11: Timer/Counter Mode

These bits setup the required operating mode for the CTM. To ensure reliable operation the CTM should be switched off before any changes are made to the CTM1 and CTM0 bits. In the Timer/Counter Mode, the CTM output pin control must be disabled.

Bit 5~4 **CTIO1~CTIO0**: Select CTM external pin (CTP/CTPB) function

Compare Match Output Mode
00: No change
01: Output low
10: Output high
11: Toggle output

PWM Output Mode
00: PWM output inactive state
01: PWM output active state
10: PWM output
11: Undefined

Timer/counter Mode:
Unused

These two bits are used to determine how the CTM output pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the CTM is running.

In the Compare Match Output Mode, the CTIO1~CTIO0 bits determine how the CTM output pin changes state when a compare match occurs from the Comparator A. The CTM output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the CTIO1~CTIO0 bits are both zero, then no change will take place on the output. The initial value of the CTM output pin should be setup using the CTOC bit. Note that the output level requested by the CTIO1~CTIO0 bits must be different from the initial value setup using the CTOC bit otherwise no change will occur on the CTM output pin when a compare match occurs. After the CTM output pin changes state it can be reset to its initial level by changing the level of the CTON bit from low to high.

In the PWM Output Mode, the CTIO1 and CTIO0 bits determine how the CTM output pin changes state when a certain compare match condition occurs. The PWM output function is modified by changing these two bits. It is necessary to change the values of the CTIO1 and CTIO0 bits only after the CTM has been switched off. Unpredictable PWM outputs will occur if the CTIO1 and CTIO0 bits are changed when the CTM is running.

Bit 3 **CTOC**: CTM CTP/CTPB Output control bit
Compare Match Output Mode
0: Initial low
1: Initial high
PWM Output Mode
0: Active low
1: Active high
This is the output control bit for the CTM output pin. Its operation depends upon whether CTM is being used in the Compare Match Output Mode or in the PWM Output Mode. It has no effect if the CTM is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the CTM output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low.

Bit 2 **CTPOL**: CTM CTP/CTPB Output polarity Control
0: Non-invert
1: Invert
This bit controls the polarity of the CTM output pins. When the bit is set high the CTM output pins will be inverted and not inverted when the bit is zero. It has no effect if the CTM is in the Timer/Counter Mode.

Bit 1 **CTDPX**: CTM PWM period/duty Control
0: CCRP - period; CCRA - duty
1: CCRP - duty; CCRA - period
This bit, determines which of the CCRA and CCRP registers are used for period and duty control of the PWM waveform.

Bit 0 **CTCCLR**: CTM Counter clear condition selection
0: CTM Comparatror P match
1: CTM Comparatror A match
This bit is used to select the method which clears the counter. Remember that the Compact TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the CTCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The CTCCLR bit is not used in the PWM Output Mode.

CTMDL Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: CTM Counter Low Byte Register bit 7 ~ bit 0
CTM 10-bit Counter bit 7 ~ bit 0

CTMDH Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: CTM Counter High Byte Register bit 1 ~ bit 0
CTM 10-bit Counter bit 9 ~ bit 8

CTMAL Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: CTM CCRA Low Byte Register bit 7 ~ bit 0
CTM 10-bit CCRA bit 7 ~ bit 0

CTMAH Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: CTM CCRA High Byte Register bit 1 ~ bit 0
CTM 10-bit CCRA bit 9 ~ bit 8

Compact Type TM Operating Modes

The Compact Type TM can operate in one of three operating modes, Compare Match Output Mode, PWM Output Mode or Timer/Counter Mode. The operating mode is selected using the CTM1 and CTM0 bits in the CTMC1 register.

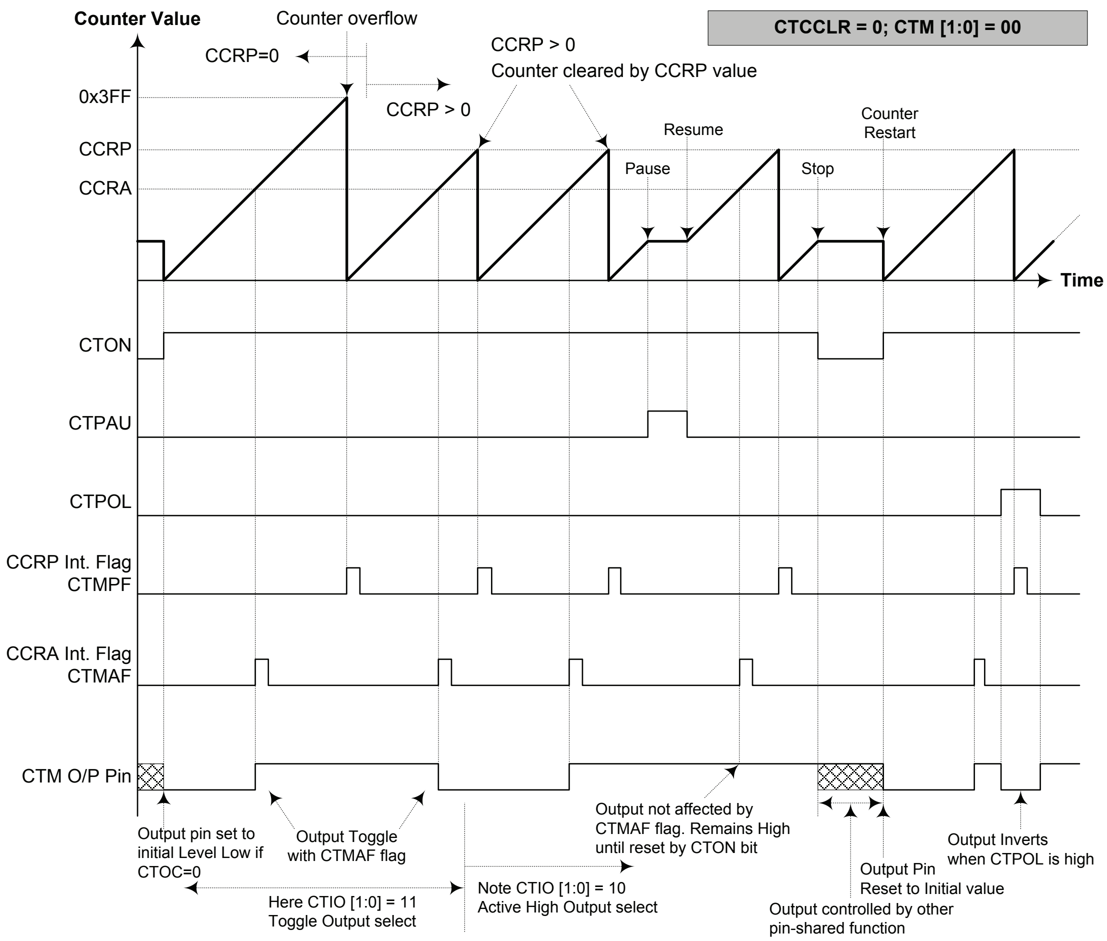
Compare Match Output Mode

To select this mode, bits CTM1 and CTM0 in the CTMC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the CTCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both CTMAF and CTMPF interrupt request flags for Comparator A and Comparator P respectively, will both be generated.

If the CTCCLR bit in the CTMC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the CTMAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when CTCCLR is high no CTMPF interrupt request flag will be generated.

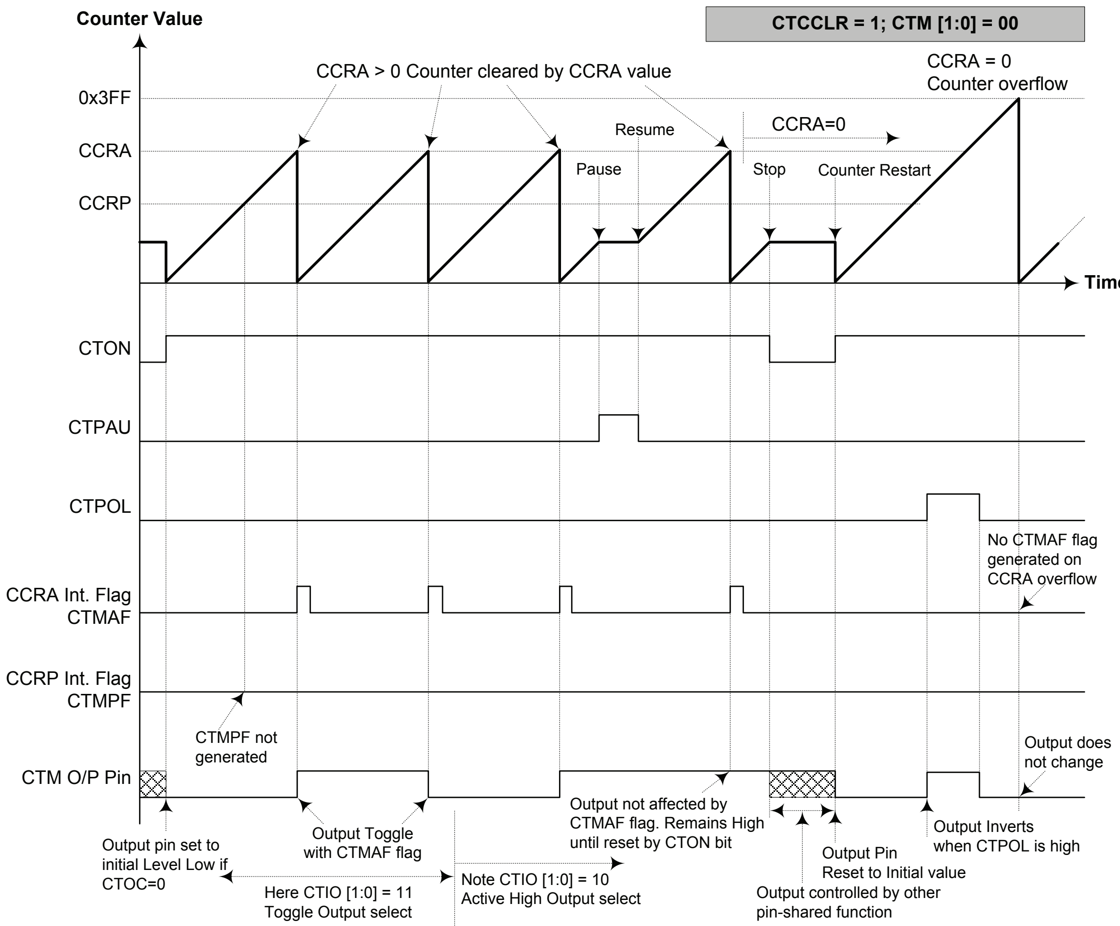
If the CCRA bits are all zero, the counter will overflow when its reaches its maximum 10-bit, 3FF Hex, value, however here the CTMAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is made, the CTM output pin, will change state. The CTM output pin condition however only changes state when a CTMAF interrupt request flag is generated after a compare match occurs from Comparator A. The CTMPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the CTM output pin. The way in which the CTM output pin changes state are determined by the condition of the CTIO1 and CTIO0 bits in the CTMC1 register. The CTM output pin can be selected using the CTIO1 and CTIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the CTM output pin, which is setup after the CTON bit changes from low to high, is setup using the CTOC bit. Note that if the CTIO1 and CTIO0 bits are zero then no pin change will take place.



Compare Match Output Mode – CTCCLR=0

Note: 1. With CTCCLR=0, a Comparator P match will clear the counter
2. The CTM output pin controlled only by the CTMAF flag
3. The output pin reset to initial state by a CTON bit rising edge



Compare Match Output Mode – CTCCLR=1

Note: 1. With CTCCLR=1, a Comparator A match will clear the counter
2. The CTM output pin controlled only by the CTMAF flag
3. The output pin reset to initial state by a CTON rising edge
4. The CTMPF flags is not generated when CTCCLR=1

Timer/Counter Mode

To select this mode, bits CTM1 and CTM0 in the CTMC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the CTM output pin is not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the CTM output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared function.

PWM Output Mode

To select this mode, bits CTM1 and CTM0 in the CTMC1 register should be set to 10 respectively. The PWM function within the CTM is useful for applications which require functions such as motor control, heating control, illumination control etc. By providing a signal of fixed frequency but of varying duty cycle on the CTM output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the CTCCLR bit has no effect as the PWM period. Both of the CCRA and CCRP registers are used to generate the PWM waveform, one register is used to clear the internal counter and thus control the PWM waveform frequency, while the other one is used to control the duty cycle. Which register is used to control either frequency or duty cycle is determined using the CTDPX bit in the CTMC1 register. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The CTOC bit In the CTMC1 register is used to select the required polarity of the PWM waveform while the two CTIO1 and CTIO0 bits are used to enable the PWM output or to force the CTM output pin to a fixed high or low level. The CTPOL bit is used to reverse the polarity of the PWM output waveform.

- **10-bit CTM, PWM Output Mode, Edge-aligned Mode, CTDPX=0**

CCRP	001b	010b	011b	100b	101b	110b	111b	000b
Period	128	256	384	512	640	768	896	1024
Duty	CCRA							

If f_{SYS} = 16MHz, CTM clock source is $f_{SYS}/4$, CCRP = 100b, CCRA =128,

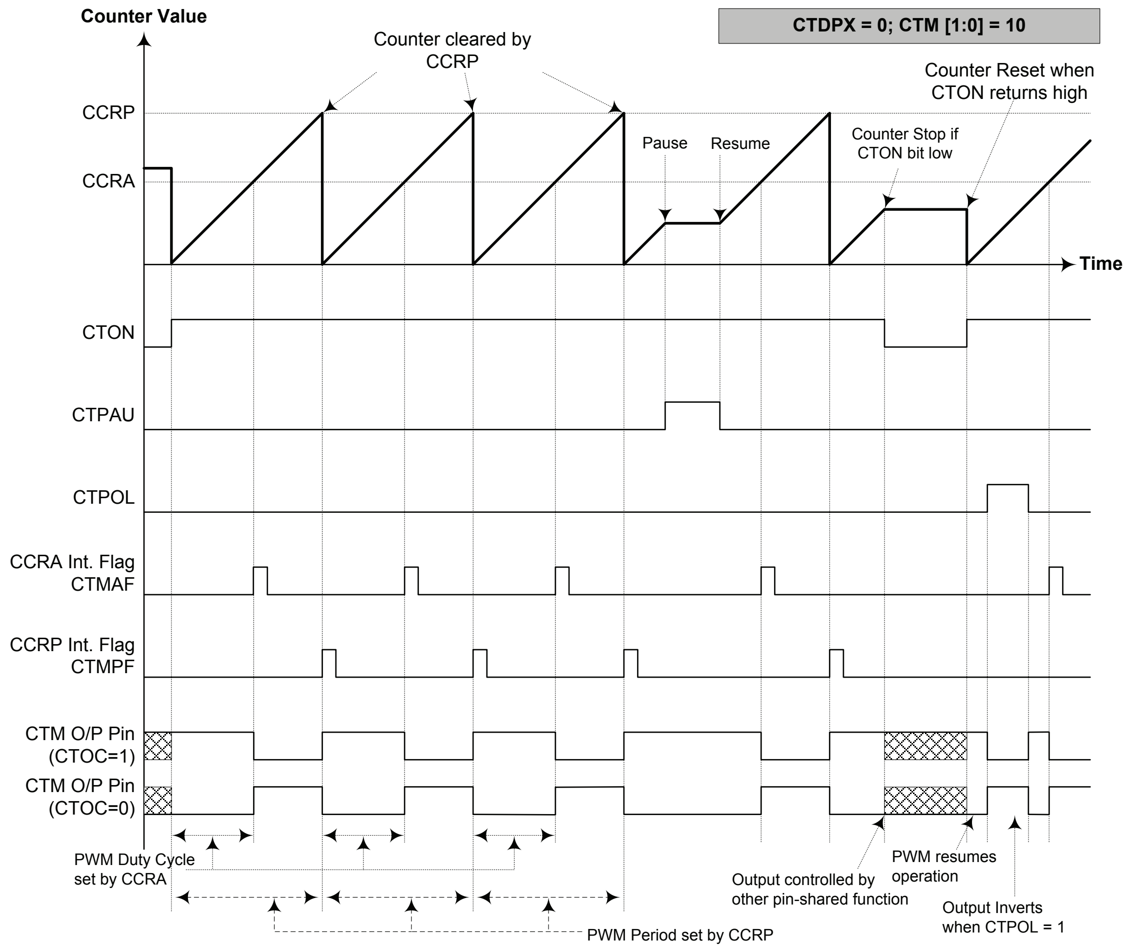
The CTM PWM output frequency = $(f_{SYS}/4)$ / 512 = $f_{SYS}/2048$ = 8kHz, duty = 128/512 = 25%.

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.

- **10-bit CTM, PWM Output Mode, Edge-aligned Mode, CTDPX=1**

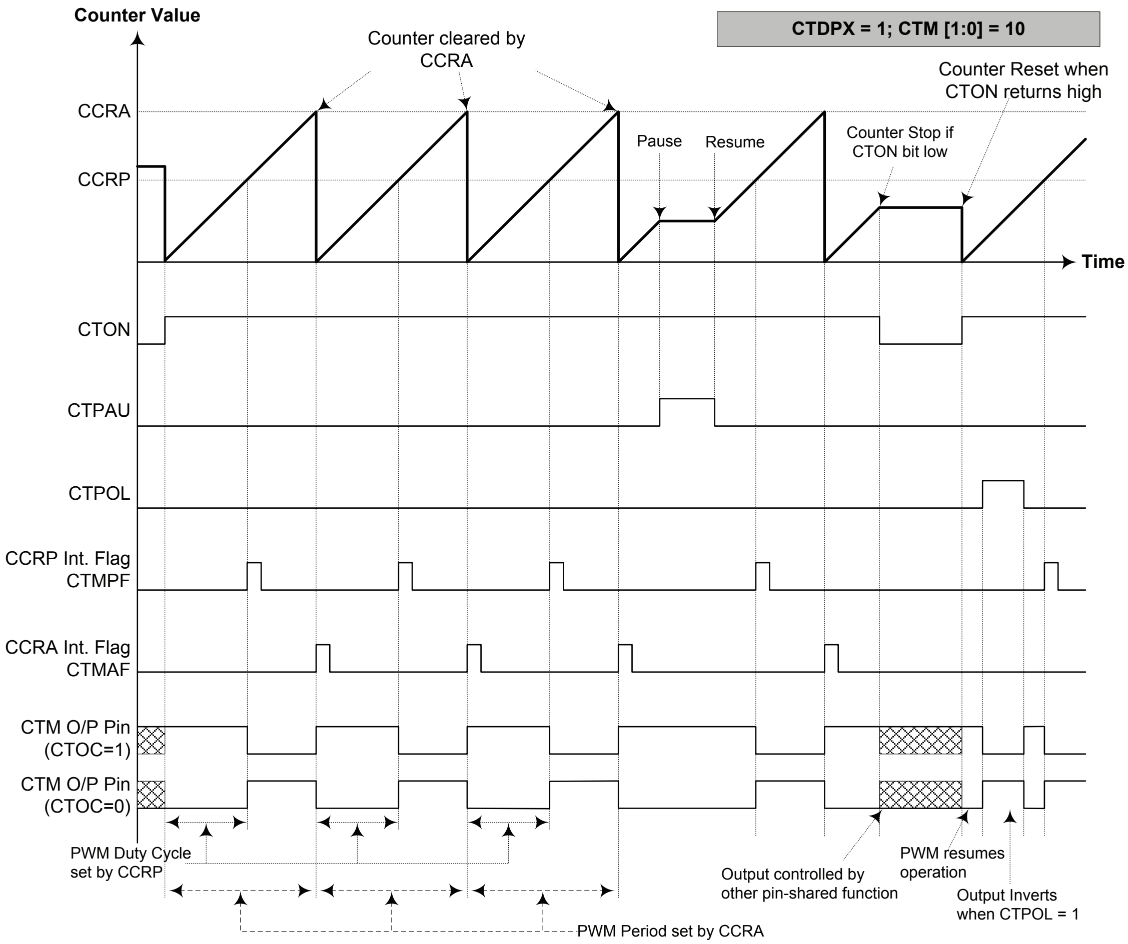
CCRP	001b	010b	011b	100b	101b	110b	111b	000b
Period	CCRA							
Duty	128	256	384	512	640	768	896	1024

The PWM output period is determined by the CCRA register value together with the CTM clock while the PWM duty cycle is defined by the CCRP register value.



PWM Output Mode – CTDPX=0

Note: 1. Here CTDPX=0 – Counter cleared by CCRP
2. A counter clear sets PWM Period
3. The internal PWM function continues running even when CTIO[1:0] = 00 or 01
4. The CTCCLR bit has no influence on PWM operation



PWM Output Mode – CTDPX=1

Note: 1. Here CTDPX=1 – Counter cleared by CCRA

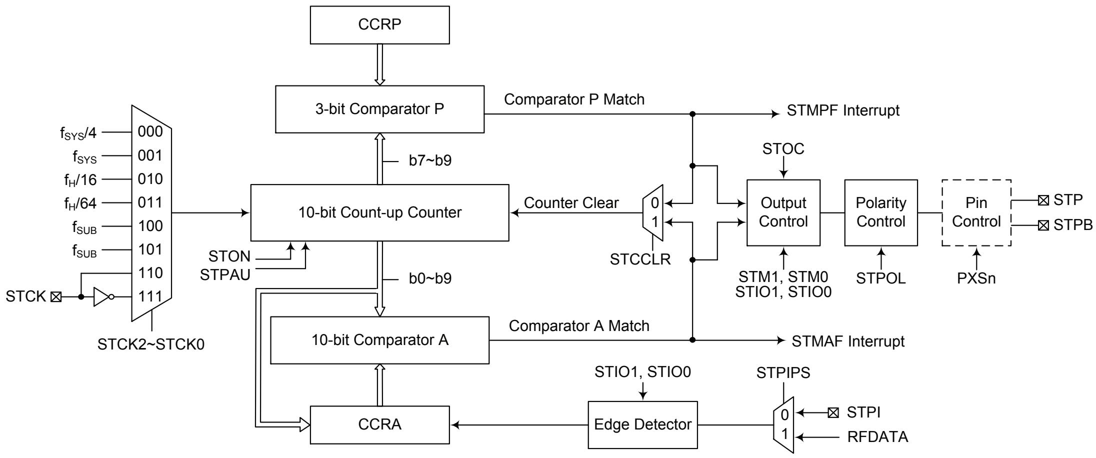
2. A counter clear sets PWM Period

3. The internal PWM function continues even when CTIO[1:0] = 00 or 01

4. The CTCCLR bit has no influence on PWM operation

Standard Type TM – STM

The Standard Type TM contains five operating modes, which are Compare Match Output, Timer/Event Counter, Capture Input, Single Pulse Output and PWM Output modes. The Standard TM can also be controlled with two external input pins and can drive two external output pins.



Note: 1. STPB is the inverted output of STP.
2. The STM capture input signal can be selected to come from the external STPI pin or the internal RFDATA signal, which is determined by the STPIPS bit in the IFS register.

Standard Type TM Block Diagram

Standard TM Operation

The size of Standard TM is 10-bit wide and its core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRP comparator is 3-bit wide whose value is compared with the highest 3 bits in the counter while the CCRA is the 10 bits and therefore compares all counter bits.

The only way of changing the value of the 10-bit counter using the application program, is to clear the counter by changing the STON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators. When these conditions occur, a STM interrupt signal will also usually be generated. The Standard Type TM can operate in a number of different operational modes, can be driven by different clock sources including an input pin and can also control two output pins. All operating setup conditions are selected using relevant internal registers.

Standard Type TM Register Description

Overall operation of the Standard TM is controlled using a series of registers. A read only register pair exists to store the internal counter 10-bit value, while a read/write register pair exists to store the internal 10-bit CCRA value. The remaining two registers are control registers which setup the different operating and control modes as well as three CCRP bits.

Register Name	Bit							
	7	6	5	4	3	2	1	0
STMC0	STPAU	STCK2	STCK1	STCK0	STON	STRP2	STRP1	STRP0
STMC1	STM1	STM0	STIO1	STIO0	STOC	STPOL	STDPX	STCCLR
STMDL	D7	D6	D5	D4	D3	D2	D1	D0
STMDH	—	—	—	—	—	—	D9	D8
STMAL	D7	D6	D5	D4	D3	D2	D1	D0
STMAH	—	—	—	—	—	—	D9	D8

10-bit Standard TM Registers List

STMC0 Register

Bit	7	6	5	4	3	2	1	0
Name	STPAU	STCK2	STCK1	STCK0	STON	STRP2	STRP1	STRP0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **STPAU**: STM Counter Pause control
0: Run
1: Pause
The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the STM will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **STCK2~STCK0**: Select STM Counter clock
000: $f_{SYS}/4$
001: f_{SYS}
010: $f_H/16$
011: $f_H/64$
100: f_{SUB}
101: f_{SUB}
110: STCK rising edge clock
111: STCK falling edge clock
These three bits are used to select the clock source for the STM. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_H and f_{SUB} are other internal clocks, the details of which can be found in the oscillator section.

Bit 3 **STON**: STM Counter On/Off control
0: Off
1: On
This bit controls the overall on/off function of the STM. Setting the bit high enables the counter to run while clearing the bit disables the STM. Clearing this bit to zero will stop the counter from counting and turn off the STM which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again. If the STM is in the Compare Match Output Mode, PWM Output Mode or Single Pulse Output Mode then the STM output pin will be reset to its initial condition, as specified by the STOC bit, when the STON bit changes from low to high.

Bit 2~0 **STRP2~STRP0**: STM CCRP 3-bit register, compared with the STM counter bit 9~bit 7

Comparator P Match Period =
000: 1024 STM clocks
001: 128 STM clocks
010: 256 STM clocks
011: 384 STM clocks
100: 512 STM clocks
101: 640 STM clocks
110: 768 STM clocks
111: 896 STM clocks

These three bits are used to setup the value on the internal CCRP 3-bit register, which are then compared with the internal counter's highest three bits. The result of this comparison can be selected to clear the internal counter if the STCCLR bit is set to zero. Setting the STCCLR bit to zero ensures that a compare match with the CCRP values will reset the internal counter. As the CCRP bits are only compared with the highest three counter bits, the compare values exist in 128 clock cycle multiples. Clearing all three bits to zero is in effect allowing the counter to overflow at its maximum value.

STMC1 Register

Bit	7	6	5	4	3	2	1	0
Name	STM1	STM0	STIO1	STIO0	STOC	STPOL	STDPX	STCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **STM1~STM0**: Select STM Operating Mode
00: Compare Match Output Mode
01: Capture Input Mode
10: PWM Output Mode or Single Pulse Output Mode
11: Timer/Counter Mode

These bits setup the required operating mode for the STM. To ensure reliable operation the STM should be switched off before any changes are made to the STM1 and STM0 bits. In the Timer/Counter Mode, the STM output pin control will be disabled.

Bit 5~4 **STIO1~STIO0**: Select STM external pin (STP/STPB or STPI) function

Compare Match Output Mode
00: No change
01: Output low
10: Output high
11: Toggle output

PWM Output Mode/Single Pulse Output Mode
00: PWM output inactive state
01: PWM output active state
10: PWM output
11: Single Pulse Output

Capture Input Mode
00: Input capture at rising edge of STPI
01: Input capture at falling edge of STPI
10: Input capture at rising/falling edge of STPI
11: Input capture disabled

Timer/Counter Mode
Unused

These two bits are used to determine how the STM external pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the STM is running.

In the Compare Match Output Mode, the STIO1 and STIO0 bits determine how the STM output pin changes state when a compare match occurs from the Comparator A. The STM output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the STM output pin should be setup using the STOC bit in the STMC1 register. Note that the output level requested by the STIO1 and STIO0 bits must be different from the initial value setup using the STOC bit otherwise no change will occur on the STM output pin when a compare match occurs. After the STM output pin changes state, it can be reset to its initial level by changing the level of the STON bit from low to high.

In the PWM Output Mode, the STIO1 and STIO0 bits determine how the STM output pin changes state when a certain compare match condition occurs. The PWM output function is modified by changing these two bits. It is necessary to only change the values of the STIO1 and STIO0 bits only after the STM has been switched off. Unpredictable PWM outputs will occur if the STIO1 and STIO0 bits are changed when the STM is running.

In the Capture Input Mode, the actual capture input trigger source can be from the external signal on the STPI pin or the internal RF out signal RFDATA, which is determined by the STPIPS bit in the IFS register.

Bit 3 **STOC**: STM STP/STPB Output control

Compare Match Output Mode
0: Initial low
1: Initial high

PWM Output Mode/Single Pulse Output Mode
0: Active low
1: Active high

This is the output control bit for the STM output pin. Its operation depends upon whether STM is being used in the Compare Match Output Mode or in the PWM Output Mode/Single Pulse Output Mode. It has no effect if the STM is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the STM output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low. In the Single Pulse Output Mode it determines the logic level of the STM output pin when the STON bit changes from low to high.

Bit 2 **STPOL**: STM STP/STPB Output polarity control
0: Non-inverted
1: Inverted

This bit controls the polarity of the STP output pin. When the bit is set high the STM output pin will be inverted and not inverted when the bit is zero. It has no effect if the STM is in the Timer/Counter Mode.

Bit 1 **STDPX**: STM PWM duty/period control
0: CCRP – period; CCRA – duty
1: CCRP – duty; CCRA – period

This bit determines which of the CCRA and CCRP registers are used for period and duty control of the PWM waveform.

Bit 0 **STCCLR**: STM Counter Clear condition selection
0: Comparator P match
1: Comparator A match

This bit is used to select the method which clears the counter. Remember that the Standard TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the STCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The STCCLR bit is not used in the PWM Output, Single Pulse Output or Capture Input Mode.

STMDL Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: STM Counter Low Byte Register bit 7 ~ bit 0
STM 10-bit Counter bit 7 ~ bit 0

STMDH Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: STM Counter High Byte Register bit 1 ~ bit 0
STM 10-bit Counter bit 9 ~ bit 8

STMAL Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: STM CCRA Low Byte Register bit 7 ~ bit 0
STM 10-bit CCRA bit 7 ~ bit 0

STMAH Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: STM CCRA High Byte Register bit 1 ~ bit 0
STM 10-bit CCRA bit 9 ~ bit 8

Standard Type TM Operation Modes

The Standard Type TM can operate in one of five operating modes, Compare Match Output Mode, PWM Output Mode, Single Pulse Output Mode, Capture Input Mode or Timer/Counter Mode. The operating mode is selected using the STM1 and STM0 bits in the STMC1 register.

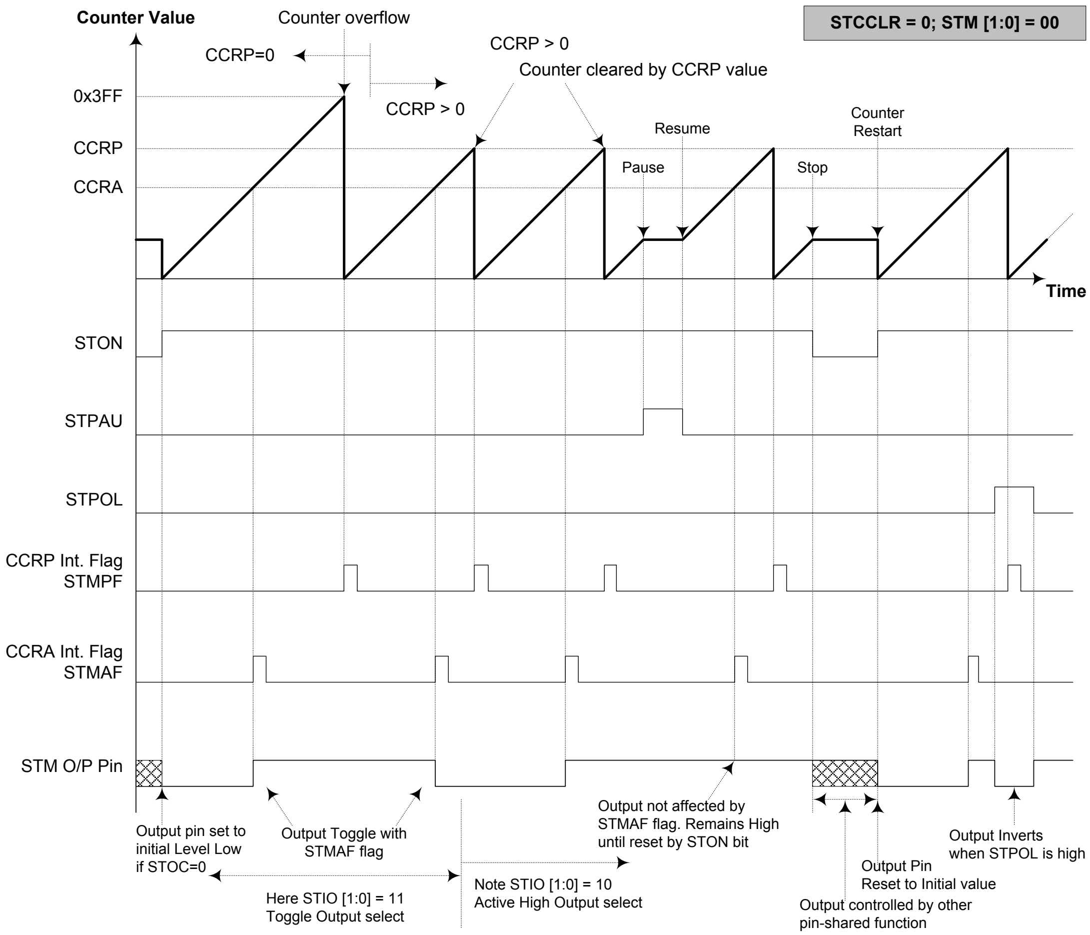
Compare Match Output Mode

To select this mode, bits STM1 and STM0 in the STMC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the STCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both STMAF and STMPF interrupt request flags for Comparator A and Comparator P respectively, will both be generated.

If the STCCLR bit in the STMC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the STMAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when STCCLR is high no STMPF interrupt request flag will be generated. In the Compare Match Output Mode, the CCRA cannot be set to "0".

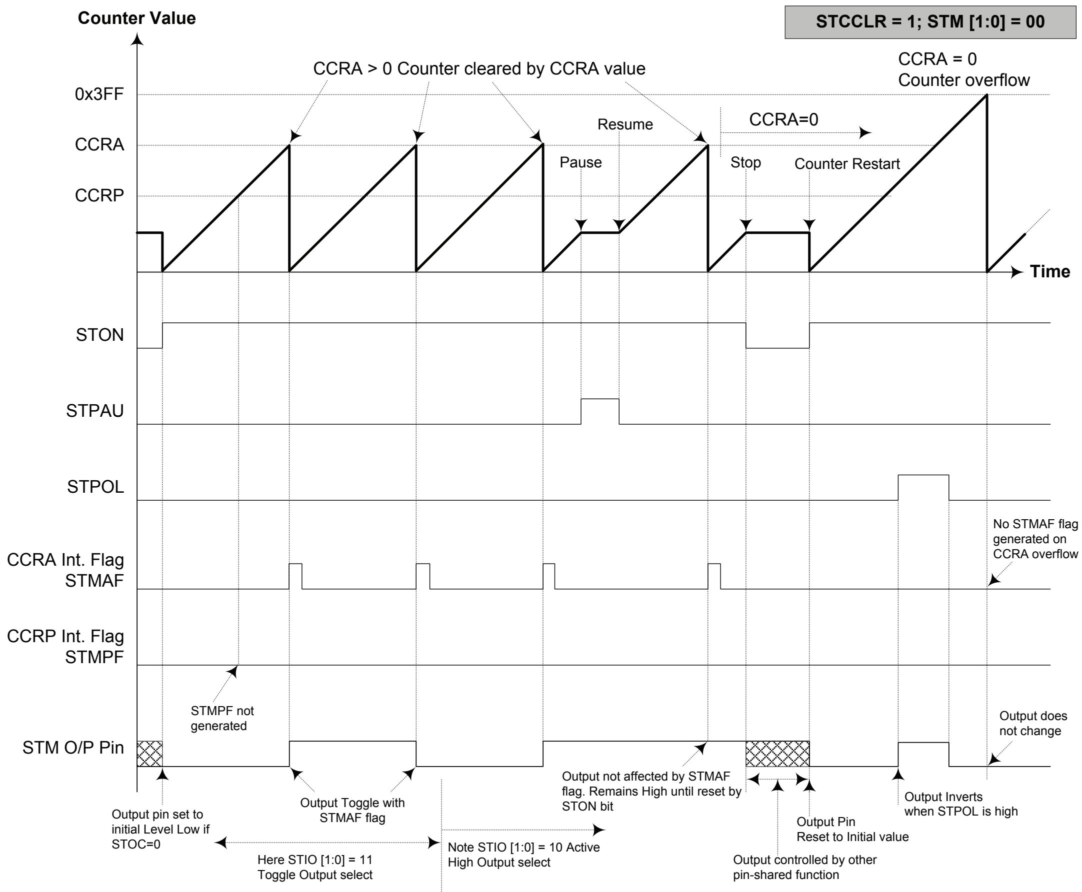
If the CCRA bits are all zero, the counter will overflow when it reaches its maximum 10-bit, 3FF Hex, value, however here the STMAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is made, the STM output pin, will change state. The STM output pin condition however only changes state when a STMAF interrupt request flag is generated after a compare match occurs from Comparator A. The STMPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the STM output pin. The way in which the STM output pin changes state are determined by the condition of the STIO1 and STIO0 bits in the STMC1 register. The STM output pin can be selected using the STIO1 and STIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the STM output pin, which is setup after the STON bit changes from low to high, is setup using the STOC bit. Note that if the STIO1 and STIO0 bits are zero then no pin change will take place.



Compare Match Output Mode – STCCLR=0

Note: 1. With STCCLR=0 a Comparator P match will clear the counter
2. The STM output pin is controlled only by the STMAF flag
3. The output pin is reset to its initial state by a STON bit rising edge



Compare Match Output Mode – STCCLR=1

Note: 1. With STCCLR=1 a Comparator A match will clear the counter
2. The STM output pin is controlled only by the STMAF flag
3. The output pin is reset to its initial state by a STON bit rising edge
4. A STMPF flag is not generated when STCCLR=1

Timer/Counter Mode

To select this mode, bits STM1 and STM0 in the STMC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the STM output pin is not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the STM output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared function.

PWM Output Mode

To select this mode, bits STM1 and STM0 in the STMC1 register should be set to 10 respectively and also the STIO1 and STIO0 bits should be set to 10 respectively. The PWM function within the STM is useful for applications which require functions such as motor control, heating control, illumination control etc. By providing a signal of fixed frequency but of varying duty cycle on the STM output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the STCCLR bit has no effect as the PWM period. Both of the CCRA and CCRP registers are used to generate the PWM waveform, one register is used to clear the internal counter and thus control the PWM waveform frequency, while the other one is used to control the duty cycle. Which register is used to control either frequency or duty cycle is determined using the STDPX bit in the STMC1 register. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The STOC bit in the STMC1 register is used to select the required polarity of the PWM waveform while the two STIO1 and STIO0 bits are used to enable the PWM output or to force the STM output pin to a fixed high or low level. The STPOL bit is used to reverse the polarity of the PWM output waveform.

- **10-bit STM, PWM Output Mode, Edge-aligned Mode, STDPX=0**

CCRP	001b	010b	011b	100b	101b	110b	111b	000b
Period	128	256	384	512	640	768	896	1024
Duty	CCRA							

If f_{SYS} = 16MHz, TM clock source is $f_{SYS}/4$, CCRP = 100b and CCRA =128,

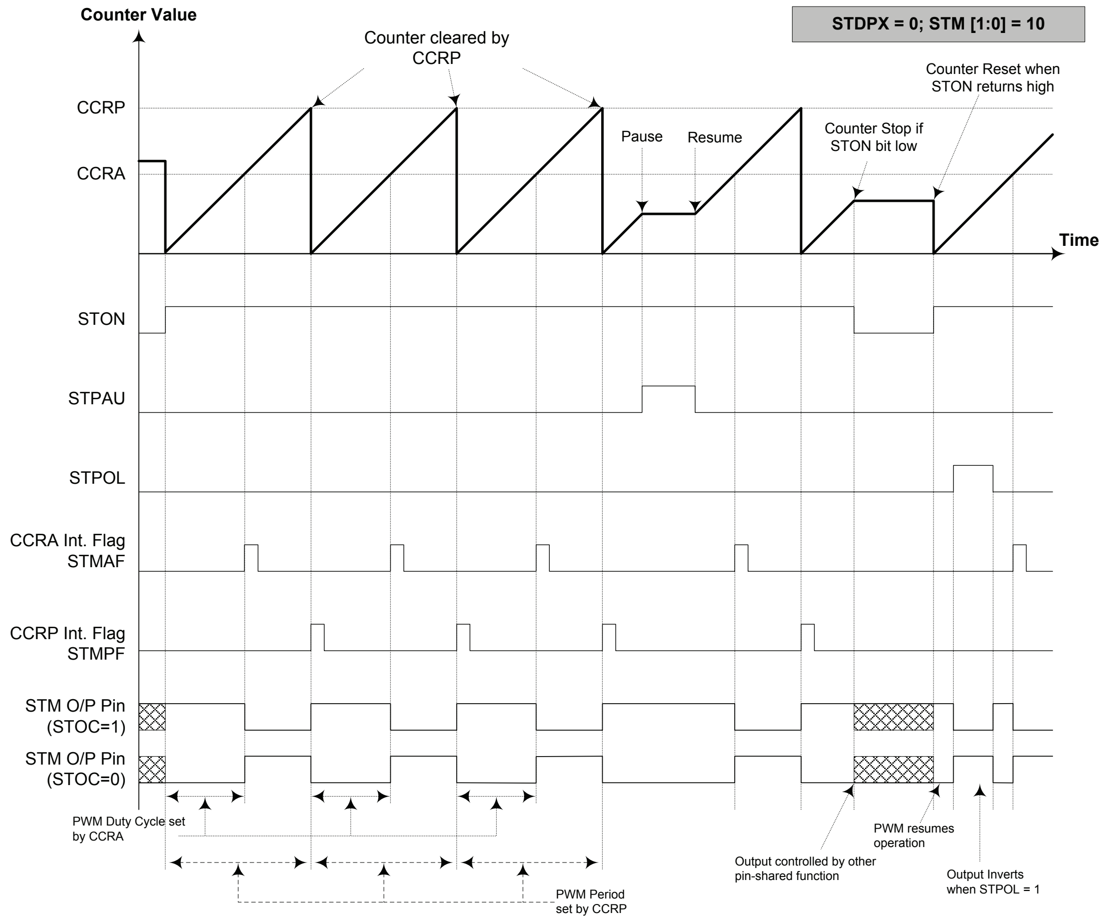
The STM PWM output frequency = $(f_{SYS}/4)$ / 512 = $f_{SYS}/2048$ = 8kHz, duty = 128/512 = 25%.

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.

- **10-bit STM, PWM Output Mode, Edge-aligned Mode, STDPX=1**

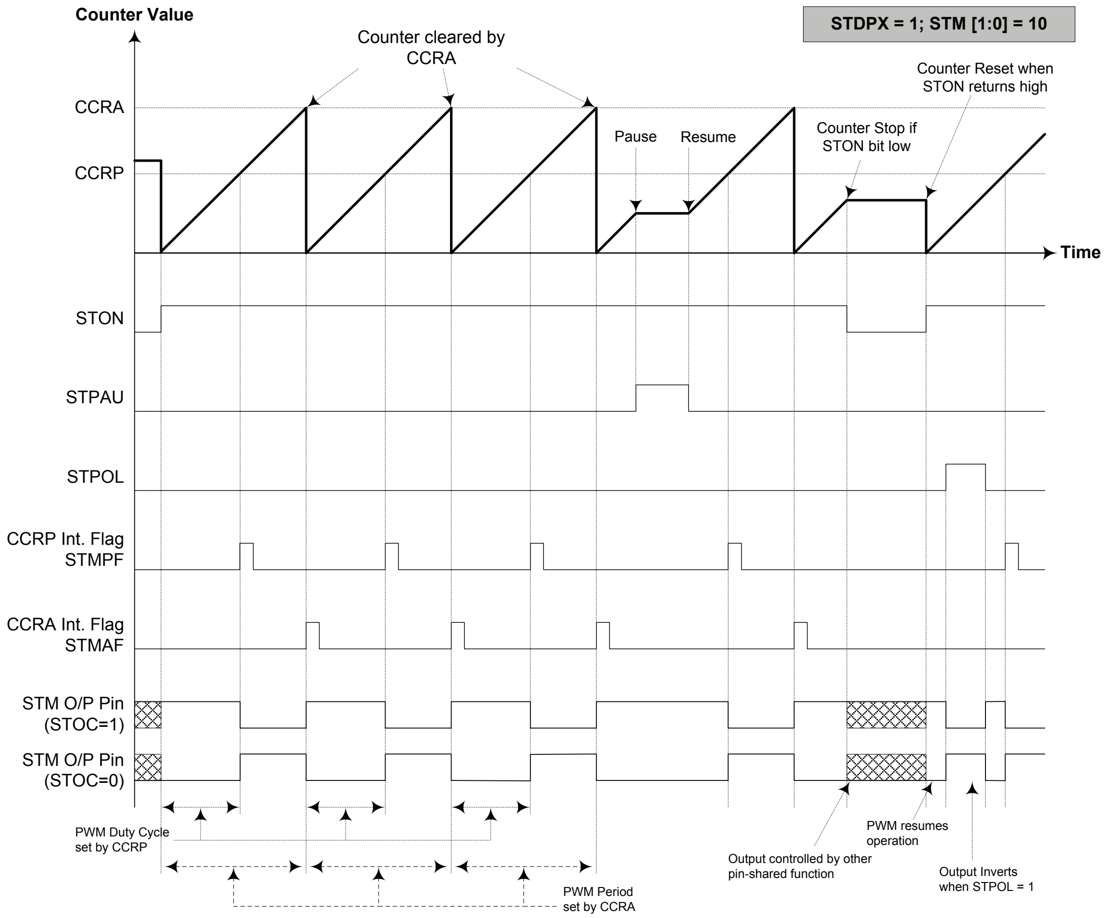
CCRP	001b	010b	011b	100b	101b	110b	111b	000b
Period	CCRA							
Duty	128	256	384	512	640	768	896	1024

The PWM output period is determined by the CCRA register value together with the STM clock while the PWM duty cycle is defined by the CCRP register value.



PWM Output Mode – STDPX=0

Note: 1. Here STDPX=0 – Counter cleared by CCRP
2. A counter clear sets the PWM Period
3. The internal PWM function continues running even when STIO[1:0] = 00 or 01
4. The STCCLR bit has no influence on PWM operation



PWM Output Mode – STDPX=1

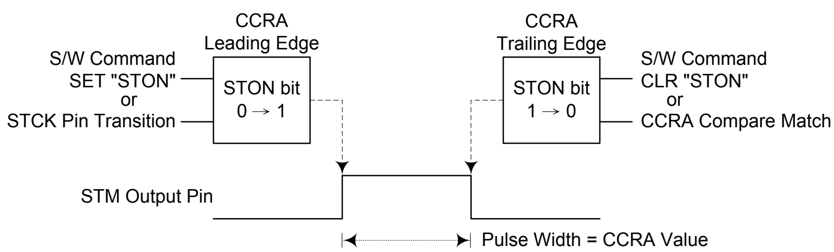
Note: 1. Here STDPX=1 – Counter cleared by CCRA
2. A counter clear sets the PWM Period
3. The internal PWM function continues even when STIO[1:0] = 00 or 01
4. The STCCLR bit has no influence on PWM operation

Single Pulse Output Mode

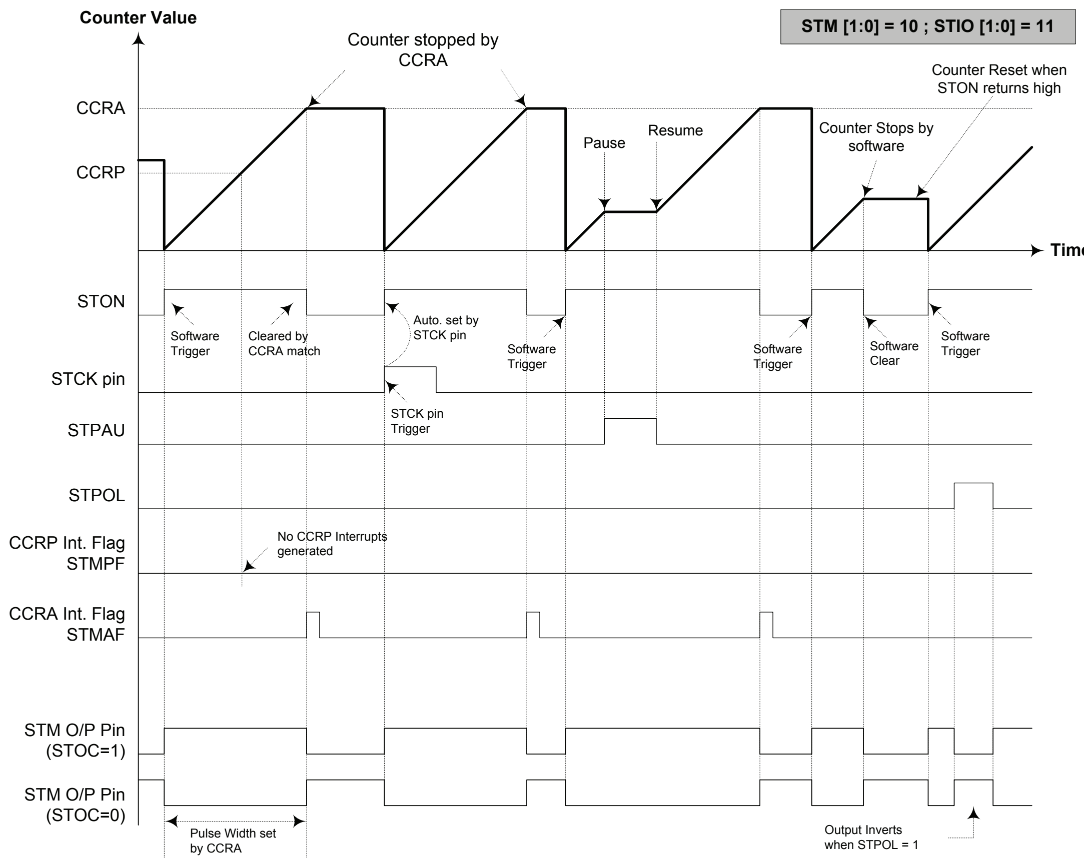
To select this mode, bits STM1 and STM0 in the STMC1 register should be set to 10 respectively and also the STIO1 and STIO0 bits should be set to 11 respectively. The Single Pulse Output Mode, as the name suggests, will generate a single shot pulse on the STM output pin.

The trigger for the pulse output leading edge is a low to high transition of the STON bit, which can be implemented using the application program. However in the Single Pulse Output Mode, the STON bit can also be made to automatically change from low to high using the external STCK pin, which will in turn initiate the Single Pulse output. When the STON bit transitions to a high level, the counter will start running and the pulse leading edge will be generated. The STON bit should remain high when the pulse is in its active state. The generated pulse trailing edge will be generated when the STON bit is cleared to zero, which can be implemented using the application program or when a compare match occurs from Comparator A.

However a compare match from Comparator A will also automatically clear the STON bit and thus generate the Single Pulse output trailing edge. In this way the CCRA value can be used to control the pulse width. A compare match from Comparator A will also generate a STM interrupt. The counter can only be reset back to zero when the STON bit changes from low to high when the counter restarts. In the Single Pulse Output Mode CCRP is not used. The STCCLR and STDPX bits are not used in this Mode.



Single Pulse Generation



Single Pulse Output Mode

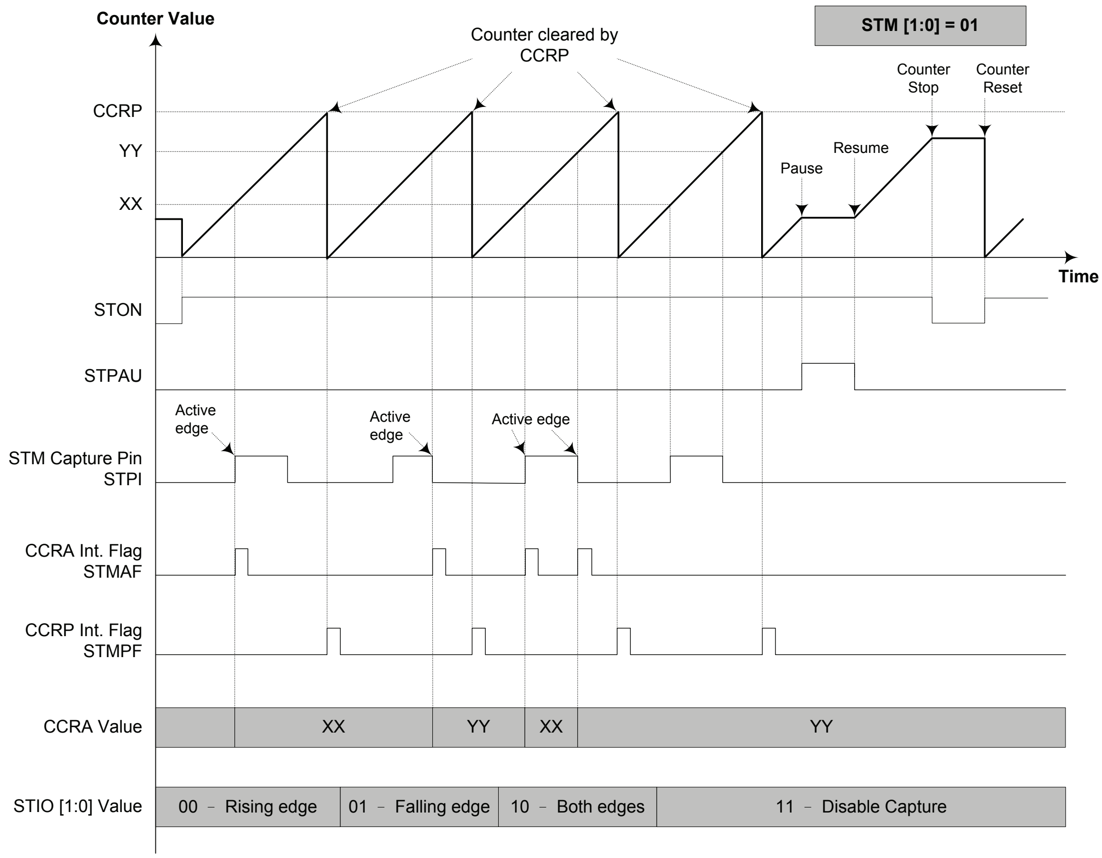
Note: 1. Counter stopped by CCRA
2. CCRP is not used
3. The pulse triggered by the STCK pin or by setting the STON bit high
4. A STCK pin active edge will automatically set the STON bit high.
5. In the Single Pulse Output Mode, STIO[1:0] must be set to "11" and cannot be changed.

Capture Input Mode

To select this mode bits STM1 and STM0 in the STMC1 register should be set to 01 respectively. This mode enables external signals to capture and store the present value of the internal counter and can therefore be used for applications such as pulse width measurements. The external signal is supplied on the STPI pin, whose active edge can be a rising edge, a falling edge or both rising and falling edges; the active edge transition type is selected using the STIO1 and STIO0 bits in the STMC1 register. The counter is started when the STON bit changes from low to high which is initiated using the application program.

When the required edge transition appears on the STPI pin the present value in the counter will be latched into the CCRA registers and a STM interrupt generated. Irrespective of what events occur on the STPI pin the counter will continue to free run until the STON bit changes from high to low. When a CCRP compare match occurs the counter will reset back to zero; in this way the CCRP value can be used to control the maximum counter value. When a CCRP compare match occurs from Comparator P, a STM interrupt will also be generated. Counting the number of overflow interrupt signals from the CCRP can be a useful method in measuring long pulse widths. The STIO1 and STIO0 bits can select the active trigger edge on the STPI pin to be a rising edge, falling edge or both edge types. If the STIO1 and STIO0 bits are both set high, then no capture operation will take place irrespective of what happens on the STPI pin, however it must be noted that the counter will continue to run. The STCCLR and STDPX bits are not used in this Mode.

Note that the STM can also capture the internal RF digital data output signal in the same way as the STPI pin.

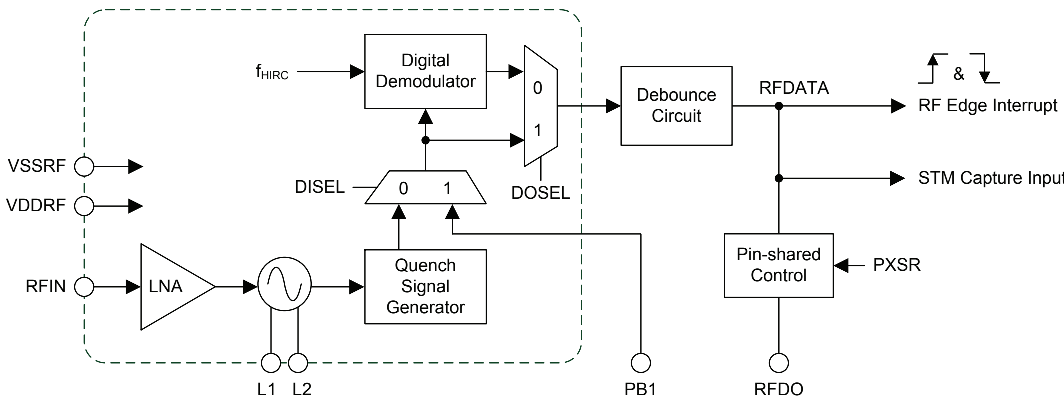


Capture Input Mode

Note: 1. STM[1:0] = 01 and active edge set by the STIO[1:0] bits
2. A STM Capture input pin active edge transfers the counter value to CCRA
3. STCCLR bit not used
4. No output function -- STOC and STPOL bits are not used
5. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero.

RF Receiver

The device contains a fully integrated RF receiver, which is capable of using On-Off Keying (OOK) demodulation for data streaming. It is in effect a genuine RF antenna-in to digital data-out fully integrated device. As all the RF and IF circuitry are integrated within the device this results in a huge reduction in the required number of external components. Having such a high degree of functional integration greatly reduces both product and manufacturing costs and provides higher reliability. The simple connection of an antenna, and some tuned LC circuits together with several software configurations allows the device to detect RF at its resonant frequency. Then by using an internal low noise amplifier and super-regenerative techniques, the demodulator can generate data on the digital data output pin. An antenna matching circuit is supplied on the RFIN pin and an LC tank circuit is connected to the L1 and L2 pins to generate the local oscillator frequency. A fully internal high frequency oscillator in the device is used to demodulate the data from the intermediate frequency signal, thus eliminating the need for any further filtering components. The addition of a decoupling capacitor on each of the power pins is then all that is required to complete the circuit.



RF Receiver Block Diagram

RF Receiver Control Registers

The RF receiver is controlled by several registers. These registers control the overall RF function, such as RF power down control, quench frequency selection, RF data out source selection, and de-bounce stage selection, etc.

Register Name	Bit							
	7	6	5	4	3	2	1	0
RFC0	—	LTMV_fast_sel	DOSR1	DOSR0	DEMOD_RST	S1	S0	PDRF
RFC1*	D7	D6	D5	D4	D3	D2	D1	D0
RFC2*	D7	D6	D5	D4	D3	D2	D1	D0
RFC3*	D7	D6	D5	D4	D3	D2	D1	D0
RFC4*	D7	D6	D5	D4	D3	D2	D1	D0
RFC5*	D7	D6	D5	D4	D3	D2	D1	D0
RFC6	PUL_RST_SEL1	PUL_RST_SEL0	EXT_PUL_RST	RST_THD_SEL1	RST_THD_SEL0	DISEL	DOSEL	CKOFF
RFC7*	D7	D6	D5	D4	D3	D2	D1	D0
RFDEBC	RFDATA	—	—	—	—	DSTAG2	DSTAG1	DSTAG0

Note: These registers are used for RF performance optimization. Refer to the corresponding application note for details.

RF Receiver Control Registers List

RFC0 Register

Bit	7	6	5	4	3	2	1	0
Name	—	LTMV_fast_sel	DOSR1	DOSR0	DEMOD_RST	S1	S0	PDRF
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	1	0	1	0	1	1

Bit 7 Unimplemented, read as "0"

Bit 6 **LTMV_fast_sel**: LTMV fast attack threshold selection
0: 4 × LTMV_offset
1: 2 × LTMV_offset
It is recommended to keep this bit at its default value.

Bit 5~4 **DOSR1~DOSR0**: Sampling rate for digital demodulation
00: 1MHz
01: 500kHz
10: 250kHz
11: 125kHz

Bit 3 **DEMOD_RST**: Digital demodulator software reset
0: Non Soft Reset RF Digit Stage
1: Soft Reset RF Digit Part

Bit 2~1 **S1~S1**: Quench frequency Decimator
00: 1/4
01: 1/8
10: 1/16
11: 1/32

Bit 0 **PDRF**: OOK RF Power down control
0: RF Part power on
1: RF Part power off
Note: No matter what condition occurs, whether MCU reset or DEMOD_RST=1 or PDRF=1, the demodulator will be reset and demod_out will also be forced to zero.

RFC0 Register Setting Description

Different setting values should be written into this register according to different Quench 0 frequency ranges and different data rates. The recommended setting values are summarised in the following table.

- **170kHz ≤ Quench 0 ≤ 570kHz.**

Data Rate – DR (Hz)	DOSR1~DOSR0 Setting Frequency (Hz)	S1~S0 Setting Quench Frequency Division	RFC0 Register Setting
300 ≤ DR < 700	125k	1/32	0x36
700 ≤ DR ≤ 3k	125k	1/16	0x34
3k < DR < 8k	250k	1/8	0x22
8k ≤ DR ≤ 10k	500k	1/4	0x10

- **If Quench 0 > 570kHz, the frequency division should be divided by 2.**

Data Rate – DR (Hz)	DOSR1, DOSR0 Setting Frequency (Hz)	S1, S0 Setting Quench Frequency Division	RFC0 Register Setting
300 ≤ DR ≤ 3k	125k	1/32	0x36
3k < DR < 8k	250k	1/16	0x24
8k ≤ DR ≤ 10k	500k	1/8	0x12

RFC6 Register

Bit	7	6	5	4	3	2	1	0
Name	PUL_RST_SEL1	PUL_RST_SEL0	EXT_PUL_RST	RST_THD_SEL1	RST_THD_SEL0	DISEL	DOSEL	CKOFF
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	1	0	0	0	1	0	0	0

Bit 7~6 **PUL_RST_SEL[1:0]**: Pulse reset selection
00: MCU uses software trigger path to control pulse reset
01: Pulse reset per 2 seconds
10: Pulse reset per 4 seconds
11: Pulse reset per 8 seconds

Bit 5 **EXT_PUL_RST**: Software trigger pulse reset control
0: Disable
1: Enable
When the PUL_RST_SEL[1:0] bits are set to 00B, this bit can be used to manually enable or disable the pulse reset function.

Bit 4~3 **RST_THD_SEL[1:0]**: Initial reset threshold selection
00: 32 sampling clocks
01: 48 sampling clocks
10: 64 sampling clocks
11: 90 sampling clocks
The sampling rate is determined by the DOSR1~DOSR0 bits in the RFC0 register. It is recommended to keep these bits at their default values.

Bit 2 **DISEL**: RF Quench signal selection
0: Internal RF Quench signal – Normal Mode
1: External Quench digit signal on the PB1 pin

Bit 1 **DOSEL**: RF data out source selection
0: Output demodulation data
1: Output Quench data

Bit 0 **CKOFF**: RF clock source (f_{HIRC}) control
0: On
1: Off

RFDEBC Register

Bit	7	6	5	4	3	2	1	0
Name	RFDATA	—	—	—	—	DSTAG2	DSTAG1	DSTAG0
R/W	R	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	1

Bit 7 **RFDATA**: RF Decimator data after debounce circuit indicator

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **DSTAG2~DSTAG0**: De-bounce stage selection
000 & 11x : No debounce
001: 1 clock period of f_{LIRC} = 0~1 LIRC clock (Typ. 31.25μs/2)
010: 2 clock period of f_{LIRC} = 1~2 LIRC clock (Typ. 62.5μs-15.6μs)
011: 4 clock period of f_{LIRC} = 3~4 LIRC clock (Typ. 125μs-15.6μs)
100: 8 clock period of f_{LIRC} = 7~8 LIRC Clock (Typ. 250μs-15.6μs)
101: 16 clock period of f_{LIRC} = 15~16 LIRC Clock (Typ. 500μs-15.6μs)

Interrupts

Interrupts are an important part of any microcontroller system. When an external event or an internal function such as a Timer Module requires microcontroller attention, their corresponding interrupt will enforce a temporary suspension of the main program allowing the microcontroller to direct attention to their respective needs. The device contains several external interrupt and internal interrupt functions. The external interrupts are generated by the action of the external INT0~INT1 pins, while the internal interrupts are generated by various internal functions such as the TMs, LVD and Time base, etc.

Interrupt Registers

Overall interrupt control, which basically means the setting of request flags when certain microcontroller conditions occur and the setting of interrupt enable bits by the application program, is controlled by a series of registers, located in the Special Purpose Data Memory, as shown in the accompanying table. The number of registers falls into three categories. The first is the INTC0~INTC1 registers which setup the primary interrupts, the second is the MFI0~MFI2 registers which setup the Multi-function interrupts. Finally there is an INTEG register to setup the external interrupt trigger edge type.

Each register contains a number of enable bits to enable or disable individual registers as well as interrupt flags to indicate the presence of an interrupt request. The naming convention of these follows a specific pattern. First is listed an abbreviated interrupt type, then the (optional) number of that interrupt followed by either an "E" for enable/disable bit or "F" for request flag.

Function	Enable Bit	Request Flag	Notes
Global	EMI	—	—
INTn Pin	INTnE	INTnF	n=0 or 1
Time Base	TBnE	TBnF	n=0 or 1
Multi-function	MFnE	MFnF	n=0~2
LVD	LVE	LVF	—
EEPROM	DEE	DEF	—
RF Edge	RFINTE	RFINTF	—
CTM	CTMPE	CTMPF	—
	CTMAE	CTMAF	
STM	STMPE	STMPF	—
	STMAE	STMAF	

Interrupt Register Bit Naming Conventions

Register Name	Bit							
	7	6	5	4	3	2	1	0
INTEG	—	—	—	—	INT1S1	INT1S0	INT0S1	INT0S0
INTC0	—	TB0F	INT1F	INT0F	TB0E	INT1E	INT0E	EMI
INTC1	MF2F	MF1F	MF0F	TB1F	MF2E	MF1E	MF0E	TB1E
MFI0	—	—	STMAF	STMPF	—	—	STMAE	STMPE
MFI1	—	—	CTMAF	CTMPF	—	—	CTMAE	CTMPE
MFI2	—	RFINTF	DEF	LVF	—	RFINTE	DEE	LVE

Interrupt Registers List

INTEG Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	INT1S1	INT1S0	INT0S1	INT0S0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3~2 **INT1S1~INT1S0**: External Interrupt edge control for INT1 pin
00: Disable
01: Rising edge
10: Falling edge
11: Rising and falling edges

Bit 1~0 **INT0S1~INT0S0**: External Interrupt edge control for INT0 pin
00: Disable
01: Rising edge
10: Falling edge
11: Rising and falling edges

INTC0 Register

Bit	7	6	5	4	3	2	1	0
Name	—	TB0F	INT1F	INT0F	TB0E	INT1E	INT0E	EMI
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as «0"

Bit 6 **TB0F**: Time Base 0 interrupt request flag
0: No request
1: Interrupt request

Bit 5 **INT1F**: INT1 interrupt request flag
0: No request
1: Interrupt request

Bit 4 **INT0F**: INT0 interrupt request flag
0: No request
1: Interrupt request

Bit 3 **TB0E**: Time Base 0 interrupt control
0: Disable
1: Enable

Bit 2 **INT1E**: INT1 interrupt control
0: Disable
1: Enable

Bit 1 **INT0E**: INT0 interrupt control
0: Disable
1: Enable

Bit 0 **EMI**: Global interrupt control
0: Disable
1: Enable

INTC1 Register

Bit	7	6	5	4	3	2	1	0
Name	MF2F	MF1F	MF0F	TB1F	MF2E	MF1E	MF0E	TB1E
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **MF2F**: Multi-function interrupt 2 request flag
0: No request
1: Interrupt request

Bit 6 **MF1F**: Multi-function interrupt 1 request flag
0: No request
1: Interrupt request

Bit 5 **MF0F**: Multi-function interrupt 0 request flag
0: No request
1: Interrupt request

Bit 4 **TB1F**: Time Base 1 interrupt request flag
0: No request
1: Interrupt request

Bit 3 **MF2E**: Multi-function interrupt 2 control
0: Disable
1: Enable

Bit 2 **MF1E**: Multi-function interrupt 1 control
0: Disable
1: Enable

Bit 1 **MF0E**: Multi-function interrupt 0 control
0: Disable
1: Enable

Bit 0 **TB1E**: Time Base 1 interrupt control
0: Disable
1: Enable

MFI0 Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	STMAF	STMPF	—	—	STMAE	STMPE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5 **STMAF**: STM Comparator A match interrupt request flag
0: No request
1: Interrupt request

Bit 4 **STMPF**: STM Comparator P match interrupt request flag
0: No request
1: Interrupt request

Bit 3~2 Unimplemented, read as "0"

Bit 1 **STMAE**: STM Comparator A match interrupt control
0: Disable
1: Enable

Bit 0 **STMPE**: STM Comparator P match interrupt control
0: Disable
1: Enable

MFI1 Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	CTMAF	CTMPF	—	—	CTMAE	CTMPE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5 **CTMAF**: CTM Comparator A match interrupt request flag
0: No request
1: Interrupt request

Bit 4 **CTMPF**: CTM Comparator P match interrupt request flag
0: No request
1: Interrupt request

Bit 3~2 Unimplemented, read as "0"

Bit 1 **CTMAE**: CTM Comparator A match interrupt control
0: Disable
1: Enable

Bit 0 **CTMPE**: CTM Comparator P match interrupt control
0: Disable
1: Enable

MFI2 Register

Bit	7	6	5	4	3	2	1	0
Name	—	RFINTF	DEF	LVF	—	RFINTE	DEE	LVE
R/W	—	R/W	R/W	R/W	—	R/W	R/W	R/W
POR	—	0	0	0	—	0	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **RFINTF**: RF data rising & falling edge interrupt request flag
0: No request
1: Interrupt request

Bit 5 **DEF**: Data EEPROM interrupt request flag
0: No request
1: Interrupt request

Bit 4 **LVF**: LVD interrupt request flag
0: No request
1: Interrupt request

Bit 3 Unimplemented, read as "0"

Bit 2 **RFINTE**: RF data rising & falling edge interrupt control
0: Disable
1: Enable

Bit 1 **DEE**: Data EEPROM interrupt control
0: Disable
1: Enable

Bit 0 **LVE**: LVD interrupt control
0: Disable
1: Enable

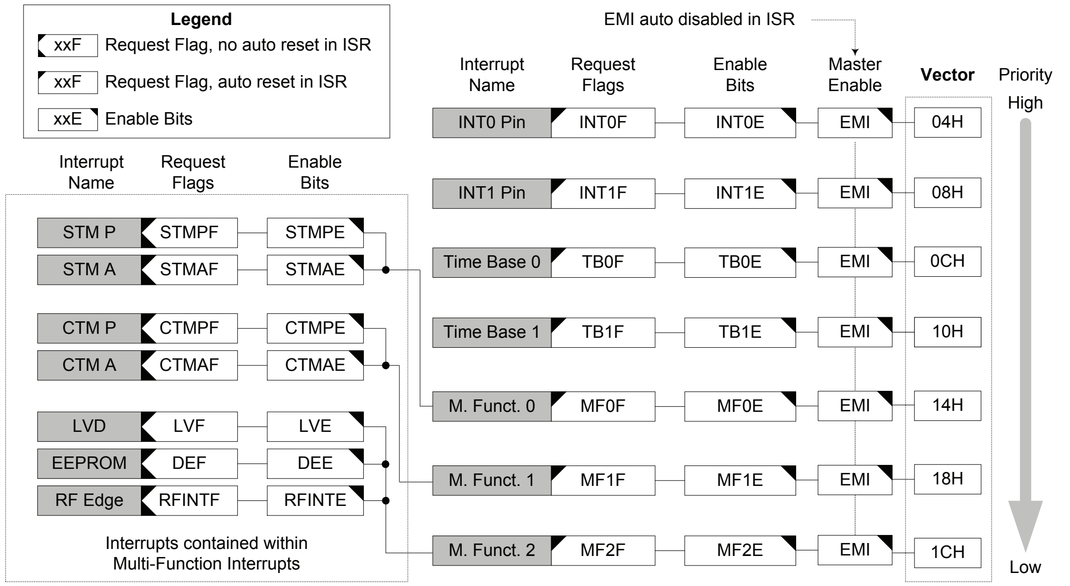
Interrupt Operation

When the conditions for an interrupt event occur, such as a TM Comparator P or Comparator A match etc., the relevant interrupt request flag will be set. Whether the request flag actually generates a program jump to the relevant interrupt vector is determined by the condition of the interrupt enable bit. If the enable bit is set high then the program will jump to its relevant vector; if the enable bit is zero then although the interrupt request flag is set an actual interrupt will not be generated and the program will not jump to the relevant interrupt vector. The global interrupt enable bit, if cleared to zero, will disable all interrupts.

When an interrupt is generated, the Program Counter, which stores the address of the next instruction to be executed, will be transferred onto the stack. The Program Counter will then be loaded with a new address which will be the value of the corresponding interrupt vector. The microcontroller will then fetch its next instruction from this interrupt vector. The instruction at this vector will usually be a "JMP" which will jump to another section of program which is known as the interrupt service routine. Here is located the code to control the appropriate interrupt. The interrupt service routine must be terminated with a "RETI", which retrieves the original Program Counter address from the stack and allows the microcontroller to continue with normal execution at the point where the interrupt occurred.

The various interrupt enable bits, together with their associated request flags, are shown in the accompanying diagrams with their order of priority. Some interrupt sources have their own individual vector while others share the same multi-function interrupt vector. Once an interrupt subroutine is serviced, all the other interrupts will be blocked, as the global interrupt enable bit, EMI bit will be cleared automatically. This will prevent any further interrupt nesting from occurring. However, if other interrupt requests occur during this interval, although the interrupt will not be immediately serviced, the request flag will still be recorded.

If an interrupt requires immediate servicing while the program is already in another interrupt service routine, the EMI bit should be set after entering the routine, to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the Stack Pointer is decremented. If immediate service is desired, the stack must be prevented from becoming full. In case of simultaneous requests, the accompanying diagram shows the priority that is applied. All of the interrupt request flags when set will wake-up the device if it is in SLEEP or IDLE Mode, however to prevent a wake-up from occurring the corresponding flag should be set before the device is in SLEEP or IDLE Mode.



Interrupt Structure

External Interrupts

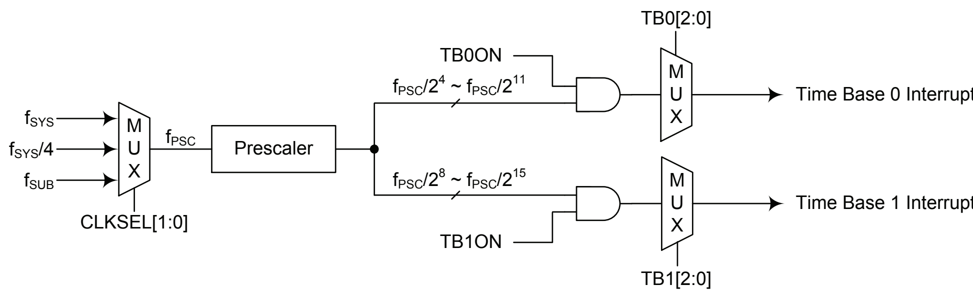
The external interrupts are controlled by signal transitions on the pins INT0~INT1. An external interrupt request will take place when the external interrupt request flags, INT0F~INT1F, are set, which will occur when a transition, whose type is chosen by the edge select bits, appears on the external interrupt pins. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective external interrupt enable bit, INT0E~INT1E, must first be set. Additionally the correct interrupt edge type must be selected using the INTEG register to enable the external interrupt function and to choose the trigger edge type. As the external interrupt pins are pin-shared with I/O pins, they can only be configured as external interrupt pins if their external interrupt enable bit in the corresponding interrupt register has been set. The pin must also be setup as an input by setting the corresponding bit in the port control register. When the interrupt is enabled, the stack is not full and the correct transition type appears on the external interrupt pin, a subroutine call to the external interrupt vector, will take place. When the interrupt is serviced, the external interrupt request flags, INT0F~INT1F, will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts. Note that any pull-high resistor selections on the external interrupt pins will remain valid even if the pin is used as an external interrupt input.

The INTEG register is used to select the type of active edge that will trigger the external interrupt. A choice of either rising or falling or both edge types can be chosen to trigger an external interrupt. Note that the INTEG register can also be used to disable the external interrupt function.

Time Base Interrupts

The function of the Time Base Interrupts is to provide regular time signal in the form of an internal interrupt. They are controlled by the overflow signals from their respective timer functions. When these happens their respective interrupt request flags, TB0F or TB1F will be set. To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI and Time Base enable bits, TB0E or TB1E, must first be set. When the interrupt is enabled, the stack is not full and the Time Base overflows, a subroutine call to their respective vector locations will take place. When the interrupt is serviced, the respective interrupt request flag, TB0F or TB1F, will be automatically reset and the EMI bit will be cleared to disable other interrupts.

The purpose of the Time Base Interrupt is to provide an interrupt signal at fixed time periods. Its clock source, f_{PSC}, originates from the internal clock source f_{SYS}, $f_{SYS}/4$ or f_{SUB} and then passes through a divider, the division ratio of which is selected by programming the appropriate bits in the TB0C and TB1C registers to obtain longer interrupt periods whose value ranges. The clock source which in turn controls the Time Base interrupt period is selected using the CLKSEL1~CLKSEL0 bits in the PSCR register.



Time Base Interrupts

PSCR Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	CLKSEL1	CLKSEL0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **CLKSEL1~CLKSEL0**: Prescaler clock source f_{PSC} selection
00: f_{SYS}
01: $f_{SYS}/4$
1x: f_{SUB}

TB0C Register

Bit	7	6	5	4	3	2	1	0
Name	TB0ON	—	—	—	—	TB02	TB01	TB00
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB0ON**: Time Base 0 Control
0: Disable
1: Enable

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **TB02~TB00**: Select Time Base 0 Time-out Period
000: $2^4/f_{PSC}$
001: $2^5/f_{PSC}$
010: $2^6/f_{PSC}$
011: $2^7/f_{PSC}$
100: $2^8/f_{PSC}$
101: $2^9/f_{PSC}$
110: $2^{10}/f_{PSC}$
111: $2^{11}/f_{PSC}$

TB1C Register

Bit	7	6	5	4	3	2	1	0
Name	TB1ON	—	—	—	—	TB12	TB11	TB10
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB1ON**: Time Base 1 Control
0: Disable
1: Enable

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **TB12~TB10**: Select Time Base 1 Time-out Period
000: $2^8/f_{PSC}$
001: $2^9/f_{PSC}$
010: $2^{10}/f_{PSC}$
011: $2^{11}/f_{PSC}$
100: $2^{12}/f_{PSC}$
101: $2^{13}/f_{PSC}$
110: $2^{14}/f_{PSC}$
111: $2^{15}/f_{PSC}$

Multi-function Interrupts

Within the devices there are up to three Multi-function interrupts. Unlike the other independent interrupts, these interrupts have no independent source, but rather are formed from other existing interrupt sources, namely the TM Interrupts, LVD Interrupt, EEPROM Interrupt and RF edge Interrupt.

A Multi-function interrupt request will take place when any of the Multi-function interrupt request flags, MFnF are set. The Multi-function interrupt flags will be set when any of their included functions generate an interrupt request flag. To allow the program to branch to its respective interrupt vector address, when the Multi-function interrupt is enabled and the stack is not full, and either one of the interrupts contained within each of Multi-function interrupt occurs, a subroutine call to one of the Multi-function interrupt vectors will take place. When the interrupt is serviced, the related Multi-function request flag will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts.

However, it must be noted that, although the Multi-function Interrupt flags will be automatically reset when the interrupt is serviced, the request flags from the original source of the Multi-function interrupts will not be automatically reset and must be manually reset by the application program.

RF Edge Interrupt

The RF Edge interrupt is contained within the Multi-function Interrupt. A RF Edge Interrupt request will take place when its interrupt request flag, RFINTF, is set, which occurs when the RF digital demodulator output data appears both rising and falling edges. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and RF Edge Interrupt enable bit, RFINTE, and associated Multi-function interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and the previously mentioned condition occurs, a subroutine call to the respective interrupt vector will take place. When the interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the Multi-function interrupt request flag will be also automatically cleared. As the RFINTF flag will not be automatically cleared, it has to be cleared by the application program.

LVD Interrupt

The Low Voltage Detector Interrupt is contained within the Multi-function Interrupt. An LVD Interrupt request will take place when the LVD Interrupt request flag, LVF, is set, which occurs when the Low Voltage Detector function detects a low power supply voltage. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, Low Voltage Interrupt enable bit, LVE, and associated Multi-function interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and a low voltage condition occurs, a subroutine call to the Multi-function Interrupt vector, will take place. When the Low Voltage Interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the Multi-function interrupt request flag will be also automatically cleared. As the LVF flag will not be automatically cleared, it has to be cleared by the application program.

EEPROM Interrupt

The EEPROM interrupt is contained within the Multi-function Interrupt. An EEPROM Interrupt request will take place when the EEPROM Interrupt request flag, DEF, is set, which occurs when an EEPROM Write cycle ends. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and EEPROM Interrupt enable bit, DEE, and associated Multi-function interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and an EEPROM Write cycle ends, a subroutine call to the respective EEPROM Interrupt vector will take place. When the EEPROM Interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the Multi-function interrupt request flag will be also automatically cleared. As the DEF flag will not be automatically cleared, it has to be cleared by the application program.

TM Interrupts

The Compact and Standard Type TMs each have two interrupts, one comes from the comparator A match situation and the other comes from the comparator P match situation. All of the TM interrupts are contained within the Multi-function Interrupts. For all of the TM types there are two interrupt request flags and two enable control bits. A TM interrupt request will take place when any of the TM request flags are set, a situation which occurs when a TM comparator P or A match situation happens.

To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, respective TM Interrupt enable bit, and relevant Multi-function Interrupt enable bit, MFnE, must first be set. When the interrupt is enabled, the stack is not full and a TM comparator match situation occurs, a subroutine call to the relevant Multi-function Interrupt vector locations, will take place. When the TM interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the related MFnF flag will be automatically cleared. As the TM interrupt request flags will not be automatically cleared, they have to be cleared by the application program.

Interrupt Wake-up Function

Each of the interrupt functions has the capability of waking up the microcontroller when in the SLEEP or IDLE Mode. A wake-up is generated when an interrupt request flag changes from low to high and is independent of whether the interrupt is enabled or not. Therefore, even though the device is in the SLEEP or IDLE Mode and its system oscillator stopped, situations such as external edge transitions on the external interrupt pins or a low power supply voltage may cause their respective interrupt flag to be set high and consequently generate an interrupt. Care must therefore be taken if spurious wake-up situations are to be avoided. If an interrupt wake-up function is to be disabled then the corresponding interrupt request flag should be set high before the device enters the SLEEP or IDLE Mode. The interrupt enable bits have no effect on the interrupt wake-up function.

Programming Considerations

By disabling the relevant interrupt enable bits, a requested interrupt can be prevented from being serviced, however, once an interrupt request flag is set, it will remain in this condition in the interrupt register until the corresponding interrupt is serviced or until the request flag is cleared by the application program.

Where a certain interrupt is contained within a Multi-function interrupt, then when the interrupt service routine is executed, as only the Multi-function interrupt request flags, MFnF, will be automatically cleared, the individual request flag for the function needs to be cleared by the application program.

It is recommended that programs do not use the "CALL" instruction within the interrupt service subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately. If only one stack is left and the interrupt is not well controlled, the original control sequence will be damaged once a CALL subroutine is executed in the interrupt subroutine.

Every interrupt has the capability of waking up the microcontroller when it is in the SLEEP or IDLE Mode, the wake up being generated when the interrupt request flag changes from low to high. If it is required to prevent a certain interrupt from waking up the microcontroller then its respective request flag should be first set high before enter SLEEP or IDLE Mode.

As only the Program Counter is pushed onto the stack, then when the interrupt is serviced, if the contents of the accumulator, status register or other registers are altered by the interrupt service program, their contents should be saved to the memory at the beginning of the interrupt service routine.

To return from an interrupt subroutine, either a RET or RETI instruction may be executed. The RETI instruction in addition to executing a return to the main program also automatically sets the EMI bit high to allow further interrupts. The RET instruction however only executes a return to the main program leaving the EMI bit in its present zero state and therefore disabling the execution of further interrupts.

Low Voltage Detector – LVD

The device has a Low Voltage Detector function, also known as LVD. This enabled the device to monitor the power supply voltage, V_{DD}, and provide a warning signal should it fall below a certain level. This function may be especially useful in battery applications where the supply voltage will gradually reduce as the battery ages, as it allows an early warning battery low signal to be generated. The Low Voltage Detector also has the capability of generating an interrupt signal.

LVD Register

The Low Voltage Detector function is controlled using a single register with the name LVDC. Three bits in this register, VLVD2~VLVD0, are used to select one of eight fixed voltages below which a low voltage condition will be determined. A low voltage condition is indicated when the LVDO bit is set. If the LVDO bit is low, this indicates that the V_{DD} voltage is above the preset low voltage value. The LVDEN bit is used to control the overall on/off function of the low voltage detector. Setting the bit high will enable the low voltage detector. Clearing the bit to zero will switch off the internal low voltage detector circuits. As the low voltage detector will consume a certain amount of power, it may be desirable to switch off the circuit when not in use, an important consideration in power sensitive battery powered applications.

LVDC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	LVDO	LVDEN	VBGEN	VLVD2	VLVD1	VLVD0
R/W	—	—	R	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5 **LVDO**: LVD Output Flag
0: No Low Voltage Detect
1: Low Voltage Detect

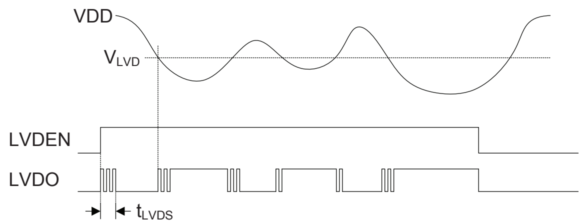
Bit 4 **LVDEN**: Low Voltage Detector Control
0: Disable
1: Enable

Bit 3 **VBGEN**: Bandgap Buffer Control
0: Disable
1: Enable
Note that the Bandgap circuit is enabled when the LVD or LVR function is enabled or when the VBGEN bit is set to 1.

Bit 2~0 **VLVD2~VLVD0**: Select LVD Voltage
000: 2.0V
001: 2.2V
010: 2.4V
011: 2.7V
100: 3.0V
101: 3.3V
110: 3.6V
111: 4.0V

LVD Operation

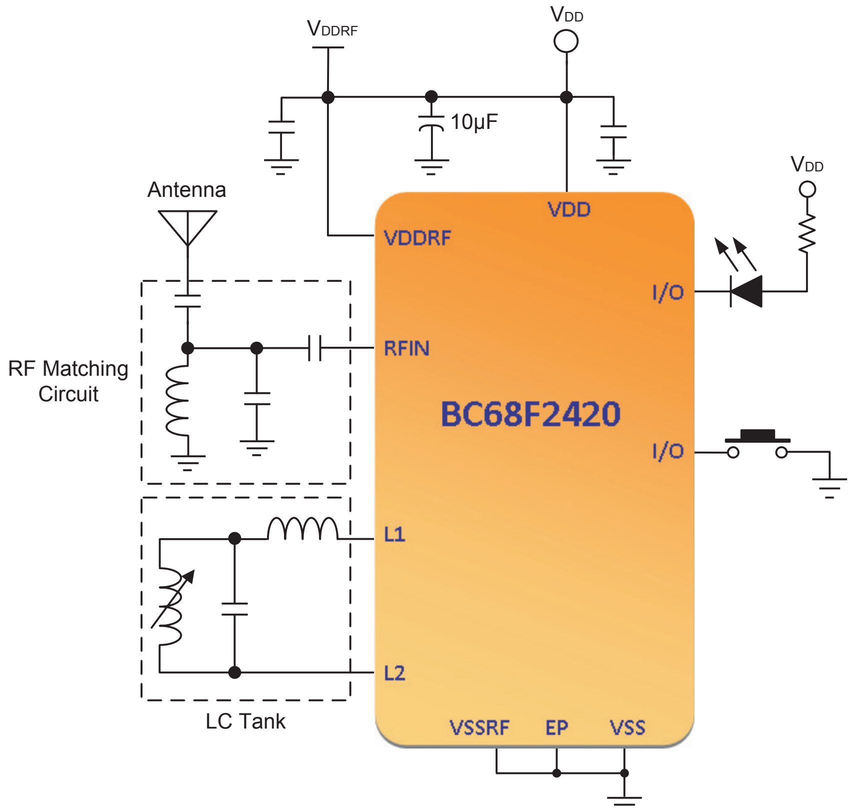
The Low Voltage Detector function operates by comparing the power supply voltage, V_{DD}, with a pre-specified voltage level stored in the LVDC register. This has a range of between 2.0V and 4.0V. When the power supply voltage, V_{DD}, falls below this pre-determined value, the LVDO bit will be set high indicating a low power supply voltage condition. The Low Voltage Detector function is supplied by a reference voltage which will be automatically enabled. When the device is in the SLEEP mode, the low voltage detector will be disabled even if the LVDEN bit is high. After enabling the Low Voltage Detector, a time delay t_{LVDS} should be allowed for the circuitry to stabilise before reading the LVDO bit. Note also that as the V_{DD} voltage may rise and fall rather slowly, at the voltage nears that of V_{LVD}, there may be multiple bit LVDO transitions.



LVD Operation

The Low Voltage Detector also has its own interrupt which is contained within one of the Multi-function interrupts, providing an alternative means of low voltage detection, in addition to polling the LVDO bit. The interrupt will only be generated after a delay of t_{LVD} after the LVDO bit has been set high by a low voltage condition. When the device is powered down the Low Voltage Detector will remain active if the LVDEN bit is high. In this case, the LVF interrupt request flag will be set, causing an interrupt to be generated if V_{DD} falls below the preset LVD voltage. This will cause the device to wake-up from the IDLE Mode, however if the Low Voltage Detector wake up function is not required then the LVF flag should be first set high before the device enters the IDLE Mode.

Application Circuits



Instruction Set

Introduction

Central to the successful operation of any microcontroller is its instruction set, which is a set of program instruction codes that directs the microcontroller to perform certain operations. In the case of Holtek microcontroller, a comprehensive and flexible set of over 60 instructions is provided to enable programmers to implement their application with the minimum of programming overheads.

For easier understanding of the various instruction codes, they have been subdivided into several functional groupings.

Instruction Timing

Most instructions are implemented within one instruction cycle. The exceptions to this are branch, call, or table read instructions where two instruction cycles are required. One instruction cycle is equal to 4 system clock cycles, therefore in the case of an 8MHz system oscillator, most instructions would be implemented within 0.5µs and branch or call instructions would be implemented within 1µs. Although instructions which require one more cycle to implement are generally limited to the JMP, CALL, RET, RETI and table read instructions, it is important to realize that any other instructions which involve manipulation of the Program Counter Low register or PCL will also take one more cycle to implement. As instructions which change the contents of the PCL will imply a direct jump to that new address, one more cycle will be required. Examples of such instructions would be "CLR PCL" or "MOV PCL, A". For the case of skip instructions, it must be noted that if the result of the comparison involves a skip operation then this will also take one more cycle, if no skip is involved then only one cycle is required.

Moving and Transferring Data

The transfer of data within the microcontroller program is one of the most frequently used operations. Making use of three kinds of MOV instructions, data can be transferred from registers to the Accumulator and vice-versa as well as being able to move specific immediate data directly into the Accumulator. One of the most important data transfer applications is to receive data from the input ports and transfer data to the output ports.

Arithmetic Operations

The ability to perform certain arithmetic operations and data manipulation is a necessary feature of most microcontroller applications. Within the Holtek microcontroller instruction set are a range of add and subtract instruction mnemonics to enable the necessary arithmetic to be carried out. Care must be taken to ensure correct handling of carry and borrow data when results exceed 255 for addition and less than 0 for subtraction. The increment and decrement instructions INC, INCA, DEC and DECA provide a simple means of increasing or decreasing by a value of one of the values in the destination specified.

Logical and Rotate Operation

The standard logical operations such as AND, OR, XOR and CPL all have their own instruction within the Holtek microcontroller instruction set. As with the case of most instructions involving data manipulation, data must pass through the Accumulator which may involve additional programming steps. In all logical data operations, the zero flag may be set if the result of the operation is zero. Another form of logical data manipulation comes from the rotate instructions such as RR, RL, RRC and RLC which provide a simple means of rotating one bit right or left. Different rotate instructions exist depending on program requirements. Rotate instructions are useful for serial port programming applications where data can be rotated from an internal register into the Carry bit from where it can be examined and the necessary serial bit set high or low. Another application which rotate data operations are used is to implement multiplication and division calculations.

Branches and Control Transfer

Program branching takes the form of either jumps to specified locations using the JMP instruction or to a subroutine using the CALL instruction. They differ in the sense that in the case of a subroutine call, the program must return to the instruction immediately when the subroutine has been carried out. This is done by placing a return instruction "RET" in the subroutine which will cause the program to jump back to the address right after the CALL instruction. In the case of a JMP instruction, the program simply jumps to the desired location. There is no requirement to jump back to the original jumping off point as in the case of the CALL instruction. One special and extremely useful set of branch instructions are the conditional branches. Here a decision is first made regarding the condition of a certain data memory or individual bits. Depending upon the conditions, the program will continue with the next instruction or skip over it and jump to the following instruction. These instructions are the key to decision making and branching within the program perhaps determined by the condition of certain input switches or by the condition of internal data bits.

Bit Operations

The ability to provide single bit operations on Data Memory is an extremely flexible feature of all Holtek microcontrollers. This feature is especially useful for output port bit programming where individual bits or port pins can be directly set high or low using either the "SET [m].i" or "CLR [m].i" instructions respectively. The feature removes the need for programmers to first read the 8-bit output port, manipulate the input data to ensure that other bits are not changed and then output the port with the correct new data. This read-modify-write process is taken care of automatically when these bit operation instructions are used.

Table Read Operations

Data storage is normally implemented by using registers. However, when working with large amounts of fixed data, the volume involved often makes it inconvenient to store the fixed data in the Data Memory. To overcome this problem, Holtek microcontrollers allow an area of Program Memory to be set as a table where data can be directly stored. A set of easy to use instructions provides the means by which this fixed data can be referenced and retrieved from the Program Memory.

Other Operations

In addition to the above functional instructions, a range of other instructions also exist such as the "HALT" instruction for Power-down operations and instructions to control the operation of the Watchdog Timer for reliable program operations under extreme electric or electromagnetic environments. For their relevant operations, refer to the functional related sections.

Instruction Set Summary

The following table depicts a summary of the instruction set categorised according to function and can be consulted as a basic instruction reference using the following listed conventions.

Table Conventions

x: Bits immediate data
m: Data Memory address
A: Accumulator
i: 0~7 number of bits
addr: Program memory address

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
ADD A,[m]	Add Data Memory to ACC	1	Z, C, AC, OV
ADDM A,[m]	Add ACC to Data Memory	1[Note]	Z, C, AC, OV
ADD A,x	Add immediate data to ACC	1	Z, C, AC, OV
ADC A,[m]	Add Data Memory to ACC with Carry	1	Z, C, AC, OV
ADCM A,[m]	Add ACC to Data memory with Carry	1[Note]	Z, C, AC, OV
SUB A,x	Subtract immediate data from the ACC	1	Z, C, AC, OV
SUB A,[m]	Subtract Data Memory from ACC	1	Z, C, AC, OV
SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	1[Note]	Z, C, AC, OV
SBC A,[m]	Subtract Data Memory from ACC with Carry	1	Z, C, AC, OV
SBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	1[Note]	Z, C, AC, OV
DAA [m]	Decimal adjust ACC for Addition with result in Data Memory	1[Note]	C
Logic Operation			
AND A,[m]	Logical AND Data Memory to ACC	1	Z
OR A,[m]	Logical OR Data Memory to ACC	1	Z
XOR A,[m]	Logical XOR Data Memory to ACC	1	Z
ANDM A,[m]	Logical AND ACC to Data Memory	1[Note]	Z
ORM A,[m]	Logical OR ACC to Data Memory	1[Note]	Z
XORM A,[m]	Logical XOR ACC to Data Memory	1[Note]	Z
AND A,x	Logical AND immediate Data to ACC	1	Z
OR A,x	Logical OR immediate Data to ACC	1	Z
XOR A,x	Logical XOR immediate Data to ACC	1	Z
CPL [m]	Complement Data Memory	1[Note]	Z
CPLA [m]	Complement Data Memory with result in ACC	1	Z
Increment & Decrement			
INCA [m]	Increment Data Memory with result in ACC	1	Z
INC [m]	Increment Data Memory	1[Note]	Z
DECA [m]	Decrement Data Memory with result in ACC	1	Z
DEC [m]	Decrement Data Memory	1[Note]	Z
Rotate			
RRA [m]	Rotate Data Memory right with result in ACC	1	None
RR [m]	Rotate Data Memory right	1[Note]	None
RRCA [m]	Rotate Data Memory right through Carry with result in ACC	1	C
RRC [m]	Rotate Data Memory right through Carry	1[Note]	C
RLA [m]	Rotate Data Memory left with result in ACC	1	None
RL [m]	Rotate Data Memory left	1[Note]	None
RLCA [m]	Rotate Data Memory left through Carry with result in ACC	1	C
RLC [m]	Rotate Data Memory left through Carry	1[Note]	C

Mnemonic	Description	Cycles	Flag Affected
Data Move			
MOV A,[m]	Move Data Memory to ACC	1	None
MOV [m],A	Move ACC to Data Memory	1[Note]	None
MOV A,x	Move immediate data to ACC	1	None
Bit Operation			
CLR [m].i	Clear bit of Data Memory	1[Note]	None
SET [m].i	Set bit of Data Memory	1[Note]	None
Branch Operation			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if Data Memory is zero	1[Note]	None
SZA [m]	Skip if Data Memory is zero with data movement to ACC	1[Note]	None
SZ [m].i	Skip if bit i of Data Memory is zero	1[Note]	None
SNZ [m].i	Skip if bit i of Data Memory is not zero	1[Note]	None
SIZ [m]	Skip if increment Data Memory is zero	1[Note]	None
SDZ [m]	Skip if decrement Data Memory is zero	1[Note]	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC	1[Note]	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC	1[Note]	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
Table Read Operation			
TABRD [m]	Read table (specific page) to TBLH and Data Memory	2[Note]	None
TABRDC [m]	Read table (current page) to TBLH and Data Memory	2[Note]	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory	2[Note]	None
Miscellaneous			
NOP	No operation	1	None
CLR [m]	Clear Data Memory	1[Note]	None
SET [m]	Set Data Memory	1[Note]	None
CLR WDT	Clear Watchdog Timer	1	TO, PDF
CLR WDT1	Pre-clear Watchdog Timer	1	TO, PDF
CLR WDT2	Pre-clear Watchdog Timer	1	TO, PDF
SWAP [m]	Swap nibbles of Data Memory	1[Note]	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC	1	None
HALT	Enter power down mode	1	TO, PDF

Note: 1. For skip instructions, if the result of the comparison involves a skip then two cycles are required, if no skip takes place only one cycle is required.

2. Any instruction which changes the contents of the PCL will also require 2 cycles for execution.

3. For the "CLR WDT1" and "CLR WDT2" instructions the TO and PDF flags may be affected by the execution status. The TO and PDF flags are cleared after both "CLR WDT1" and "CLR WDT2" instructions are consecutively executed. Otherwise the TO and PDF flags remain unchanged.

Instruction Definition

ADC A,[m] Add Data Memory to ACC with Carry
Description: The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.
Operation: ACC ← ACC + [m] + C
Affected flag(s): OV, Z, AC, C

ADCM A,[m] Add ACC to Data Memory with Carry
Description: The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.
Operation: [m] ← ACC + [m] + C
Affected flag(s): OV, Z, AC, C

ADD A,[m] Add Data Memory to ACC
Description: The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.
Operation: ACC ← ACC + [m]
Affected flag(s): OV, Z, AC, C

ADD A,x Add immediate data to ACC
Description: The contents of the Accumulator and the specified immediate data are added. The result is stored in the Accumulator.
Operation: ACC ← ACC + x
Affected flag(s): OV, Z, AC, C

ADDM A,[m] Add ACC to Data Memory
Description: The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.
Operation: [m] ← ACC + [m]
Affected flag(s): OV, Z, AC, C

AND A,[m] Logical AND Data Memory to ACC
Description: Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.
Operation: ACC ← ACC ″AND″ [m]
Affected flag(s): Z

AND A,x Logical AND immediate data to ACC
Description: Data in the Accumulator and the specified immediate data perform a bit wise logical AND operation. The result is stored in the Accumulator.
Operation: ACC ← ACC ″AND″ x
Affected flag(s): Z

ANDM A,[m] Logical AND ACC to Data Memory
Description: Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.
Operation: [m] ← ACC ″AND″ [m]
Affected flag(s): Z

CALL addr	Subroutine call
Description	Unconditionally calls a subroutine at the specified address. The Program Counter then increments by 1 to obtain the address of the next instruction which is then pushed onto the stack. The specified address is then loaded and the program continues execution from this new address. As this instruction requires an additional operation, it is a two cycle instruction.
Operation	Stack ← Program Counter + 1 Program Counter ← addr
Affected flag(s)	None

CLR [m]	Clear Data Memory
Description	Each bit of the specified Data Memory is cleared to 0.
Operation	[m] ← 00H
Affected flag(s)	None

CLR [m].i	Clear bit of Data Memory
Description	Bit i of the specified Data Memory is cleared to 0.
Operation	[m].i ← 0
Affected flag(s)	None

CLR WDT	Clear Watchdog Timer
Description	The TO, PDF flags and the WDT are all cleared.
Operation	WDT cleared TO ← 0 PDF ← 0
Affected flag(s)	TO, PDF

CLR WDT1	Pre-clear Watchdog Timer
Description	The TO, PDF flags and the WDT are all cleared. Note that this instruction works in conjunction with CLR WDT2 and must be executed alternately with CLR WDT2 to have effect. Repetitively executing this instruction without alternately executing CLR WDT2 will have no effect.
Operation	WDT cleared TO ← 0 PDF ← 0
Affected flag(s)	TO, PDF

CLR WDT2	Pre-clear Watchdog Timer
Description	The TO, PDF flags and the WDT are all cleared. Note that this instruction works in conjunction with CLR WDT1 and must be executed alternately with CLR WDT1 to have effect. Repetitively executing this instruction without alternately executing CLR WDT1 will have no effect.
Operation	WDT cleared TO ← 0 PDF ← 0
Affected flag(s)	TO, PDF

CPL [m]	Complement Data Memory
Description	Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa.
Operation	[m] ← $\overline{[m]}$
Affected flag(s)	Z

CPLA [m]	Complement Data Memory with result in ACC
Description	Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC ← $\overline{[m]}$
Affected flag(s)	Z

DAA [m]	Decimal-Adjust ACC for addition with result in Data Memory
Description	Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.
Operation	[m] ← ACC + 00H or [m] ← ACC + 06H or [m] ← ACC + 60H or [m] ← ACC + 66H
Affected flag(s)	C

DEC [m]	Decrement Data Memory
Description	Data in the specified Data Memory is decremented by 1.
Operation	[m] ← [m] − 1
Affected flag(s)	Z

DECA [m]	Decrement Data Memory with result in ACC
Description	Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	ACC ← [m] − 1
Affected flag(s)	Z

HALT	Enter power down mode
Description	This instruction stops the program execution and turns off the system clock. The contents of the Data Memory and registers are retained. The WDT and prescaler are cleared. The power down flag PDF is set and the WDT time-out flag TO is cleared.
Operation	TO ← 0 PDF ← 1
Affected flag(s)	TO, PDF

INC [m]	Increment Data Memory
Description	Data in the specified Data Memory is incremented by 1.
Operation	[m] ← [m] + 1
Affected flag(s)	Z

INCA [m]	Increment Data Memory with result in ACC
Description	Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	ACC ← [m] + 1
Affected flag(s)	Z

JMP addr Jump unconditionally

Description The contents of the Program Counter are replaced with the specified address. Program execution then continues from this new address. As this requires the insertion of a dummy instruction while the new address is loaded, it is a two cycle instruction.

Operation Program Counter ← addr

Affected flag(s) None

MOV A,[m] Move Data Memory to ACC

Description The contents of the specified Data Memory are copied to the Accumulator.

Operation ACC ← [m]

Affected flag(s) None

MOV A,x Move immediate data to ACC

Description The immediate data specified is loaded into the Accumulator.

Operation ACC ← x

Affected flag(s) None

MOV [m],A Move ACC to Data Memory

Description The contents of the Accumulator are copied to the specified Data Memory.

Operation [m] ← ACC

Affected flag(s) None

NOP No operation

Description No operation is performed. Execution continues with the next instruction.

Operation No operation

Affected flag(s) None

OR A,[m] Logical OR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″OR″ [m]

Affected flag(s) Z

OR A,x Logical OR immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″OR″ x

Affected flag(s) Z

ORM A,[m] Logical OR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.

Operation [m] ← ACC ″OR″ [m]

Affected flag(s) Z

RET Return from subroutine

Description The Program Counter is restored from the stack. Program execution continues at the restored address.

Operation Program Counter ← Stack

Affected flag(s) None

RET A,x Return from subroutine and load immediate data to ACC

Description: The Program Counter is restored from the stack and the Accumulator loaded with the specified immediate data. Program execution continues at the restored address.

Operation: Program Counter ← Stack
ACC ← x

Affected flag(s): None

RETI Return from interrupt

Description: The Program Counter is restored from the stack and the interrupts are re-enabled by setting the EMI bit. EMI is the master interrupt global enable bit. If an interrupt was pending when the RETI instruction is executed, the pending Interrupt routine will be processed before returning to the main program.

Operation: Program Counter ← Stack
EMI ← 1

Affected flag(s): None

RL [m] Rotate Data Memory left

Description: The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.

Operation: [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← [m].7

Affected flag(s): None

RLA [m] Rotate Data Memory left with result in ACC

Description: The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation: ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← [m].7

Affected flag(s): None

RLC [m] Rotate Data Memory left through Carry

Description: The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.

Operation: [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← C
C ← [m].7

Affected flag(s): C

RLCA [m] Rotate Data Memory left through Carry with result in ACC

Description: Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation: ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← C
C ← [m].7

Affected flag(s): C

RR [m] Rotate Data Memory right

Description: The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.

Operation: [m].i ← [m].(i+1); (i=0~6)
[m].7 ← [m].0

Affected flag(s): None

RRA [m] Rotate Data Memory right with result in ACC

Description: Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation: ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← [m].0

Affected flag(s): None

RRC [m] Rotate Data Memory right through Carry

Description: The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.

Operation: [m].i ← [m].(i+1); (i=0~6)
[m].7 ← C
C ← [m].0

Affected flag(s): C

RRCA [m] Rotate Data Memory right through Carry with result in ACC

Description: Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation: ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← C
C ← [m].0

Affected flag(s): C

SBC A,[m] Subtract Data Memory from ACC with Carry

Description: The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: ACC ← ACC − [m] − C

Affected flag(s): OV, Z, AC, C

SBCM A,[m] Subtract Data Memory from ACC with Carry and result in Data Memory

Description: The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: [m] ← ACC − [m] − C

Affected flag(s): OV, Z, AC, C

SDZ [m] Skip if decrement Data Memory is 0

Description: The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation: [m] ← [m] − 1
Skip if [m]=0

Affected flag(s): None

SDZA [m] Skip if decrement Data Memory is zero with result in ACC

Description: The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation: ACC ← [m] − 1
Skip if ACC=0

Affected flag(s): None

SET [m] Set Data Memory

Description: Each bit of the specified Data Memory is set to 1.

Operation: [m] ← FFH

Affected flag(s): None

SET [m].i Set bit of Data Memory

Description: Bit i of the specified Data Memory is set to 1.

Operation: [m].i ← 1

Affected flag(s): None

SIZ [m] Skip if increment Data Memory is 0

Description: The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation: [m] ← [m] + 1
Skip if [m]=0

Affected flag(s): None

SIZA [m] Skip if increment Data Memory is zero with result in ACC

Description: The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation: ACC ← [m] + 1
Skip if ACC=0

Affected flag(s): None

SNZ [m].i Skip if bit i of Data Memory is not 0

Description: If bit i of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation: Skip if [m].i ≠ 0

Affected flag(s): None

SUB A,[m] Subtract Data Memory from ACC

Description: The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: ACC ← ACC − [m]

Affected flag(s): OV, Z, AC, C

SUBM A,[m] Subtract Data Memory from ACC with result in Data Memory

Description: The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: [m] ← ACC − [m]

Affected flag(s): OV, Z, AC, C

SUB A,x Subtract immediate data from ACC

Description: The immediate data specified by the code is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: ACC ← ACC − x

Affected flag(s): OV, Z, AC, C

SWAP [m] Swap nibbles of Data Memory

Description: The low-order and high-order nibbles of the specified Data Memory are interchanged.

Operation: [m].3~[m].0 ↔ [m].7~[m].4

Affected flag(s): None

SWAPA [m] Swap nibbles of Data Memory with result in ACC

Description: The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation: ACC.3~ACC.0 ← [m].7~[m].4
ACC.7~ACC.4 ← [m].3~[m].0

Affected flag(s): None

SZ [m] Skip if Data Memory is 0

Description: If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation: Skip if [m]=0

Affected flag(s): None

SZA [m] Skip if Data Memory is 0 with data movement to ACC

Description: The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation: ACC ← [m]
Skip if [m]=0

Affected flag(s): None

SZ [m].i Skip if bit i of Data Memory is 0

Description: If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation: Skip if [m].i=0

Affected flag(s): None

TABRD [m] Read table (specific page) to TBLH and Data Memory

Description: The low byte of the program code (specific page) addressed by the table pointer pair (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation: [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s): None

TABRDC [m] Read table (current page) to TBLH and Data Memory

Description: The low byte of the program code (current page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation: [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s): None

TABRDL [m] Read table (last page) to TBLH and Data Memory

Description: The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation: [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s): None

XOR A,[m] Logical XOR Data Memory to ACC

Description: Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation: ACC ← ACC ″XOR″ [m]

Affected flag(s): Z

XORM A,[m] Logical XOR ACC to Data Memory

Description: Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.

Operation: [m] ← ACC ″XOR″ [m]

Affected flag(s): Z

XOR A,x Logical XOR immediate data to ACC

Description: Data in the Accumulator and the specified immediate data perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation: ACC ← ACC ″XOR″ x

Affected flag(s): Z

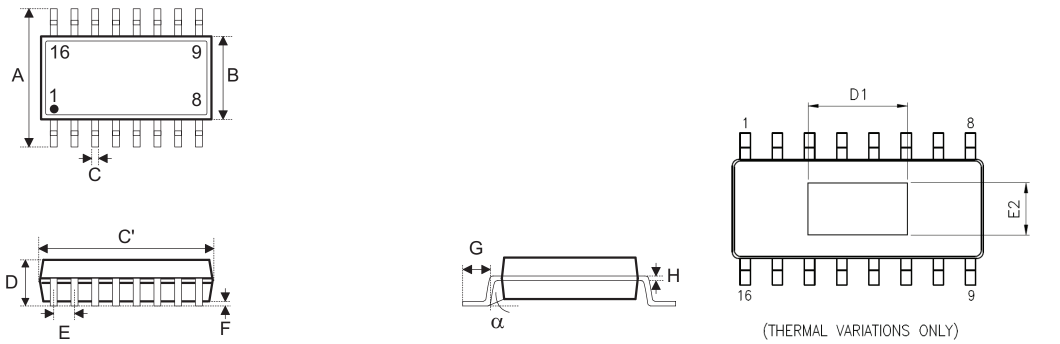
Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the Holtek website for the latest version of the Package/Carton Information.

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Further Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- Packing Meterials Information
- Carton information

16-pin NSOP (150mil) Outline Dimensions (Exposed Pad)



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.012	—	0.020
C’	—	0.390 BSC	—
D	—	—	0.069
E	—	0.050 BSC	—
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6 BSC	—
B	—	3.9 BSC	—
C	0.31	—	0.51
C’	—	9.9 BSC	—
D	—	—	1.75
E	—	1.27 BSC	—
F	0.10	—	0.25
G	0.40	—	1.27
H	0.10	—	0.25
α	0°	—	8°

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